



General Description

The MAX98088 is a full-featured audio codec whose high performance and low power consumption make it ideal for portable applications.

Class D speaker amplifiers provide efficient amplification for two speakers. Low radiated emissions enable completely filterless operation. Integrated bypass switches optionally connect an external amplifier to the transducer when the Class D amplifiers are disabled.

The IC features a stereo Class H headphone amplifier that utilizes a dual-mode charge pump to maximize efficiency while outputting a ground referenced signal that does not require output coupling capacitors.

The IC also features a mono differential amplifier that can also be configured as a stereo line output.

Three differential analog microphone inputs are available as well as support for two PDM digital microphones. Integrated switches allow microphone signals to be routed out to external devices. Two flexible single-ended or differential line inputs may be connected to an FM radio or other sources.

Integrated FLEXSOUND™ technology improves loudspeaker performance by optimizing the signal level and frequency response while limiting the maximum distortion and power at the output to prevent speaker damage. Automatic gain control (AGC) and a noise gate optimize the signal level of microphone input signals to make best use of the ADC dynamic range.

The device is fully specified over the -40°C to +85°C extended temperature range.

FLEXSOUND is a trademark of Maxim Integrated Products, Inc.

Features

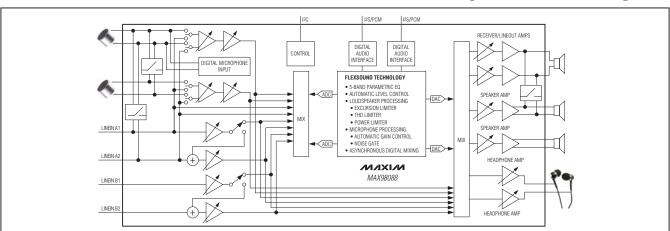
- ♦ 5.6mW Power Comsumption (DAC to HP at 97dB DR)
- ♦ 101dB DR Stereo DAC (8kHz < f_S < 96kHz)
 </p>
- ♦ 93dB DR Stereo ADC (8kHz < fs < 96kHz)
- Stereo Low EMI Class D Amplifiers 950mW/Channel (8 Ω , VSPKVDD = 4.2V)
- **♦** Efficient Class H Headphone Amplifier
- ♦ Differential Receiver Amplifier/Stereo Line Outputs
- 2 Stereo Single-Ended/Mono Differential Line Inputs
- ♦ 3 Differential Microphone Inputs
- ♦ FLEXSOUND Technology 5-Band Parametric EQ **Automatic Level Control (ALC) Excursion Limiter Speaker Power Limiter** Speaker Distortion Limiter Microphone Automatic Gain Control and Noise Gate
- ♦ Dual I2S/PCM/TDM Digital Audio Interfaces
- **♦** Asynchronous Digital Mixing
- **Supports Master Clock Frequencies from 10MHz** to 60MHz
- ♦ RF Immune Analog Inputs and Outputs
- ♦ Extensive Click-and-Pop Reduction Circuitry
- Available in 63-Bump WLP Package (3.80mm x 3.30mm, 0.4mm Pitch)

Ordering Information

PART	TEMP RANGE	PIN-PACKAGE		
MAX98088EWY+	-40°C to +85°C	63 WLP		

⁺Denotes lead(Pb)-free/RoHS-compliant package.

Simplified Block Diagram



MIXIM

Maxim Integrated Products 1

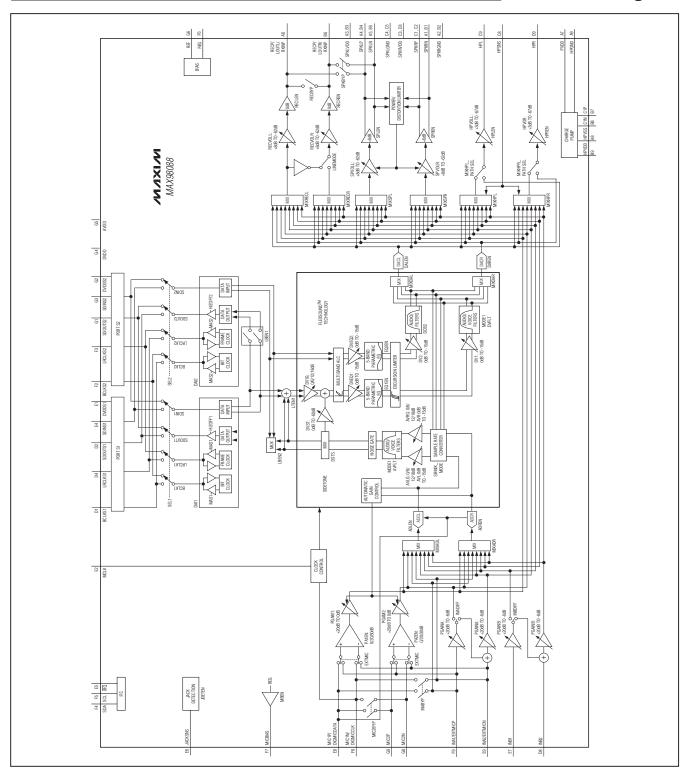
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Functional Diagram



ABSOLUTE MAXIMUM RATINGS

(Voltages with respect to AGND.)	
DVDD, AVDD, HPVDD	0.3V to +2.2V
SPKLVDD, SPKRVDD, DVDDS1, DVD	
DGND, HPGND, SPKLGND, SPKRGN	ND0.1V to +0.1V
HPVSS(HPGND -	2.2V) to (HPGND + 0.3V)
C1N (HPVSS -	0.3V) to (HPGND + 0.3V)
C1P(HPGND	- 0.3V) to (HPVDD + 0.3V)
REF, MICBIAS	0.3V to (SPKLVDD + 0.3V)
MCLK, SDINS1, SDINS2, JACKSNS,	
SDA, SCL, ĪRQ	0.3V to +6.0V
LRCLKS1, BCLKS1, SDOUTS1	-0.3V to (DVDDS1 + 0.3V)
LRCLKS2, BCLKS2, SDOUTS2	-0.3V to (DVDDS2 + 0.3V)

REG, INA1, INA2, INB1, INB2, MIC1P/DIGMICDATA,
MIC1N/DIGMICCLK, MIC2P, MIC2N0.3V to +2.2V
HPSNS(HPGND - 0.3V) to (HPGND + 0.3V)
HPL, HPR(HPVSS - 0.3V) to (HPVDD + 0.3V)
RECP, RECN(SPKLGND - 0.3V) to (SPKLVDD + 0.3V)
SPKLP, SPKLN(SPKLGND - 0.3V) to (SPKLVDD + 0.3V)
SPKRP, SPKRN(SPKRGND - 0.3V) to (SPKRVDD + 0.3V)
Continuous Power Dissipation (T _A = +70°C)
63-Bump WLP (derate 25.6mW/°C above +70°C)2.05W
Operating Temperature Range40°C to +85°C
Storage Temperature Range65°C to +150°C
Soldering Temperature (reflow)+260°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. Line out loads (RLOAD) connected from LOUTL and LOUTR to ground. $RLOAD = RHP = \infty$, $RREC = \infty$, $ZSPK = \infty$, $CREF = 2.2\mu$ F, $CMICBIAS = CREG = 1\mu$ F, $CC1N-C1P = 1\mu$ F, $CHPVDD = CHPVSS = 1\mu$ F. AVMICPRE = +20dB, AVMICPRE = 0dB, AVMICPRE = 0dB,

PARAMETER	SYMBOL	CONE	DITIONS	MIN	TYP	MAX	UNITS
POWER SUPPLY							
			VSPKLVDD, VSPKRVDD	2.8		5.5	
POWER SUPPLY Supply Voltage Range Total Supply Current (Notes 2 and 3) Shutdown Supply Current (Note 2) REF Voltage		Guaranteed by PSRR	VDVDD, VAVDD, VPVDD	1.65	1.8	2	V
			VDVDDS1, VDVDDS2	1.65		3.6	
		Full durates Old In many	Analog		4.5	8	
		Full-duplex 8kHz mono, receiver output	Speaker		1.6	2.3	
		Teceiver output	Digital		1.3	2]
T. 1. 1. 0		DAC playback 48kHz stereo, headphone out- puts	Analog		1.9	3	mA
	I _{VDD}		Speaker		0.001	0.0058	
(Notes 2 and 3)			Digital		2.47	3.5	
		DAC playback 48kHz stereo, speaker outputs	Analog		3.6	6.5	
			Speaker		6.41	8.5	
			Digital		2.49	3.5	
Claustalanua Comaralin Comara			Analog		0.2	2	μΑ
''''		$T_A = +25^{\circ}C$	Speaker		0.01	1	
(Note 2)			Digital		1	5]
REF Voltage					2.5		V
REG Voltage					0.79		V
Chutdown to Full Operation		SLEW = 0			30		
Shutdown to Full Operation		SLEW = 1			17		ms

ELECTRICAL CHARACTERISTICS (continued)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
MICROPHONE TO ADC P	ATH						
Dynamic Range	DR	fs = 8kHz, MODE = 0 (1 0dB (Note 4)	IR voice), AVMICPRE_ =		88		dB
T		$V_{IN} = 0.1V_{P-P}, f_S = 8kH$	z, f = 1kHz		-77		
Total Harmonic Distortion + Noise	THD+N	AVMICPRE_ = 0dB, VIN	= 1V _{P-P} , f = 1kHz		-84		dB
T INDISE		AVMICPRE_ = +30dB, VIN	$_{\text{I}} = 32\text{mVp-p}, f = 1\text{kHz}$		-70		
Common-Mode Rejection Ratio	CMRR	V _{IN} = 100mV _{P-P} , f = 21	7Hz		62		dB
		VAVDD = 1.65V to 1.95V MIC inputs floating	/, input referred,	50	62		
Power-Supply Rejection	DCDD	f = 217Hz, V _{RIPPLE} = 10 AV _{ADC} = 0dB, input ref	I		62		
Ratio	PSRR	f = 1kHz, V _{RIPPLE} = 100mV _{P-P} , AV _{ADC} = 0dB, input referred			62		- dB
		f = 10kHz, V _{RIPPLE} = 100mV _{P-P} , AV _{ADC} = 0dB, input referred			53		
			MODE = 0 (IIR voice) 8kHz		2.2		
		pass filter disabled measured from analog input to digital output	MODE = 0 (IIR voice) 16kHz		1.1		- ms
Path Phase Delay			MODE = 1 (FIR audio) 8kHz		4.5		
			MODE = 1 (FIR audio) 48kHz		0.76		
MICROPHONE PREAMP							
Full-Scale Input		AVMICPRE_ = 0dB			1.05		VP-P
			PA1EN/PA2EN = 01		0		
Preamplifier Gain	AVMICPRE_	(Note 5)	PA1EN/PA2EN = 10	19.5	20	20.5	dB
			PA1EN/PA2EN = 11	29.5	30	30.5	1
PGA Gain	AVMICPGA_	(Note 5)	PGAM1/PGAM2 = 0x00	19	20	21	dB
	, WINIOF GA_		PGAM1/PGAM2 = 0x14		0		
MIC Input Resistance	RIN_MIC	All gain settings, measu MIC1N/MIC2P/MIC2N	ired at MIC1P/		50		kΩ

ELECTRICAL CHARACTERISTICS (continued)

(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = $\pm 1.8V$, VSPKLVDD = VSPKRVDD = $\pm 3.7V$. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. Line out loads (RLOAD) connected from LOUTL and LOUTR to ground. RLOAD = RHP = $\pm \infty$, RREC = $\pm \infty$, ZSPK = $\pm \infty$, CREF = $\pm \infty$, CMICBIAS = CREG = $\pm \infty$, CC1N-C1P = $\pm \infty$, CHPVDD = CHPVSS = $\pm \infty$, AVMICPRE_ = $\pm \infty$, AVMICPGA_ = $\pm \infty$, OdB, AVDACGAIN = $\pm \infty$, AVDACGAIN = $\pm \infty$, AVADCGAIN = $\pm \infty$, A

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
MICROPHONE BIAS						
MICBIAS Output Voltage	VMICBIAS	ILOAD = 1mA	2.15	2.2	2.25	V
Load Regulation		ILOAD = 1mA to 2mA		0.5	4.5	mV
Line Regulation		VSPKLVDD = 2.8V to 5.5V		110		μV
Dinale Dejection		f = 217Hz, VRIPPLE (SPKLVDD) = 100mVp-p		92		4D
Ripple Rejection		f = 10kHz, VRIPPLE (SPKLVDD) = 100mVp-p		83		- dB
		A-weighted, f = 20Hz to 20kHz		3.9		
Noise Voltage		P-weighted, f = 20Hz to 4kHz		2.1		μVRMS
		f = 1kHz		50		nV/√Hz
MICROPHONE BYPASS S	WITCH					
On-Resistance	Ron	I _{MIC1_} = 100mA, INABYP = MIC2BYP = 1,		5	30	Ω
Total Harmonic Distortion + Noise	THD+N	$V_{IN} = 2V_{P-P}, V_{CM} = 0.9V, R_L = 10k\Omega,$ f = 1kHz, INABYP = MIC2BYP = 1		-80		dB
Off-Isolation		$V_{IN} = 2V_{P-P}$, $V_{CM} = 0.9V$, $R_L = 10k\Omega$, $f = 1kHz$		60		dB
Off-Leakage Current		VMIC1_ = [0V, AVDD], VMIC2_/VINA_ = [AVDD, 0V]	-1		+1	μА
LINE INPUT TO ADC PATH	1					
Dynamic Range (Note 4)	DR	INA pin direct, fs = 48kHz, MODE = 1 (FIR audio)		93		dB
Total Harmonic Distortion + Noise	THD+N	V _{IN} = 1V _{P-P} , f = 1kHz		82	74	dB
Gain Error		DC accuracy		1		%
		VAVDD = 1.65V to 1.95V, input referred, line inputs floating	57	68		
Power-Supply Rejection Ratio	DODD	f = 217Hz, VRIPPLE = 100mVp-p, AVADC = 0dB, input referred		72		-10
	PSRR	f = 1kHz, VRIPPLE = 100mVP-P, AVADC = 0dB, input referred		70		- dB
		f = 10kHz, VRIPPLE = 100mVp-p, AVADC = 0dB, input referred		60		

ELECTRICAL CHARACTERISTICS (continued)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
LINE INPUT PREAMP							
Full-Scale Input	\/	AVPGAIN_ = 0dB			1		VP-P
Full-Scale Input	VIN	AVPGAIN_ = -6dB			1.4		7 VP-P
			PGAINA/PGAINB = 0x0	19	20	21	
Level Adjust Gain			PGAINA/PGAINB = 0x1	13	14	15	
		7 0500	PGAINA/PGAINB = 0x2	2	3	4	
	AVPGAIN_	$T_A = +25^{\circ}C$ (Note 5)	PGAINA/PGAINB = 0x3		0		dB
		(Note 5)	PGAINA/PGAINB = 0x4	-4	-3	-2	1
			PGAINA/PGAINB = 0x5, 0x6, 0x7	-7	-6	-5	
		AVPGAIN_ = +20dB		14.5	21	28	
		AVPGAIN_ = +14dB			20		1
land to Desistance	D	AVPGAIN_ = +3dB			20		1.0
Input Resistance	RIN	AVPGAIN_ = 0dB		7.5	10	14	kΩ
		AVPGAIN_ = -3dB			20		j
		AVPGAIN_ = -6dB			20		
Feedback Resistance	R _{IN_FB}	INAEXT/INBEXT = 1 $\frac{T_A = +25^{\circ}C}{T_A = T_{MIN} \text{ to } T_{MAX}}$	$T_A = +25^{\circ}C$	18	20	22	kΩ
reeuback nesistance			16		24	K77	
ADC LEVEL CONTROL							
ADC Level Adjust Range	AVADCLVL	AVL/AVR = 0xF to 0x0	(Note 5)	-12		+3	dB
ADC Level Step Size					1		dB
ADC Gain Adjust Range	AVADCGAIN	AVLG/AVRG = 00 to 1	1 (Note 5)	0		18	dB
ADC Gain Adjust Step Size					6		dB
ADC DIGITAL FILTERS							
VOICE MODE IIR LOWPAS	S FILTER (I	MODE1 = 0)					
Passband Cutoff	fpl p	Ripple limit cutoff		0.441 x	fs		Hz
rasspand Culon	IPLP	-3dB cutoff		0.449 x	fs		HZ
Passband Ripple		f < fPLP		-0.1		+0.1	dB
Stopband Cutoff	fSLP					0.47 x fs	Hz
Stopband Attenuation (Note 6)		f > fSLP		74			dB

ELECTRICAL CHARACTERISTICS (continued)

 $(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (R_{REC}) connected between RECP and RECN. Headphone loads (R_{HP}) connected from HPL or HPR to HPGND. Line out loads (R_{LOAD}) connected from LOUTL and LOUTR to ground. R_{LOAD} = R_{HP} = <math>\infty$, R_{REC} = ∞ , Z_{SPK} = ∞ , C_{REF} = 2.2 μ F, C_{MICBIAS} = C_{REG} = 1 μ F, C_{1N-C_{1P}} = 1 μ F, C_{HPVDD} = C_{HPVSS} = 1 μ F. AVMICPRE_ = +20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCGAIN = 0dB, AVPREC = 0dB, AVSPK_ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. T_A = +25°C, unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP MAX	UNITS
VOICE MODE IIR HIGHP	ASS FILTER ((MODE1 = 0)			
		AVFLT = 0x1 (Elliptical tuned for f _S = 16kHz + 217Hz notch)		0.0161 x fs	
Passband Cutoff (-3dB from Peak)		AVFLT = 0x2 (500Hz Butterworth tuned for fs = 16kHz)		0.0319 x fs	
	fAHPPB	AVFLT = 0x3 (Elliptical tuned for fs = 8kHz + 217Hz notch)		0.0321 x fs	Hz
		AVFLT = 0x4 (500Hz Butterworth tuned for fs = 8kHz)		0.0632 x fs	!
		AVFLT = 0x5 (fg/240 Butterworth)		0.0043 x fs	
		AVFLT = 0x1 (Elliptical tuned for fs = 16kHz + 217Hz notch)	0.0139 x fs		
		AVFLT = 0x2 (500Hz Butterworth tuned for fS = 16kHz)	0.0156 x fs		
Stopband Cutoff (-30dB from Peak)	fAHPSB	AVFLT = 0x3 (Elliptical tuned for fS = 8kHz + 217Hz notch)	0.0279 x fs		Hz
		AVFLT = 0x4 (500Hz Butterworth tuned for fS = 8kHz)	0.0312 x fs		
		AVFLT = 0x5 (fs/240 Butterworth)	0.0018 x fs		
DC Attenuation	DCATTEN	AVFLT ≠ 000		90	dB
STEREO AUDIO MODE F	IR LOWPASS	S FILTER (MODE1 = 1, DHF1 = 0, LRCLK < 50kHz)		
		Ripple limit cutoff	0.43 x fs		
Passband Cutoff	fpLp	-3dB cutoff	0.48 x fs		Hz
		-6.02dB cutoff	0.5 x fs		
Passband Ripple		f < fplp	-0.1	+0.1	dB
Stopband Cutoff	fSLP			0.58 x f	s Hz
Stopband Attenuation (Note 6)		f < fSLP	60		dB
ADC STEREO AUDIO MO	DDE FIR LOW	PASS FILTER (MODE1 = 1, DHF1 = 1, LRCLK > 5	0kHz)		
Passband Cutoff	foun	Ripple limit cutoff	0.208 x fs		Hz
Passpand Culon	fPLP	-3dB cutoff	0.28 x fs		
Passband Ripple		f < fpLp	-0.1	+0.1	dB
Stopband Cutoff	fSLP			0.417 x fg	3 Hz
Stopband Attenuation		f < f _{SLP}	60		dB

ELECTRICAL CHARACTERISTICS (continued)

 $(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. Line out loads (RLOAD) connected from LOUTL and LOUTR to ground. RLOAD = RHP = <math>\infty$, RREC = ∞ , ZSPK = ∞ , CREF = 2.2μ F, CMICBIAS = CREG = 1μ F, CC1N-C1P = 1μ F, CHPVDD = CHPVSS = 1μ F. AVMICPRE_ = +20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVPREC = 0dB, AVSPK_ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1.TA = $+25^{\circ}$ C, unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
ADC STEREO AUDIO MOD	E DC BLOC	KING HIGHPASS FILTER (MODE	1 = 1)				•
Passband Cutoff (-3dB from Peak)	fанррв	AVFLT ≠ 000				0.000125 x fs	Hz
DC Attenuation	DC _{Atten}	AVFLT ≠ 000			90		dB
MICROPHONE AUTOMATI	C GAIN COI	NTROL					
AGC Hold Duration		AGCHLD = 01			50		ms
AGC FIOIG DUIATION		AGCHLD = 11			400		1115
AGC Attack Time		AGCATK = 00			2		_ mo
AGC Attack Time		AGCATK = 11			123		ms
AGC Release Time		AGCRLS = 000			0.078		
		AGCRLS = 111			10		S
AGC Threshold Level		AGCTH = 0x0 to 0xF		-3		+18	dB
AGC Threshold Step Size					1		dB
AGC Gain		(Note 5)		0		20	dB
ADC NOISE GATE							
NG Threshold Level		ANTH = 0x3 to 0xF, referred to 0c	IBFS	-64		-16	dB
NG Attenuation		(Note 5)		0		12	dB
ADC-TO-DAC DIGITAL SID	ETONE (MC	DDE = 0)					
Sidetone Gain Adjust	۸۱/۵=۵۰	DVST = 0x01			-0.5		ط۵
Range	AVSTGA	DVST = 0x1F			-60.5		dB
Sidetone Gain Adjust Step Size					2		dB
Cidatara Dath Dhaas Dalass		1kHz, 0dB input, highpass filter	8kHz		2.2		
Sidetone Path Phase Delay		disabled	16kHz		1.1		ms
ADC-TO-DAC DIGITAL LO	OP-THROUG	GH PATH					
Dynamic Range (Note 4)	DR	fs = 48kHz, MCLK = 12.288MHz, (FIR audio), MIC to HP output, TA		83	93		dB
Total Harmonic Distortion + Noise	THD+N	f = 1kHz, fs = 48kHz, MCLK = 12.288MHz, MODE = 1 (FIR audio), MIC to HP output			81		dB
DAC LEVEL CONTROL							
DAC Attenuation Range	AVDACATTN	DV1DV2 = 0xF to 0x0 (Note 5)		-15		0	dB
DAC Attenuation Step Size					1		dB
DAC Gain Adjust Range	AVDACGAIN	DV1G = 00 to 11 (Note 5)		0		18	dB
DAC Gain Adjust Step Size					6		dB

ELECTRICAL CHARACTERISTICS (continued)

 $(VAVDD = VPVDD = VDVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. Line out loads (RLOAD) connected from LOUTL and LOUTR to ground. RLOAD = RHP = <math>\infty$, RREC = ∞ , ZSPK = ∞ , CREF = 2.2μ F, CMICBIAS = CREG = 1μ F, CC1N-C1P = 1μ F, CHPVDD = CHPVSS = 1μ F. AVMICPRE_ = +20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVHP_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1.74 = +25°C, unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP MAX	UNITS
DAC DIGITAL FILTERS					
VOICE MODE IIR LOWPA	SS FILTER (MODE1 = 0)			
Darahan di Outaff	f	Ripple limit cutoff	0.448 x fs		
Passband Cutoff	f _{PLP}	-3dB cutoff	0.451 x fs		- Hz
Passband Ripple		f < fplp	-0.1	+0.1	dB
Stopband Cutoff	fSLP			0.476 x fs	Hz
Stopband Attenuation (Note 6)		f > fSLP	75		dB
VOICE MODE IIR HIGHPA	SS FILTER (MODE1 = 0)			
		DVFLT = 0x1 (Elliptical tuned for fs = 16kHz + 217Hz notch)		0.0161 x fs	
		DVFLT = 0x2 (500Hz Butterworth tuned for fs = 16kHz)		0.0312 x fs	
Passband Cutoff (-3dB from Peak)	fDHPPB	DVFLT = 0x3 (Elliptical tuned for fs = 8kHz + 217Hz notch)		0.0321 x fs	Hz
		DVFLT = 0x4 (500Hz Butterworth tuned for fs = 8kHz)		0.0625 x fs	
		DVFLT = 0x5 (fs/240 Butterworth)		0.0042 x fs	
		DVFLT = 0x1 (Elliptical tuned for fs = 16kHz + 217Hz notch)	0.0139 x fs		
		DVFLT = 0x2 (500Hz Butterworth tuned for fs = 16kHz)	0.0156 x fs		
Stopband Cutoff (-30dB from Peak)	fDHPSB	DVFLT = 0x3 (Elliptical tuned for fs = 8kHz + 217Hz notch)	0.0279 x fs		Hz
		DVFLT = 0x4 (500Hz Butterworth tuned for fs = 8kHz)	0.0312 x fs		
		DVFLT = 0x5 (fg/240 Butterworth)	0.0021 x fs		
DC Attenuation	DCATTEN	DVFLT ≠ 000		85	dB
STEREO AUDIO MODE FI	R LOWPASS	FILTER (MODE1 = 1, DHF1/DHF2 = 0, LRCLK <	50kHz)		
		Ripple limit cutoff	0.43 x fs		
Passband Cutoff	fPLP	-3dB cutoff	0.47 x fs		Hz
D 1 10' '		-6.02dB cutoff	0.5 x fs		
Passband Ripple		f < fplp	-0.1	+0.1	dB
Stopband Cutoff	fSLP			0.58 x fs	Hz
Stopband Attenuation (Note 6)		f > fSLP	60		dB

MIXIM

ELECTRICAL CHARACTERISTICS (continued)

 $(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. Line out loads (RLOAD) connected from LOUTL and LOUTR to ground. RLOAD = RHP = <math>\infty$, RREC = ∞ , ZSPK = ∞ , CREF = 2.2µF, CMICBIAS = CREG = 1µF, CC1N-C1P = 1µF, CHPVDD = CHPVSS = 1µF. AVMICPRE_ = +20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCGAIN = 0dB, AVADCGAIN = 0dB, AVPREC = 0dB, AVSPK_ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. TA = +25°C, unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL	CONDITION	S	MIN	TYP	MAX	UNITS
STEREO AUDIO MODE FIR	LOWPASS	FILTER (MODE1 = 1, DHF1/DI	HF2 = 1 for LRCLK	> 50kHz)			•
Passband Cutoff	fpl p	Ripple limit cutoff		0.24 x fs			Hz
rasspariu Guloii	IPLP	-3dB cutoff		0.31 x fs			112
Passband Ripple		f < fPLP		-0.1		+0.1	dB
Stopband Cutoff	fSLP					0.477 x fs	Hz
Stopband Attenuation (Note 6)		f < fSLP		60			dB
STEREO AUDIO MODE DO	BLOCKING	G HIGHPASS FILTER					
Passband Cutoff (-3dB from Peak)	fDHPPB	DVFLT ≠ 000 (DAI1), DCB2 = 1	(DAI2)			0.000104 x fs	Hz
DC Attenuation	DCATTEN	DVFLT ≠ 000 (DAI1), DCB2 = 1	(DAI2)		90		dB
AUTOMATIC LEVEL CONT	ROL						
Dual Band Lowpass Corner Frequency		ALCMB = 1			5		kHz
Dual Band Highpass Corner Frequency		ALCMB = 1	CMB = 1				kHz
Gain Range				0		12	dB
Low-Signal Threshold		ALCTH = 111 to 001		-48		-12	dBFS
Release Time		ALCRLS = 101			0.25		
nelease Time		ALCRLS = 000			8		S
PARAMETRIC EQUALIZER	R						
Number of Bands					5		Bands
Per Band Gain Range				-12		+12	dB
Preattenuator Gain Range		(Note 5)		-15		0	dB
Preattenuator Step Size					1		dB
DAC TO RECEIVER AMPL	IFIER PATH	<u> </u>					
Dynamic Range	DR	fs = 48kHz, f = 1kHz (Note 4)			96		dB
Total Harmonic Distortion + Noise	THD+N	f = 1kHz, POUT = 15mW, RREC	= 32Ω		70	63	dB
		VSPKLVDD = 2.8V to 5.5V	/SPKLVDD = 2.8V to 5.5V		75		
Power-Supply Rejection	PSRR	f = 217Hz, VRIPPLE = 100mVp-F	= 217Hz, VRIPPLE = 100mVp-p		-59		dB
Ratio	FORK	f = 1kHz, VRIPPLE = 100mVp-p			-59		Jub
		f = 10kHz, VRIPPLE = 100mVp-F)		-59		
Click-and-Pop Level	KCP	Peak voltage, A-weighted, 32 samples per second, AVREC	Into shutdown		68		dBV
	1.01	= 0dB	Out of shutdown		72		

ELECTRICAL CHARACTERISTICS (continued)

(VAVDD = VPVDD = VDVDD = VDVDDS1 = VDVDDS2 = $\pm 1.8V$, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. Line out loads (RLOAD) connected from LOUTL and LOUTR to ground. RLOAD = RHP = ∞ , RREC = ∞ , ZSPK = ∞ , CREF = 2.2μ F, CMICBIAS = CREG = 1μ F, CC1N-C1P = 1μ F, CHPVDD = CHPVSS = 1μ F. AVMICPRE_ = $\pm 2.0d$ B, AVMICPGA_ = $\pm 0.0d$ B, AVDACGAIN = $\pm 0.0d$ B, AVADCGAIN =

Output Power POUT RREC = 32Ω, f = 1kHz, THD = 1% 83 mW Full-Scale Output (Note 7) 1 VRMS Volume Control (Note 5) AVREC RECVOL = 0x00 -62 dB RECVOL = 0x1F 8 8 dB +8dB to +6dB 0.5 -6dB to +0dB 1 Volume Control Step Size 0dB to -14dB 2 dB -14dB to -38dB 3 -14dB to -62dB 4	PARAMETER	SYMBOL	CONDI	TION	S	MIN	TYP	MAX	UNITS
Total Harmonic Distortion	LINE INPUT TO RECEIVER	AMPLIFIE	R PATH						
+ Noise HID+N	Dynamic Range (Note 4)	DR	Referenced to full-scale or	utput	level		94		dB
Click-and-Pop Level KCP samples per second, AVREC odB Out of shutdown -49 dBV		THD+N					64		dB
Beceiver Amplifier Pout Rec 32Ω, f = 1kHz, THD = 1% 83 mW	Click and Dan Laval	Kon			Into shutdown		-51		dD\/
Output Power POUT (Note 7) RREC = 32Ω, f = 1kHz, THD = 1% 83 mW Full-Scale Output (Note 7) 1 VRMS Volume Control (Note 5) AVREC RECVOL = 0x00 RECVOL = 0x1F 8 dB AVREC RECVOL = 0x00 RECVOL = 0x1F 8 dB AVREC +8dB to +6dBB +6dB to +0dB -14dB to +38dB -38dB to -62dB 1 dB Mute Attenuation f = 1kHz 88 dB Capacitive Drive Capability No sustained oscillations RREC = 32Ω RREC = 32Ω RREC = ∞ 500 RREC = ∞ pF DAC TO LINE OUT AMPLIFIER PATH TOTAL Harmonic Distortion + Noise THD+N f = 1kHz, RL = 1kΩ 83 96 dB LINE INPUT TO LINE OUT AMPLIFIER PATH TOTAL Harmonic Distortion + Noise THD+N f = 1kHz, RL = 1kΩ 78 72 dB LINE INPUT TO LINE OUT AMPLIFIER PATH DR Referenced to full-scale output level 92 dB Line Information Distortion + Noise THD+N f = 1kHz, RL = 10kΩ 76 dB Line Information Distortion + Noise THD+N f = 1kHz, RL = 10kΩ 76 <td>Click-and-Pop Level</td> <td>NCP NCP</td> <td>1 ' '</td> <td>EC</td> <td>Out of shutdown</td> <td></td> <td>-49</td> <td></td> <td>Q Q Q</td>	Click-and-Pop Level	NCP NCP	1 ' '	EC	Out of shutdown		-49		Q Q Q
Full-Scale Output	RECEIVER AMPLIFIER								
AVREC RECVOL = 0x00 RECVOL = 0x1F REC	Output Power	Pout	RREC = 32Ω , f = 1kHz, TH	$ID = \frac{1}{2}$	1%		83		mW
Volume Control (Note 5) AVREC RECVOL = 0x1F 8 dB Volume Control Step Size $\frac{1}{480B}$ to +6dB 0.5 0.6 0.0	Full-Scale Output		(Note 7)	ote 7)					VRMS
$ \begin{tabular}{ c c c c c c c c c c c c c c c c c c c$	Values Cantral (Nata E)	A\/p=0	RECVOL = 0x00				-62		٩D
Volume Control Step Size	Volume Control (Note 5)	AVREC	RECVOL = 0x1F				8		T GB
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$			+8dB to +6dB	B to +6dB					
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$			+6dB to +0dB				1]
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Volume Control Step Size		0dB to -14dB	B to -14dB			2		dB
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$			-14dB to -38dB				3		
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$			-38dB to -62dB				4]
Capacitive Drive Capability No sustained oscillations RREC = ∞ 100 pF DAC TO LINE OUT AMPLIFIER PATH Dynamic Range (Note 4) DR fs = 48kHz, f = 1kHz 83 96 dB Total Harmonic Distortion + Noise THD+N f = 1kHz, RL = 1kΩ 78 72 dB Total Harmonic Distortion + Noise THD+N f = 1kHz, RL = 10kΩ 76 dB Full-Scale Output AVHP = 0dB, AVOUT = 0 dB (Note 7) 2 VP-P Mute Attenuation f = 1kHz 85 dB Output Offset Voltage Vos AVHP = -67dB ±3.0 4 mV	Mute Attenuation		f = 1kHz				88		dB
PAREC = ∞ 100 DAC TO LINE OUT AMPLIFIER PATH Dynamic Range (Note 4) DR $f_S = 48 \text{kHz}$, $f = 1 \text{kHz}$ 83 96 dB Total Harmonic Distortion + Noise THD+N $f = 1 \text{kHz}$, $R_L = 1 \text{k}\Omega$ 78 72 dB LINE INPUT TO LINE OUT AMPLIFIER PATH Dynamic Range (Note 4) DR Referenced to full-scale output level 92 dB Total Harmonic Distortion + Noise THD+N $f = 1 \text{kHz}$, $R_L = 10 \text{k}\Omega$ 76 dB Full-Scale Output AVHP = 0dB, AVOUT = 0 dB (Note 7) 2 VP-P Mute Attenuation $f = 1 \text{kHz}$ 85 dB Output Offset Voltage Vos AVHP = -67dB ±3.0 4 mV	Canacitiva Driva Canability		No quatained assillations	RRE	C = 32Ω		500		nE
Dynamic Range (Note 4)DRfs = 48kHz, f = 1kHz8396dBTotal Harmonic Distortion + NoiseTHD+N $f = 1kHz$, $R_L = 1kΩ$ 7872dBLINE INPUT TO LINE OUT AMPLIFIER PATHDynamic Range (Note 4)DRReferenced to full-scale output level92dBTotal Harmonic Distortion + NoiseTHD+N $f = 1kHz$, $R_L = 10kΩ$ 76dBFull-Scale OutputAVHP = 0dB, AVOUT = 0 dB (Note 7)2VP-PMute Attenuation $f = 1kHz$ 85dBOutput Offset VoltageVosAVHP = -67dB±3.04mV	Capacilive Drive Capability		INO SUSTAINED OSCIIIATIONS	RRE	C = ∞		100] PF
Total Harmonic Distortion $+$ Noise $+$ ThD+N $= 1 \text{kHz}$, $R_L = 1 \text{k}\Omega$ $+$ ThD+N $= 1 \text{kHz}$, $R_L = 1 \text{k}\Omega$ $+$ ThD+N $= 1 \text{kHz}$, $R_L = 1 \text{k}\Omega$ $+$ ThD+N $= 1 \text{kHz}$, $R_L = 1 \text{k}\Omega$ $+$ Total Harmonic Distortion $+$ Noise $+$ ThD+N $= 1 \text{kHz}$, $R_L = 1 \text{k}\Omega$ $+$ ThD+N $= 1 \text{kHz}$, $R_L = 1 \text{k}\Omega$ $+$ ThD+N $= 1 \text{kHz}$, $R_L = 1 \text{k}\Omega$ $+$ ThD+N $= 1 \text{kHz}$, $R_L = 1 \text{k}\Omega$ $+$ ThD+N $= 1 \text{kHz}$, $R_L = 1 \text{k}\Omega$ $+$ ThD+N $= 1 \text{kHz}$, $R_L = 1 \text{k}\Omega$ $+$ ThD+N $= 1 \text{kHz}$ $+$ T	DAC TO LINE OUT AMPLIF	IER PATH							
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Dynamic Range (Note 4)	DR	$f_S = 48kHz, f = 1kHz$			83	96		dB
Dynamic Range (Note 4) DR Referenced to full-scale output level 92 dB Total Harmonic Distortion + Noise THD+N $f = 1kHz$, $R_L = 10kΩ$ 76 dB Full-Scale Output AVHP = 0dB, AVOUT = 0 dB (Note 7) 2 VP-P Mute Attenuation $f = 1kHz$ 85 dB Output Offset Voltage Vos AVHP = -67dB ±3.0 4 mV		THD+N	$f = 1kHz, R_L = 1k\Omega$				78	72	dB
Total Harmonic Distortion + NoiseTHD+N $f = 1 \text{kHz}$, $R_L = 10 \text{k}\Omega$ 76dBFull-Scale OutputAVHP = 0dB, AVOUT = 0 dB (Note 7)2VP-PMute Attenuation $f = 1 \text{kHz}$ 85dBOutput Offset VoltageVosAVHP = -67 dB±3.04mV	LINE INPUT TO LINE OUT	AMPLIFIER	PATH						
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Dynamic Range (Note 4)	DR	Referenced to full-scale or	utput	level		92		dB
		THD+N	$=$ 1kHz, R _L = 10k Ω				76		dB
Output Offset Voltage Vos AVHP = -67dB ±3.0 4 mV	Full-Scale Output		$AV_{HP} = 0dB, AV_{OUT} = 0 dB$		2		V _{P-P}		
	Mute Attenuation		f = 1kHz						dB
	Output Offset Voltage	Vos	$AV_{HP} = -67dB$				±3.0	4	mV
	Capacitive Drive Capability		No sustained oscillations,	RL =	1kΩ		500		pF

ELECTRICAL CHARACTERISTICS (continued)

(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. Line out loads (RLOAD) connected from LOUTL and LOUTR to ground. RLOAD = RHP = ∞ , RREC = ∞ , ZSPK = ∞ , CREF = 2.2μ F, CMICBIAS = CREG = 1μ F, CC1N-C1P = 1μ F, CHPVDD = CHPVSS = 1μ F. AVMICPRE_ = +20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVPC =

PARAMETER	SYMBOL		CONDITIONS	3	MIN	TYP	MAX	UNITS
DAC TO SPEAKER AMPL	IFIER PATH							
Total Harmonic Distortion + Noise	THD+N	f = 1kHz, Pout	= 200mW, ZSPK	= 8Ω + 68μΗ		-68		dB
Crosstalk			PKL to SPKR and SPKR to SPKL, DUT = 640mW, f = 1kHz			-88		dB
Output Noise						53		μVRMS
Click-and-Pop Level	KCP		eak voltage, A-weighted, 2 samples per second,			65		dBV
		AVSPK_ = 0dB	/SPK_ = 0dB Out of shutdown			66		
MIC INPUT TO SPEAKER	AMPLIFIER	PATH						
Dynamic Range (Note 4)	DR	Referenced to fu	II-scale output lev	el, AV _{SPK} _ = 0dB		82		dB
Total Harmonic Distortion + Noise	THD+N	f = 1kHz, Pout	= 200mW, R _L =	8Ω + 68μH		71		dB
		Peak voltage, A	•	Into shutdown		55		
Click-and-Pop Level	KCP	samples per ser = 0dB	cond, AV _{SPK} _	Out of shutdown		52		dBV
SPEAKER AMPLIFIER								
		f = 1kHz, THD	VSPKLVDD = VS	SPKRVDD = 5.0V		1323		
Output Power	Pout	= 1%,	VSPKLVDD = VS	SPKRVDD = 4.2V		914		mW
Output i owei	1 001	$Z_{SPK} = 8\Omega +$	VSPKLVDD = VS	SPKRVDD = 3.7V		700		
		68µH	VSPKLVDD = VS	SPKRVDD = 3.2V		514		
Full-Scale Output		(Note 7)				2		VRMS
Volume Control	AV _{SPK} _	(Note 5)	SPVOLL/SPVO			-62		dB
Volumo Control	/ (V OI IX_		SPVOLL/SPVO	LR = 0x1F		+8		L GB
		+8dB to +6dB				0.5		
		+6dB to +0dB				1		
Volume Control Step Size		0dB to -14dB				2		dB
		-14dB to -38dB	14dB to -38dB			3		
		-38dB to -64dB				4		
Mute Attenuation		f = 1kHz				86		dB
Output Offset Voltage	Vos	$AV_{SPK} = -61dE$	B, $T_A = +25^{\circ}C$			±0.5	±3	mV

ELECTRICAL CHARACTERISTICS (continued)

 $(VAVDD = VPVDD = VDVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. Line out loads (RLOAD) connected from LOUTL and LOUTR to ground. RLOAD = RHP = <math>\infty$, RREC = ∞ , ZSPK = ∞ , CREF = 2.2μ F, CMICBIAS = CREG = 1μ F, CC1N-C1P = 1μ F, CHPVDD = CHPVSS = 1μ F. AVMICPRE_ = +20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVHP_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1.74 = +25°C, unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL	CONDIT	IONS	MIN	TYP	MAX	UNITS
EXCURSION LIMITER		•					
Upper Corner Frequency Range		DHPUCF = 001 to 100		400		1000	Hz
Lower Corner Frequency		DHPLCF = 01 to 10			400		Hz
		DHPUCF = 000 (fixed mod	e)		100		
Diama di Minima Caman		DHPUCF = 001			200		
Biquad Minimum Corner Frequency		DHPUCF = 010			300		Hz
requeriey		DHPUCF = 011		400			
		DHPUCF = 100			500		
Throughold Voltage		$Z_{SPK} = 8\Omega + 68\mu H$	DHPTH = 000		0.34		\/5
Threshold Voltage		VSPKLVDD = VSPKRVDD = 5.5V, AVSPK_ = 8dB	DHPTH = 111		0.95		VP
Release Time		ALCRLS = 101			0.25		
nelease Time		ALCRLS = 000			4		S
POWER LIMITER							
Attenuation					-64		dB
Threshold		$Z_{SPK} = 8\Omega + 68\mu H,$ $V_{SPKLVDD} = V_{SPKRVDD} =$	PWRTH = 0x1		0.08		W
Tillesiloid		$VSPKLVDD = VSPKRVDD = 5.5V$, $AVSPK_ = 8dB$	PWRTH = 0xF	1.23			VV
Time Constant 1	†DIA/D4	PWRT1 = 0x1			0.5		s
Time Constant 1	tPWR1	PWRT1 = 0xF			8.7		5
Time Constant 2	tpwR2	PWRT2 = 0x1 to 0xF			0.5		min
Time Constant 2	IPWR2	PWRT2 = 0xF			8.7		1111111
Weighting Factor	kpwr	PWRK = 000 to 111		12.5		100	%
DISTORTION LIMITER							
Distortion Limit		THDCLP = 0x1			< 1		- %
DISTOLUDIT CIITIII		THDCLP = 0xF	24			7 %	
Release Time Constant		THDT1 = 000		0.76		s	
nelease Time Constant		THDT1 = 111			6.2		7 8

ELECTRICAL CHARACTERISTICS (continued)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
DAC TO HEADPHONE AM	PLIFIER PA	TH					,
			Master or slave mode		101		
Dynamic Range (Note 4)	DR	$f_S = 48kHz$	Slave mode	97			dB
			Low power mode	95	97		
Total Harmonic Distortion	THD+N	f = 1kHz, Pout = 20mW	$RHP = 16\Omega$		-84	-64	dB
+ Noise	IIID+N	=	$R_{HP} = 32\Omega$		-83		UB UB
Crosstalk		HPL to HPR and HPR to HF f = 1kHz, RHP = 32Ω	PL, $POUT = 5mW$,		83		dB
		VAVDD = VPVDD = 1.65V to	2.0V	46	54		
		f = 217Hz, VRIPPLE = 200m AV _{VOL} = 0dB	VP-P,		72		
Power-Supply Rejection Ratio	PSRR	f = 1kHz, V _{RIPPLE} = 200mV AV _{VOL} = 0dB	P-P,		63		dB
		f = 10kHz, V _{RIPPLE} = 200m AV _{VOL} = 0dB		43			
			MODE = 0 (voice) 8kHz		2.2		
		filter disabled measured from digital input to analog	MODE = 0 (voice) 16kHz		1.1		
DAC Path Phase Delay			MODE = 1 (music) 8kHz		4.5		- ms
			MODE = 1 (music) 48kHz	, ,			
Gain Error					1	5	%
Channel Gain Mismatch					1		%
Click-and-Pop Level	KCP	Peak voltage, A-weighted, 32 samples per second,	Into shutdown		-62		dBV
oner and rep zever	1.01	$AV_{HP} = 0dB$	Out of shutdown		-63		ab.
LINE INPUT TO HEADPHO	NE AMPLIF	IER PATH		•			
Total Harmonic Distortion + Noise	THD+N	V _{IN} = 1V _{P-P} , f =1kHz, R _L =	32Ω		81		dB
Dynamic Range (Note 4)					92.5		dB
Click-and-Pop Level	KCP	Peak voltage, A-weighted, 32 samples per second,	Into shutdown		-62		dBV
	1,01	AVHP_ = 0dB	Out of shutdown		-63		

ELECTRICAL CHARACTERISTICS (continued)

 $(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. Line out loads (RLOAD) connected from LOUTL and LOUTR to ground. RLOAD = RHP = <math>\infty$, RREC = ∞ , ZSPK = ∞ , CREF = 2.2µF, CMICBIAS = CREG = 1µF, CC1N-C1P = 1µF, CHPVDD = CHPVSS = 1µF. AVMICPRE_ = +20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPRAIN_ = 0dB, AVPRAIN_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. TA = +25°C, unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL	CONDITIO	NS		MIN	TYP	MAX	UNITS
HEADPHONE AMPLIFIER	1							1
Output Power	Do. IT	f 1kHz THD 10/		$R_L = 32\Omega$		30		mW
Output Power	Pout	f = 1kHz, THD = 1%		$RL = 16\Omega$		38		TITIVV
Positive Charge-Pump	HPVDD	V _{OUT} = 0.2V, R _L = ∞				PVDD/2		V
Output Voltage	לוו עטט	Vout = 0.5V, RL = ∞				PVDD		V
Negative Charge-Pump	HPVSS	V _{OUT} = 0.2V, R _L = ∞				-PVDD/2		V
Output Voltage	111 700	VOUT = 0.5V, RL = ∞				-PVDD		\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \
Output Voltage Threshold (Output Voltage at which the Charge Pump Switches Modes; VOUT Rising; Transition from Split to Invert Mode)	VTH2	RL = ∞				±PVIN x 0.25		V
Full-Scale Output		(Note 7)				1		VRMS
Volume Control	AVHP	(Note 5)	HP	VOL_ = 0x00		-67		- dB
Volume Control	AVHP_	(Note 5)	HP	VOL_ = 0x1F		+3		T UB
		+3dB to +1dB				0.5		
		+1dB to -5dB				1		
Volume Control Step Size		-5dB to -19dB	3 to -19dB 2					dB
		-19dB to -43dB				3		
		-43dB to -67dB				4		
Mute Attenuation		f = 1kHz				100		dB
Output Offset Voltage	Vos	AVHP = -67dB		= +25°C		±0.5	±1	mV
	***************************************	/ WIII _ = 01 dB		= TMIN to TMAX			±3	1111
Capacitive Drive Capability		No sustained oscillations		₽ = 32Ω		500		pF
			RH	P = ∞		100		
SPEAKER BYPASS SWITC	H							1
On-Resistance	Ron	ISPKL_ = 100mA, SPKBYP = VRXIN_ = [0V, VSPKLVDD]				2.8		Ω
Total Harmonic Distortion		VIN = 2VP-P, VCM = VSPKLVD	D/2,	$R_S = 10\Omega$		60		
+ Noise	THD+N	Z SPK = 8 Ω + 68 μ H, f = 1kHz SPKBYP = 1	,	$R_S = 0\Omega$		60		- dB
Off-Isolation		VIN = 2VP-P, VCM = VSPKLVD f = 1kHz	$V_{IN} = 2V_{P-P}$, $V_{CM} = V_{SPKLVDD}/2$, $Z_{L} = 8\Omega + 68\mu H$, $f = 1kHz$			96		dB
Off-Leakage Current		VRXIN_ = [0V, VSPKLVDD], VSPKL_ = [VSPKLVDD, 0V]			-20		+20	μΑ

ELECTRICAL CHARACTERISTICS (continued)

 $(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. Line out loads (RLOAD) connected from LOUTL and LOUTR to ground. RLOAD = RHP = <math>\infty$, RREC = ∞ , ZSPK = ∞ , CREF = 2.2µF, CMICBIAS = CREG = 1µF, CC1N-C1P = 1µF, CHPVDD = CHPVSS = 1µF. AVMICPRE_ = +20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCGAIN = 0dB, AVADCGAIN = 0dB, AVPREC = 0dB, AVSPK_ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. TA = +25°C, unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
RECEIVER BYPASS SWIT	СН					
On-Resistance	Ron	IRECP = 100mA, RECBYP = 1, V _{RECN} = [0V, V _{SPKLVDD}]		2		Ω
Total Harmonic Distortion + Noise	THD+N	VIN = 2VP-P, VCM = VSPKLVDD/2, ZL = 8Ω + 68μ H, f = 1kHz, RECBYP = 1, R _S = 0Ω		60		%
Off-Isolation		VIN = 2VP-P, VCM = VSPKLVDD/2, ZL = 8Ω + 68μ H, f = 1 kHz		84		dB
Off-Leakage Current		VRECP = [0V, VSPKLVDD], VRECN = [VSPKLVDD, 0V]	-15		+15	μΑ
JACK DETECTION						
JACKSNS Threshold		SHDN = 1, JACKSNS rising	0.92 x VMICBIAS	0.95 x VMICBIAS	0.98 x VMICBIAS	\ S
JACKSNS Mieshold		SHDN = 0, JKSNS		SPKLVDD -	0.7	
JACKSNS Sense Voltage		SHDN = 0		SPKLVD	D	V
JACKSNS Sense Current		VJACKSNS = 0V		4	10	μΑ
BATTERY ADC						
Input Voltage Range			2.6		5.6	V
LSB Size				0.1		V

DIGITAL INPUT/OUTPUT CHARACTERISTICS

(VAVDD = VHPVDD = VDVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V, TA = +25°C, unless otherwise noted.)(Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
MCLK						,
Input High Voltage	VIH		1.2			V
Input Low Voltage	VIL				0.6	V
Input Leakage Current	I _{IH} , I _{IL}	VDVDD = 2.0V, VIN = 0V, 5.5V; TA = +25°C	-1		+1	μΑ
Input Capacitance				10		рF
SDINS1, BCLKS1, LRCLKS1-	-INPUT					
Input High Voltage	VIH		0.7 x DVDDS1			V
Input Low Voltage	VIL				0.29 x DVDDS1	V
Input Hysteresis				200		mV
Input Leakage Current	IIH, IIL	V _D V _D DS1 = 3.6V, V _I N = 0V, 3.6V; T _A = +25°C	-1		+1	μΑ
Input Capacitance				10		рF

DIGITAL INPUT/OUTPUT CHARACTERISTICS (continued)

(VAVDD = VHPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V, TA = +25°C, unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
BCLKS1, LRCLKS1, SDOUTS1	I—OUTPUT					
Output Low Voltage	Vol	VDVDDS1 = 1.65V, IOL = 3mA			0.4	V
Output High Voltage	VoH	V _{DVDDS1} = 1.65V, I _{OH} = 3mA	DVDDS1 - 0.4			V
Input Leakage Current	IIH, IIL	V _{DVDD} = 2.0V, V _{IN} = 0V, 5.5V; T _A = +25°C, high-impedance state	-1		+1	μΑ
SDINS2, BCLKS2, LRCLKS2—	INPUT					
Input High Voltage	VIH		0.7 x DVDDS2			V
Input Low Voltage	VIL				0.29 x DVDDS2	V
Input Hysteresis				200		mV
Input Leakage Current	IIH, IIL	VDVDDS2 = 3.6V, VIN = 0V, 3.6V; TA = +25°C	-1		+1	μΑ
Input Capacitance				10		рF
BCLKS2, LRCLKS2, SDOUTS2	OUTPUT					
Output Low Voltage	VoL	$V_{DVDDS2} = 1.65V$, $I_{OL} = 3mA$			0.4	V
Output High Voltage	Vон	V _{DVDDS2} = 1.65V, I _{OH} = 3mA	DVDDS2 - 0.4			V
Input Leakage Current	I _{IH} , I _{IL}	VDVDD = 2.0V, VIN = 0V, 5.5V; TA = +25°C, high-impedance state	-1		+1	μΑ
SDA, SCL—INPUT						
Input High Voltage	VIH		0.7 x DVDD			V
Input Low Voltage	VIL				0.3 x DVDD	V
Input Hysteresis				210		mV
Input Leakage Current	I _{IH} , I _I L	V _{DVDD} = 2.0V, V _{IN} = 0V, 5.5V; T _A = +25°C	-1		+1	μΑ
Input Capacitance				10		рF
SDA, IRQ—OUTPUT						
Output High Current	ЮН	V _{OUT} = 5.5V, T _A = +25°C			1	mA
Output Low Voltage	VoL	V _{DVDD} = 1.65V, I _{OL} = 3mA			0.2 x DVDD	V
DIGMICDATA—INPUT						
Input High Voltage	VIH		0.65 x DVDD			V
Input Low Voltage	VIL				0.35 x DVDD	V
Input Hysteresis				125		mV
Input Leakage Current	I _{IH} , I _{IL}	VDVDD = 2.0V, VIN = 0V, 2.0V; TA = +25°C	-25		+25	μΑ
Input Capacitance				10		рF

DIGITAL INPUT/OUTPUT CHARACTERISTICS (continued)

(VAVDD = VHPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V, TA = +25°C, unless otherwise noted.)(Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
DIGMICCLK—OUTPUT						
Output Low Voltage	VoL	V _{DVDD} = 1.65V, I _{OL} = 1mA			0.4	V
Output High Voltage	Vон	V _D V _D D = 1.65V, I _O H = 1mA	DVDD - 0.4			V

INPUT CLOCK CHARACTERISTICS

(VAVDD = VHPVDD = VDVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V, TA = +25°C, unless otherwise noted.)(Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
MCLK Input Frequency	fMCLK		10		60	MHz
MCLK Input Duty Cycle		PSCLK = 01	40	50	60	%
MCLK Input Duty Cycle		PSCLK = 10 or 11	30		70	70
Maximum MCLK Input Jitter				100		ps _{RMS}
LRCLK Sample Rate (Note 8)		DHF_ = 0	8		48	kHz
LNOLK Sample hate (Note o)		DHF_ = 1	48		96	NI IZ
DAI1 LRCLK Average Frequency		FREQ1 = 0x8 to 0xF	0		0	%
Error (Note 9)		FREQ1 = 0x0	-0.025		+0.025	/0
DAI2 LRCLK Average Frequency Error (Note 9)			-0.025		+0.025	%
DIL Look Time		Rapid lock mode		2	7	
PLL Lock Time		Nonrapid lock mode		12	25	ms
Maximum LRCLK Jitter to Maintain PLL Lock					100	ns
Soft-Start/Stop Time				10		ms

AUDIO INTERFACE TIMING CHARACTERISTICS

(VAVDD = VHPVDD = VDVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V, TA = +25°C, unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL		CONDITIONS	MIN	TYP	MAX	UNITS
BCLK Cycle Time	t _{BCLK}	Slave mode	•	90			ns
BCLK High Time	tBCLKH	Slave mode		20			ns
BCLK Low Time	[†] BCLKL	Slave mode	•	20			ns
BCLK or LRCLK Rise and Fall Time	t _R , t _F	Master mod	le, C _L = 15pF				ns
SDIN to BCLK Setup Time	tsetup			20			ns
LRCLK to BCLK Setup Time	tsyncset	Slave mode)	20			ns
SDIN to BCLK Hold Time	tHOLD			20			ns
LRCLK to BCLK Hold Time	tsynchold	Slave mode	•	20			ns
Minimum Delay Time from LSB BCLK Falling Edge to High-Impedance State	tHIZOUT	Master mod	Master mode, TDM_ = 1		42		ns
LRCLK Rising Edge to SDOUT MSB Delay	tsynctx	C _L = 30pF,	TDM_ = 1, FSW_ = 1			50	ns
BCLK to SDOUT Delay	to	C. 20pE	TDM_ = 1, BCLK rising edge			50	20
BCLK to SDOOT Delay	tCLKTX	$C_L = 30pF$	$TDM_{-} = 0$			50	ns
			TDM_ = 1	-15		+15	
Delay Time from BCLK to LRCLK	tCLKSYNC	Master mode	TDM_ = 0			0.8 x tBCLKL	ns
Delay Time from LRCLK to BCLK After LSB	tendsync	Master mode	TDM_ = 1, FSW_ = 1	20			ns

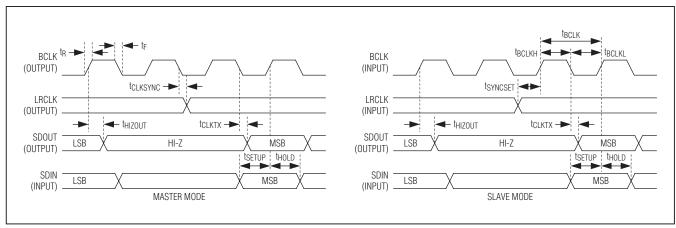


Figure 1. Non-TDM Audio Interface Timing Diagrams (TDM_ = 0)

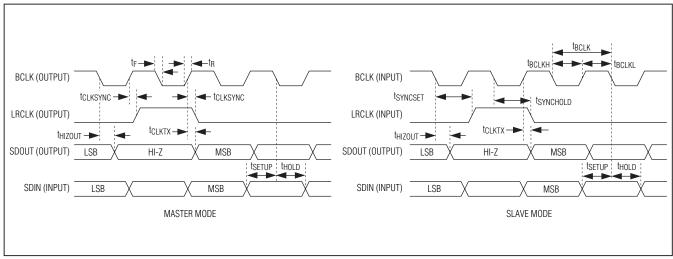


Figure 2. TDM Audio Interface Timing Diagram (TDM_ = 1, FSW_ = 0)

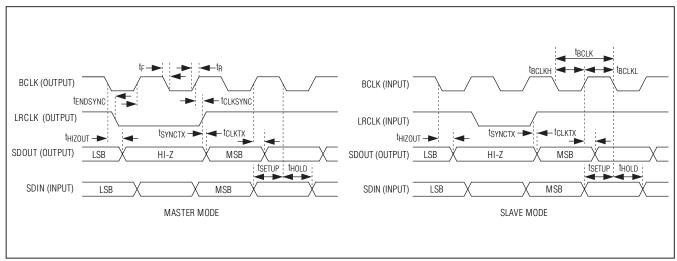


Figure 3. TDM Audio Interface Timing Diagram (TDM_ = 1, FSW_ = 1)

DIGITAL MICROPHONE TIMING CHARACTERSTICS

(VAVDD = VHPVDD = VDVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V, TA = +25°C, unless otherwise noted.)(Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	
DIGMICCLK Frequency	francour	MICCLK = 00		MCLK/8		NALI-	
	†MICCLK	MICCLK = 01		MCLK/6		MHz	
DIGMICDATA to DIGMICCLK Setup Time	tsu,MIC	Either clock edge	20			ns	
DIGMICDATA to DIGMICCLK Hold Time	tHD,MIC	Either clock edge	0			ns	

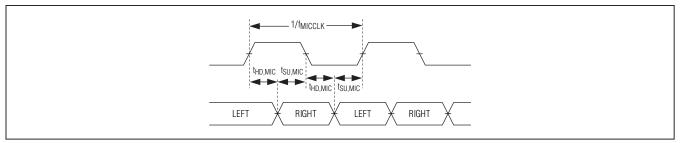


Figure 4. Digital Microphone Timing Diagram

I2C TIMING CHARACTERSTICS

 $(V_{AVDD} = V_{HPVDD} = V_{DVDDS1} = V_{DVDDS2} = +1.8V, V_{SPKLVDD} = V_{SPKRVDD} = 3.7V, T_A = +25^{\circ}C, unless otherwise noted.)$ (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Serial-Clock Frequency	fscL	Guaranteed by SCL pulse-width low and high	0		400	kHz
Bus Free Time Between STOP and START Conditions	[†] BUF		1.3			μs
Hold Time (Repeated) START Condition	tHD,STA		0.6			μs
SCL Pulse-Width Low	tLOW		1.3			μs
SCL Pulse-Width High	tHIGH		0.6			μs
Setup Time for a Repeated START Condition	tsu,sta		0.6			μs
Data Hold Time	thd,dat	$R_{PU} = 475\Omega$, CB = 100pF, 400pF	0		900	ns
Data Setup Time	tsu,dat		100			ns
SDA and SCL Receiving Rise Time	tR	(Note 10)	20 + 0.1C _B		300	ns
SDA and SCL Receiving Fall Time	tF	(Note 10)	20 + 0.1C _B		300	ns
SDA Transmitting Fall Time	tF	$R_{PU} = 475\Omega$, $C_B = 100pF$, $400pF$ (Note 10)	20 + 0.05CB		250	ns
Setup Time for STOP Condition	tsu,sto		0.6			μs
Bus Capacitance	Св	Guaranteed by SDA transmitting fall time			400	рF
Pulse Width of Suppressed Spike	tsp		0		50	ns

I²C TIMING CHARACTERISTICS (continued)

(VAVDD = VHPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. TA = +25°C, unless otherwise noted.)(Note 1)

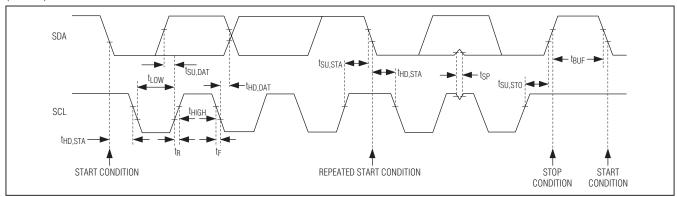


Figure 5. I2C Interface Timing Diagram

- **Note 1:** The IC is 100% production tested at $T_A = +25^{\circ}C$. Specifications over temperature limits are guaranteed by design.
- Note 2: Analog supply current = IAVDD + IHPVDD. Speaker supply current = ISPKLVDD + ISPKRVDD. Digital supply current = IDVDD + IDVDDS1 + IDVDDS2.
- Note 3: Clocking all zeros into the DAC.
- Note 4: Dynamic range measured using the EIAJ method. -60dBFS, 1kHz output signal, A-weighted and normalized to 0dBFS. f = 20Hz to 20kHz.
- Note 5: Gain measured relative to the 0dB setting.
- Note 6: The filter specification is accurate only for synchronous clocking modes, where NI is a multiple of 0x1000.
- Note 7: OdBFS for DAC input. 1VP-P for INA/INB inputs.
- Note 8: LRCLK may be any rate in the indicated range. Asynchronous or noninteger MCLK/LRCLK ratios may exhibit some full-scale performance degradation compared to synchronous integer related MCLK/LRCLK ratios.
- Note 9: In master-mode operation, the accuracy of the MCLK input proportionally determines the accuracy of the sample clock rate.
- Note 10: CB is in pF.

Power Consumption

(VAVDD = VPVDD = VDVDD = VDVDDS1 = VDVDDS2 = 1.8V, VSPKLVDD = VSPKRVDD = 3.7V)

MODE	I _{AVDD} (mA)	IPVDD (mA)	ISPKVDD + ISPKLVDD (mA)	I _{DVDD} (mA)	IDVDDS1 + IDVDDS2 (mA)	POWER (W)	DYNAMIC RANGE (dB)
Playback to Headphone Only							
DAC Playback 48kHz Stereo HP DAC → HP Low power mode, 24-bit, music filters, 256Fs	1.25	0.47	0.00	1.35	0.01	5.55	97
DAC Playback 48kHz Stereo HP DAC → HP Low power mode, 24-bit, music filters, 256Fs, 0.1mW/channel, RHP = 32Ω	1.25	1.81	0.00	1.56	0.01	8.32	97

Power Consumption (continued)

(VAVDD = VPVDD = VDVDD = VDVDDS1 = VDVDDS2 = 1.8V, VSPKLVDD = VSPKRVDD = 3.7V)

MODE	I _{AVDD} (mA)	I _{PVDD} (mA)	ISPKVDD + ISPKLVDD (mA)	I _{DVDD} (mA)	IDVDDS1 + IDVDDS2 (mA)	POWER (W)	DYNAMIC RANGE (dB)
DAC Playback 48kHz Stereo HP DAC → HP 24-bit, music filters, 256Fs	2.04	1.27	0.00	1.53	0.01	8.72	101
DAC Playback 48kHz Stereo HP DAC → HP 24-bit, music filters, 256Fs, 0.1mW/ channel, R _{HP} = 32Ω	2.04	2.11	0.00	1.74	0.01	10.63	101
DAC Playback 44.1kHz Stereo HP DAC → HP 24-bit, music filters	2.03	1.27	0.00	1.41	0.01	8.46	100
DAC Playback 44.1kHz Stereo HP DAC → HP Low power mode, 24-bit, music filters	1.25	0.47	0.00	1.25	0.01	5.34	97
DAC Playback 8kHz Stereo HP DAC → HP 16-bit, voice filters	2.04	1.27	0.00	1.07	0.00	7.89	95
DAC Playback 8kHz Stereo HP DAC → HP 16-bit, low power mode, voice filters	1.26	0.47	0.00	0.90	0.00	4.72	94
DAC Playback 8kHz Mono HP DAC → HP 16-bit, low power mode, voice filters	0.77	0.29	0.00	0.79	0.00	3.33	93.7
Line Playback Stereo HP INA → HP Single-ended inputs	2.40	1.27	0.00	0.02	0.00	6.67	95
DAC Playback to Class D Speaker							
DAC Playback 48kHz Stereo SPK DAC → SPK 24-bit, music filters	2.31	0.00	6.33	2.14	0.01	31.44	86

_Power Consumption (continued)

(VAVDD = VPVDD = VDVDD = VDVDDS1 = VDVDDS2 = 1.8V, VSPKLVDD = VSPKRVDD = 3.7V)

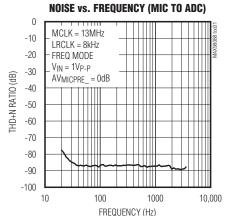
MODE	IAVDD (mA)	IPVDD (mA)	ISPKVDD + ISPKLVDD (mA)	I _{DVDD} (mA)	IDVDDS1 + IDVDDS2 (mA)	POWER (W)	DYNAMIC RANGE (dB)	
DAC Playback 48kHz Mono SPK DAC → SPK 24-bit, music filters	1.35	0.00	3.23	1.84	0.01	17.69	86	
Line Playback Mono SPK INA → SPKL Differential inputs	1.01	0.00	3.24	0.03	0.00	13.83	83	
Full Duplex								
Full-Duplex 8kHz Mono RCV MIC1 → ADC DAC → REC 16-bit, voice filters	6.32	0.00	1.54	1.24	0.01	19.33	Record = 87 Playback = 94	
Full-Duplex 8kHz Stereo HP MIC1/2 → ADC DAC → HP 16-bit, mixer, voice filters	11.19	1.27	0.48	1.28	0.01	26.43	Record = 87 Playback = 96	
Full-Duplex 8kHz Stereo HP MIC1/2 → ADC DAC → HP 16-bit, low power mode, voice filters	7.12	0.47	0.48	1.10	0.02	17.44	Record = 87 Playback = 94	
Line Record					1		1	
Line Stereo Record 48kHz INA → ADC 24-bit, low power, music filters	6.19	0.00	0.20	1.31	0.15	14.47	91	
Line Stereo Record 48kHz INA → ADC Direct pin input, 24bit, low power, music filters	5.69	0.00	0.20	1.31	0.12	13.53	93	

Typical Operating Characteristics

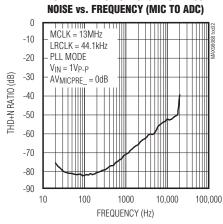
(VAVDD = VPVDD = VDVDD = VDVDDS1 = VDVDDS2 = \pm 1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. RHP = ∞ , RREC = ∞ , ZSPK = ∞ , CREF = \pm 2.2 μ F, CMICBIAS = CREG = \pm 1 μ F, CC1N-C1P = \pm 1 μ F, CHPVDD = CHPVSS = \pm 1 μ F. AVMICPRE_ = \pm 20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVHP_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = \pm 2.288MHz, LRCLK = \pm 48kHz, MAS = \pm 1. TA = \pm 25°C, unless otherwise noted.)

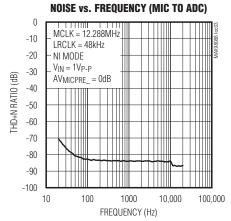
Microphone to ADC

TOTAL HARMONIC DISTORTION PLUS

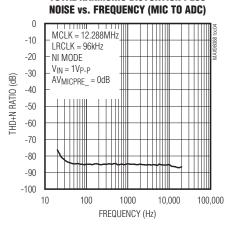


TOTAL HARMONIC DISTORTION PLUS

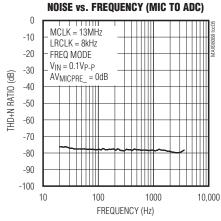




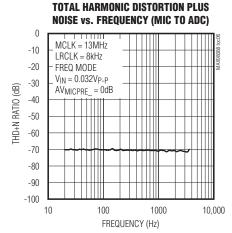
TOTAL HARMONIC DISTORTION PLUS



TOTAL HARMONIC DISTORTION PLUS

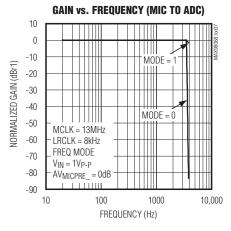


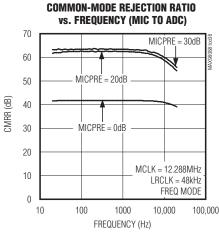
TOTAL HARMONIC DISTORTION PLUS

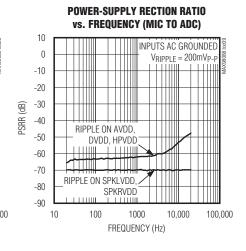


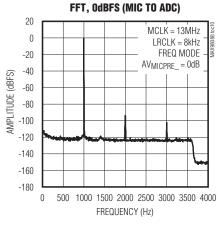
Typical Operating Characteristics (continued)

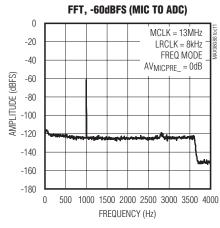
 $(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. RHP = <math>\infty$, RREC = ∞ , ZSPK = ∞ , CREF = 2.2 μ F, CMICBIAS = CREG = 1 μ F, CC1N-C1P = 1 μ F, CHPVDD = CHPVSS = 1 μ F. AVMICPRE_ = +20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVHP_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. TA = +25°C, unless otherwise noted.)

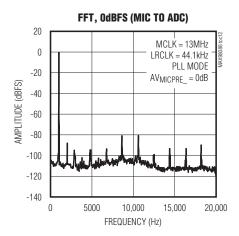






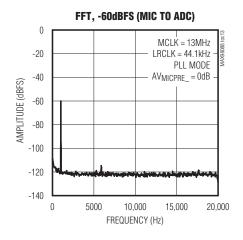


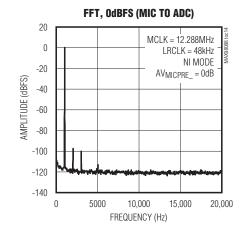


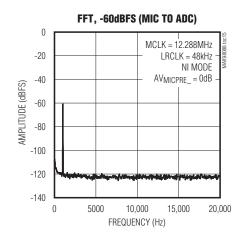


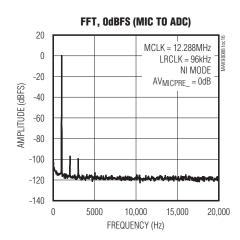
Typical Operating Characteristics (continued)

(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. RHP = ∞ , RREC = ∞ , ZSPK = ∞ , CREF = 2.2 μ F, CMICBIAS = CREG = 1 μ F, CC1N-C1P = 1 μ F, CHPVDD = CHPVSS = 1 μ F. AVMICPRE_ = +20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVHP_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. TA = +25°C, unless otherwise noted.)



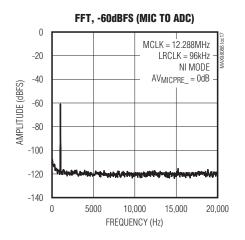


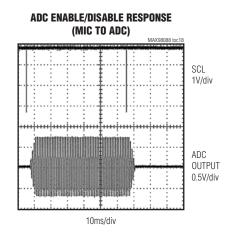


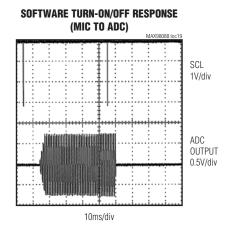


Typical Operating Characteristics (continued)

(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. RHP = ∞ , RREC = ∞ , ZSPK = ∞ , CREF = 2.2 μ F, CMICBIAS = CREG = 1 μ F, CC1N-C1P = 1 μ F, CHPVDD = CHPVSS = 1 μ F. AVMICPRE_ = +20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVHP_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. TA = +25°C, unless otherwise noted.)





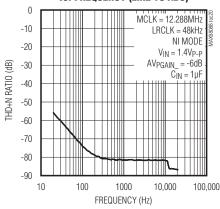


Typical Operating Characteristics (continued)

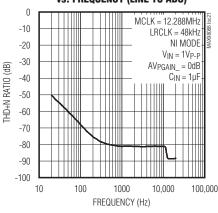
(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = \pm 1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. RHP = ∞ , RREC = ∞ , ZSPK = ∞ , CREF = 2.2 μ F, CMICBIAS = CREG = 1μ F, CC1N-C1P = 1μ F, CHPVDD = CHPVSS = 1μ F. AVMICPRE_ = \pm 20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVHP_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = \pm 2.288MHz, LRCLK = \pm 48KHz, MAS = \pm 1. TA = \pm 25°C, unless otherwise noted.)

Line to ADC

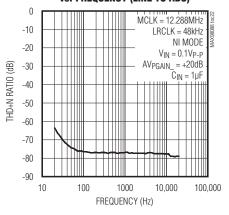




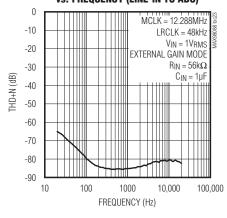
TOTAL HARMONIC DISTORTION PLUS NOISE vs. Frequency (Line to ADC)



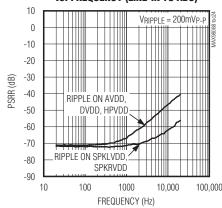
TOTAL HARMONIC DISTORTION PLUS NOISE vs. Frequency (Line to ADC)



TOTAL HARMONIC DISTORTION PLUS NOISE vs. Frequency (Line-In to ADC)



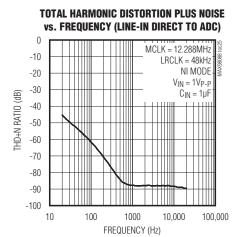
POWER-SUPPLY REJECTION RATIO vs. Frequency (Line-in to ADC)

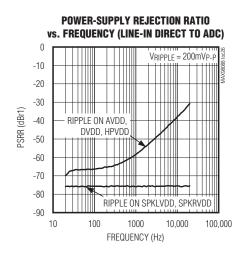


Typical Operating Characteristics (continued)

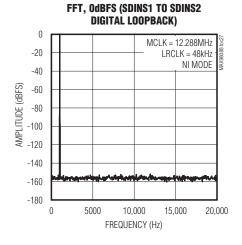
 $(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. RHP = <math>\infty$, RREC = ∞ , ZSPK = ∞ , CREF = 2.2 μ F, CMICBIAS = CREG = 1 μ F, CC1N-C1P = 1 μ F, CHPVDD = CHPVSS = 1 μ F. AVMICPRE_ = +20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVHP_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. TA = +25°C, unless otherwise noted.)

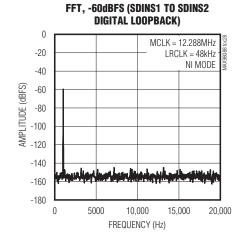
Line-In Pin Direct to ADC





Digital Loopback



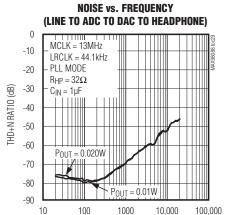


Typical Operating Characteristics (continued)

(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. RHP = ∞ , RREC = ∞ , ZSPK = ∞ , CREF = 2.2 μ F, CMICBIAS = CREG = 1 μ F, CC1N-C1P = 1 μ F, CHPVDD = CHPVSS = 1 μ F. AVMICPRE_ = +20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVHP_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. TA = +25°C, unless otherwise noted.)

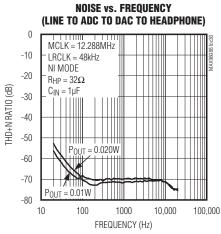
Analog Loopback

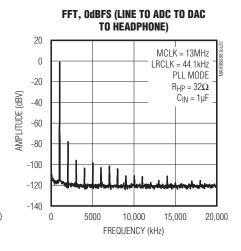
TOTAL HARMONIC DISTORTION PLUS

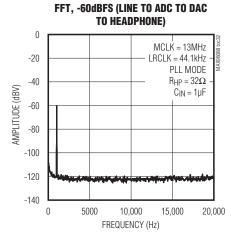


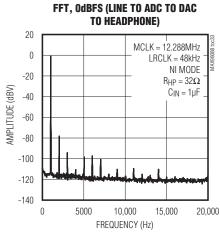
FREQUENCY (Hz)

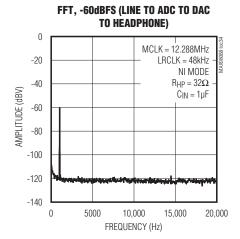
TOTAL HARMONIC DISTORTION PLUS







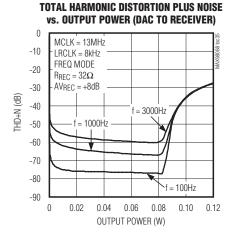


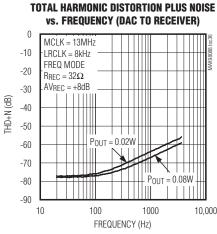


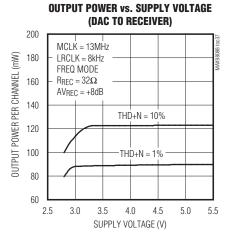
Typical Operating Characteristics (continued)

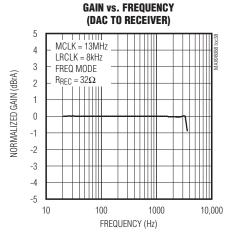
 $(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. RHP = <math>\infty$, RREC = ∞ , ZSPK = ∞ , CREF = 2.2μ F, CMICBIAS = CREG = 1μ F, CC1N-C1P = 1μ F, CHPVDD = CHPVSS = 1μ F. AVMICPRE_ = +20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVHP_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = $1.T_A = +25^{\circ}C$, unless otherwise noted.)

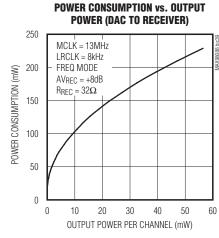
DAC to Receiver

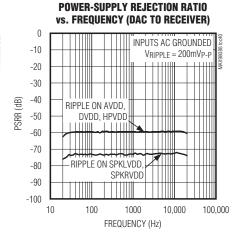






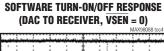


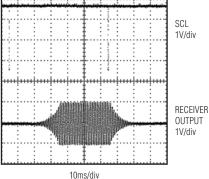




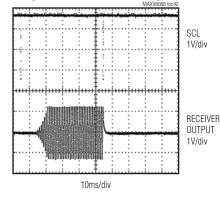
Typical Operating Characteristics (continued)

 $(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. RHP = <math>\infty$, RREC = ∞ , ZSPK = ∞ , CREF = 2.2 μ F, CMICBIAS = CREG = 1 μ F, CC1N-C1P = 1 μ F, CHPVDD = CHPVSS = 1 μ F. AVMICPRE_ = +20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVHP_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. TA = +25°C, unless otherwise noted.)

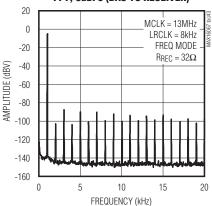




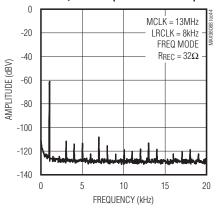
SOFTWARE TURN-ON/OFF RESPONSE (DAC TO RECEIVER, VSEN = 1)



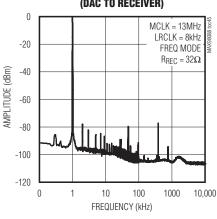
FFT, OdBFS (DAC TO RECEIVER)



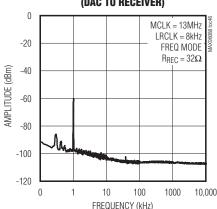
FFT, -60dBFS (DAC TO RECEIVER)



WIDEBAND FFT, Odbfs (DAC TO RECEIVER)



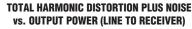
WIDEBAND FFT, Odbfs (DAC TO RECEIVER)

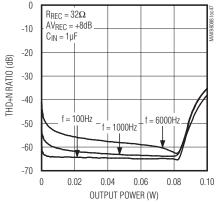


Typical Operating Characteristics (continued)

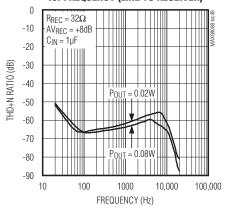
 $(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. RHP = <math>\infty$, RREC = ∞ , ZSPK = ∞ , CREF = 2.2μ F, CMICBIAS = CREG = 1μ F, CC1N-C1P = 1μ F, CHPVDD = CHPVSS = 1μ F. AVMICPRE_ = +20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVHP_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = $1.T_A = +25^{\circ}C$, unless otherwise noted.)

Line to Receiver

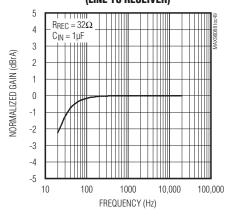




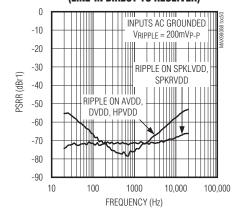
TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (LINE TO RECEIVER)



GAIN vs. FREQUENCY (LINE TO RECEIVER)



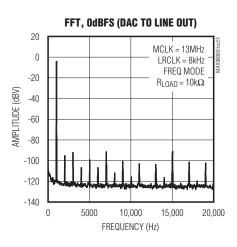
POWER-SUPPLY REJECTION RATIO vs. FREQUENCY (LINE-IN DIRECT TO RECEIVER)

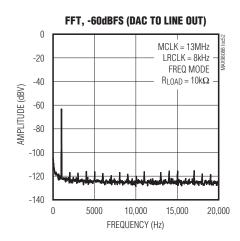


Typical Operating Characteristics (continued)

(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = \pm 1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. RHP = ∞ , RREC = ∞ , ZSPK = ∞ , CREF = 2.2 μ F, CMICBIAS = CREG = 1μ F, CC1N-C1P = 1μ F, CHPVDD = CHPVSS = 1μ F. AVMICPRE_ = \pm 20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVHP_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = \pm 2.288MHz, LRCLK = \pm 48KHz, MAS = \pm 1. TA = \pm 25°C, unless otherwise noted.)

DAC to Line Output



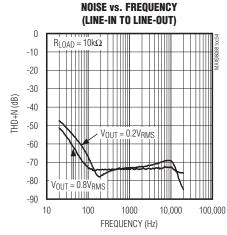


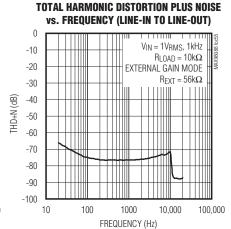
Line to Line Output

TOTAL HARMONIC DISTORTION PLUS

NOISE vs. OUTPUT LEVEL (LINE-IN TO LINE-OUT) $R_{LOAD} = 10k\Omega$ -10 -20 -30 -40 -50 6kHz -60 -70 -80 - 1kH -90 0.6 0.8 1.2 OUTPUT LEVEL (V_{RMS})

TOTAL HARMONIC DISTORTION PLUS



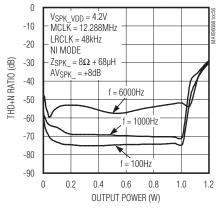


Typical Operating Characteristics (continued)

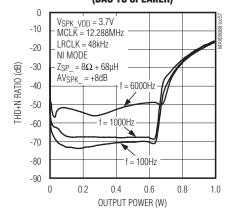
 $(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. RHP = <math>\infty$, RREC = ∞ , ZSPK = ∞ , CREF = 2.2 μ F, CMICBIAS = CREG = 1 μ F, CC1N-C1P = 1 μ F, CHPVDD = CHPVSS = 1 μ F. AVMICPRE_ = +20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVHP_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. TA = +25°C, unless otherwise noted.)

DAC to Speaker

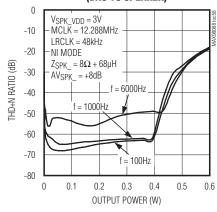




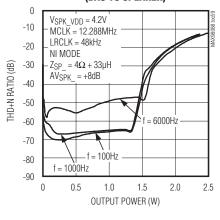
TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO SPEAKER)



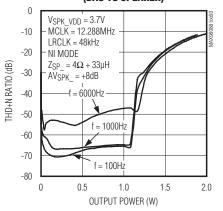
TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO SPEAKER)



TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO SPEAKER)

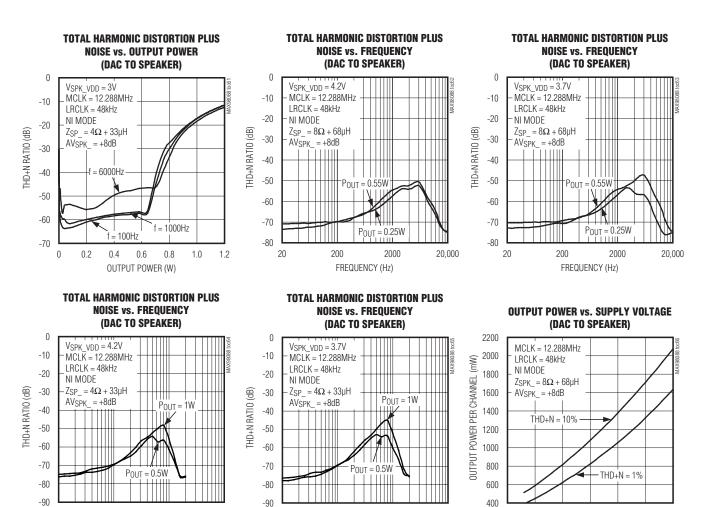


TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO SPEAKER)



Typical Operating Characteristics (continued)

(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = \pm 1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. RHP = ∞ , RREC = ∞ , ZSPK = ∞ , CREF = 2.2 μ F, CMICBIAS = CREG = 1μ F, CC1N-C1P = 1μ F, CHPVDD = CHPVSS = 1μ F. AVMICPRE_ = \pm 20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVHP_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = \pm 2.288MHz, LRCLK = \pm 48KHz, MAS = \pm 1. TA = \pm 25°C, unless otherwise noted.)



10,000

FREQUENCY (Hz)

100,000

2.5

3.0

SUPPLY VOLTAGE (V)

100

10,000

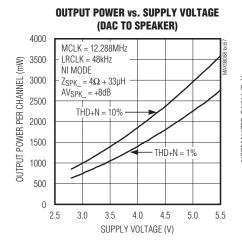
FREQUENCY (Hz)

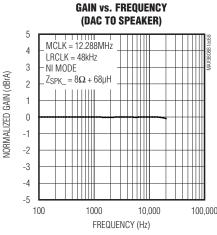
100,000

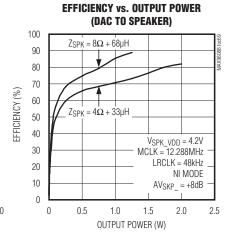
100

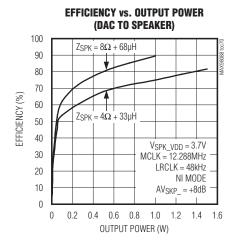
Typical Operating Characteristics (continued)

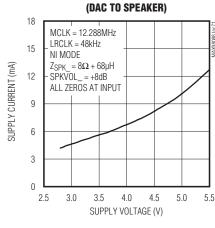
 $(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. RHP = <math>\infty$, RREC = ∞ , ZSPK = ∞ , CREF = 2.2 μ F, CMICBIAS = CREG = 1 μ F, CC1N-C1P = 1 μ F, CHPVDD = CHPVSS = 1 μ F. AVMICPRE_ = +20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVHP_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. TA = +25°C, unless otherwise noted.)



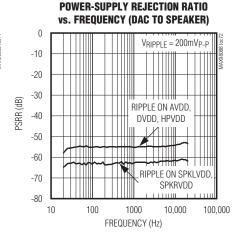






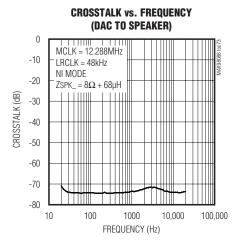


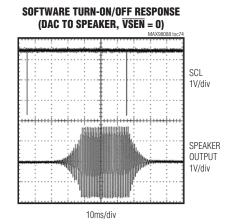
SUPPLY CURRENT vs. SUPPLY VOLTAGE

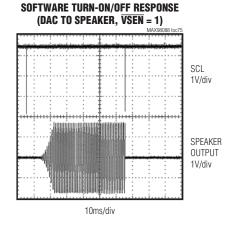


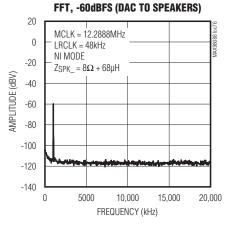
Typical Operating Characteristics (continued)

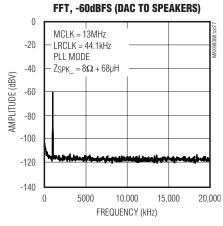
 $(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. RHP = <math>\infty$, RREC = ∞ , ZSPK = ∞ , CREF = 2.2 μ F, CMICBIAS = CREG = 1 μ F, CC1N-C1P = 1 μ F, CHPVDD = CHPVSS = 1 μ F. AVMICPRE_ = +20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVHP_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. TA = +25°C, unless otherwise noted.)

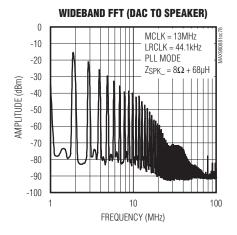








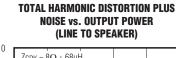


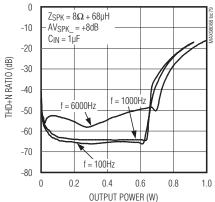


Typical Operating Characteristics (continued)

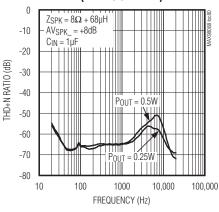
 $(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. RHP = <math>\infty$, RREC = ∞ , ZSPK = ∞ , CREF = 2.2μ F, CMICBIAS = CREG = 1μ F, CC1N-C1P = 1μ F, CHPVDD = CHPVSS = 1μ F. AVMICPRE_ = +20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVHP_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = $1.T_A = +25^{\circ}C$, unless otherwise noted.)

Line to Speaker

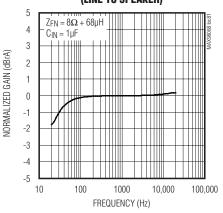




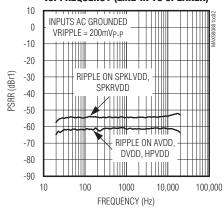
TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (LINE TO SPEAKER)



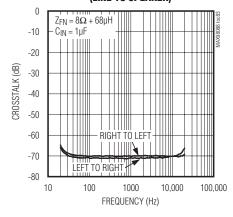
GAIN vs. FREQUENCY (LINE TO SPEAKER)



POWER-SUPPLY REJECTION RATIO vs. Frequency (Line-in to Speaker)



CROSSTALK vs. FREQUENCY (LINE TO SPEAKER)

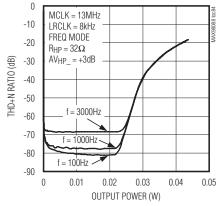


Typical Operating Characteristics (continued)

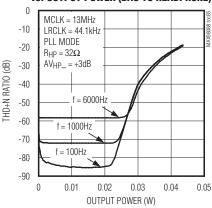
(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = \pm 1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. RHP = ∞ , RREC = ∞ , ZSPK = ∞ , CREF = 2.2 μ F, CMICBIAS = CREG = 1μ F, CC1N-C1P = 1μ F, CHPVDD = CHPVSS = 1μ F. AVMICPRE_ = \pm 20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVHP_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = \pm 2.288MHz, LRCLK = \pm 48KHz, MAS = \pm 1. TA = \pm 25°C, unless otherwise noted.)

DAC to Headphone

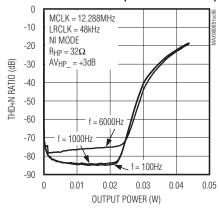




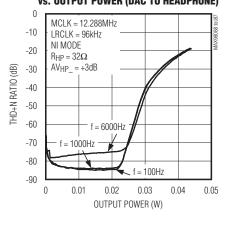
TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO HEADPHONE)



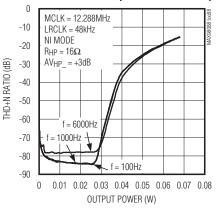
TOTAL HARMONIC DISTORTION PLUS NOISE vs. Output power (dac to headphone)



TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO HEADPHONE)



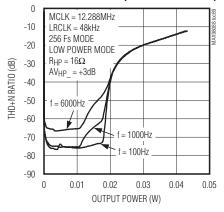
TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO HEADPHONE)



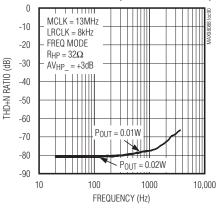
Typical Operating Characteristics (continued)

 $(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. RHP = <math>\infty$, RREC = ∞ , ZSPK = ∞ , CREF = 2.2 μ F, CMICBIAS = CREG = 1 μ F, CC1N-C1P = 1 μ F, CHPVDD = CHPVSS = 1 μ F. AVMICPRE_ = +20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVHP_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. TA = +25°C, unless otherwise noted.)

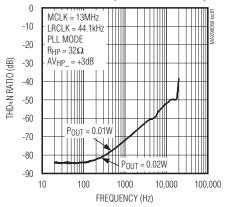
TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO HEADPHONE)



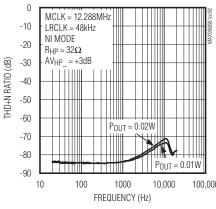
TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (DAC TO HEADPHONE)



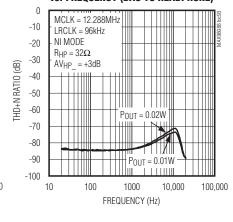
TOTAL HARMONIC DISTORTION PLUS NOISE vs. Frequency (DAC to Headphone)



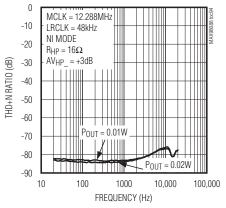
TOTAL HARMONIC DISTORTION PLUS NOISE vs. FREQUENCY (DAC TO HEADPHONE)



TOTAL HARMONIC DISTORTION PLUS NOISE vs. Frequency (DAC to Headphone)

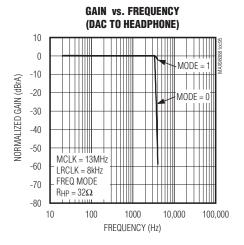


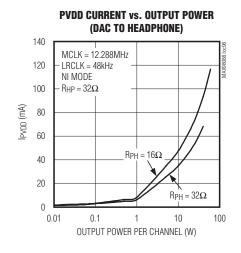
TOTAL HARMONIC DISTORTION PLUS NOISE vs. Frequency (DAC to Headphone)

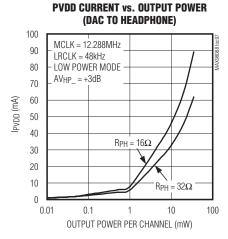


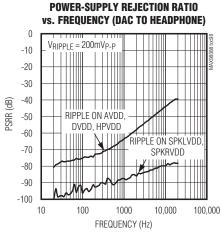
Typical Operating Characteristics (continued)

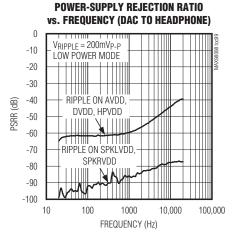
(VAVDD = VPVDD = VDVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. RHP = ∞, RREC = ∞, ZSPK = ∞, CREF = 2.2μF, CMICBIAS = CREG = 1μF, CC1N-C1P = 1μF, CHPVDD = CHPVSS = 1μF. AVMICPRE_ = +20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVHP_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. TA = +25°C, unless otherwise noted.)





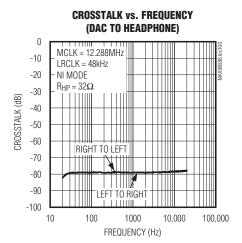


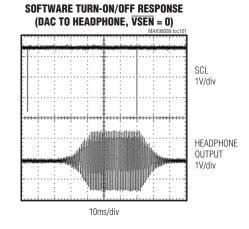


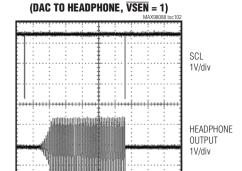


Typical Operating Characteristics (continued)

 $(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. RHP = <math>\infty$, RREC = ∞ , ZSPK = ∞ , CREF = 2.2 μ F, CMICBIAS = CREG = 1 μ F, CC1N-C1P = 1 μ F, CHPVDD = CHPVSS = 1 μ F. AVMICPRE_ = +20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVHP_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. TA = +25°C, unless otherwise noted.)





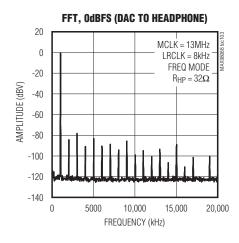


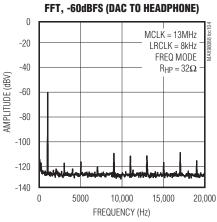
SOFTWARE TURN-ON/OFF RESPONSE

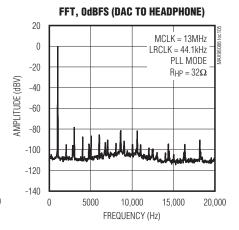
10ms/div

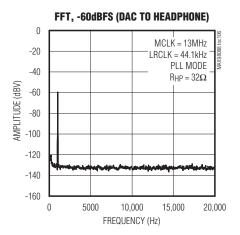
Typical Operating Characteristics (continued)

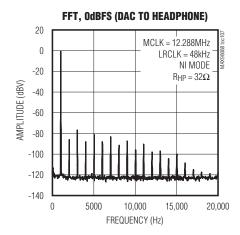
(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = \pm 1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. RHP = ∞ , RREC = ∞ , ZSPK = ∞ , CREF = 2.2 μ F, CMICBIAS = CREG = 1μ F, CC1N-C1P = 1μ F, CHPVDD = CHPVSS = 1μ F. AVMICPRE_ = \pm 20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVHP_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = \pm 2.288MHz, LRCLK = \pm 48KHz, MAS = \pm 1. TA = \pm 25°C, unless otherwise noted.)





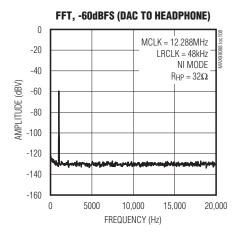


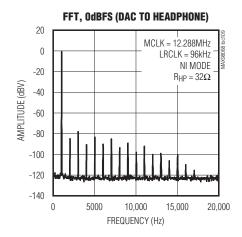


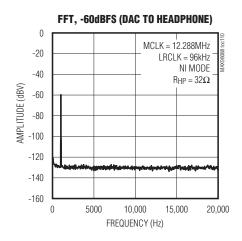


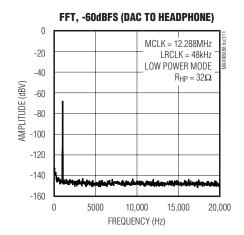
Typical Operating Characteristics (continued)

(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. RHP = ∞ , RREC = ∞ , ZSPK = ∞ , CREF = 2.2 μ F, CMICBIAS = CREG = 1 μ F, CC1N-C1P = 1 μ F, CHPVDD = CHPVSS = 1 μ F. AVMICPRE_ = +20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVHP_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. TA = +25°C, unless otherwise noted.)



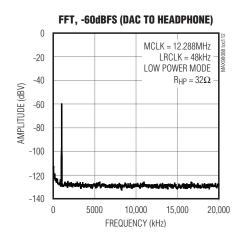


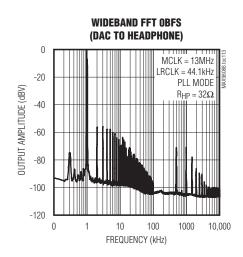


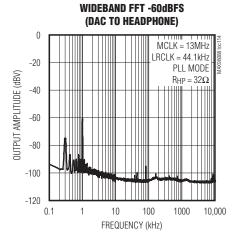


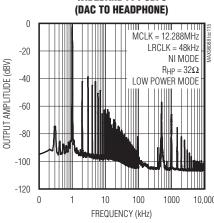
Typical Operating Characteristics (continued)

(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. RHP = ∞ , RREC = ∞ , ZSPK = ∞ , CREF = 2.2 μ F, CMICBIAS = CREG = 1 μ F, CC1N-C1P = 1 μ F, CHPVDD = CHPVSS = 1 μ F. AVMICPRE_ = +20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVHP_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. TA = +25°C, unless otherwise noted.)

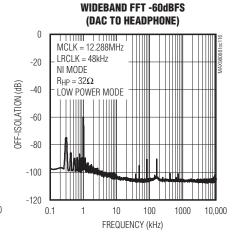








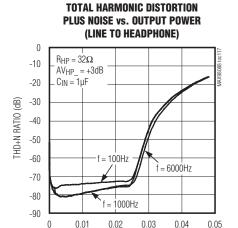
WIDEBAND FFT OBFS



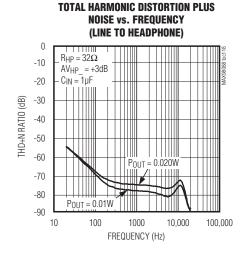
Typical Operating Characteristics (continued)

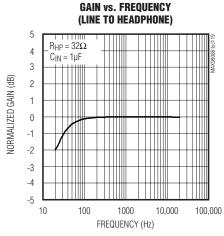
 $(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. RHP = <math>\infty$, RREC = ∞ , ZSPK = ∞ , CREF = 2.2 μ F, CMICBIAS = CREG = 1 μ F, CC1N-C1P = 1 μ F, CHPVDD = CHPVSS = 1 μ F. AVMICPRE_ = +20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVHP_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. TA = +25°C, unless otherwise noted.)

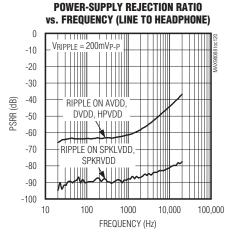
Line to Headphone

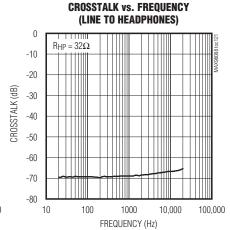


OUTPUT POWER (W)





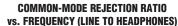


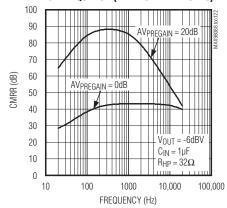


Typical Operating Characteristics (continued)

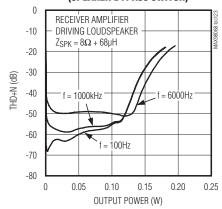
(VAVDD = VPVDD = VDVDDS1 = VDVDDS2 = +1.8V, VSPKLVDD = VSPKRVDD = 3.7V. Speaker loads (ZSPK) connected between SPK_P and SPK_N. Receiver load (RREC) connected between RECP and RECN. Headphone loads (RHP) connected from HPL or HPR to HPGND. RHP = ∞ , RREC = ∞ , ZSPK = ∞ , CREF = 2.2 μ F, CMICBIAS = CREG = 1 μ F, CC1N-C1P = 1 μ F, CHPVDD = CHPVSS = 1 μ F. AVMICPRE_ = +20dB, AVMICPGA_ = 0dB, AVDACATTN = 0dB, AVDACGAIN = 0dB, AVADCLVL = 0dB, AVADCGAIN = 0dB, AVPGAIN_ = 0dB, AVHP_ = 0dB, AVREC = 0dB, AVSPK_ = 0dB, MCLK = 12.288MHz, LRCLK = 48kHz, MAS = 1. TA = +25°C, unless otherwise noted.) (Note 1)

Speaker Bypass Switch

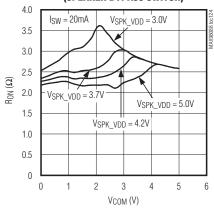




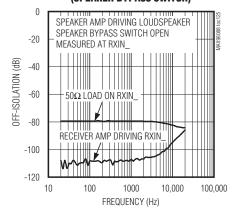
TOTAL HARMONIC DISTORTION PLUS NOISE vs. OUTPUT POWER (SPEAKER BYPASS SWITCH)



ON-RESISTANCE vs. VCOM (SPEAKER BYPASS SWITCH)



OFF-ISOLATION vs. FREQUENCY (SPEAKER BYPASS SWITCH)



_Pin Configuration

_	1	2	3	4	5	6	7	8	9
-	+ (SPKRN)	(SPKRGND)	(SPKLVDD)	SPKLP	(SPKLN)	(RECP) (LOUTL/) RXINP	PVDD	(HPVSS)	(HPGND)
	(SPKRN)	(SPKRGND)	(SPKLVDD)	SPKLP	SPKLN	RECN/ LOUTR/ RXINN	(C1P)	(C1N)	(HPVDD)
	(SPKRP)	SPKRP	(SPKRVDD)	(SPKLGND)	(SPKLGND)	(N.C)	(N.C.)	(HPSNS)	HPL
	(BCLKS1)	(SDOUTS1)	(SPKRVDD)	(LRCLKS1)	MAX98088 N.C.	(N.C.	(N.C.)	(INB2	HPR
	(DVDDS1)	MCLK	(N.C.	(SDINS1)	(IRQ)	(JACKSNS)	(INB1)	MIC1P/ DIGMICDATA	(INA2/ EXTMICN)
	(DGND)	(BCLKS2)	(LRCLKS2)	(SDA)	SCL	REG	(MICBIAS)	(MIC1N/ DIGMICCLK)	(INA1/ EXTMICP)
	(SDOUTS2)	(DVDDS2)	(SDINS2)	(DVDD)	(AVDD)	(REF)	AGND	(MIC2N)	MIC2P

Pin Description

PIN	NAME	FUNCTION
A1, B1	SPKRN	Negative Right-Channel Class D Speaker Output
A2, B2	SPKRGND	Right-Speaker Ground
A3, B3	SPKLVDD	Left-Speaker, REF, Receiver Amp Power Supply. Bypass to SPKLGND with a 1μF and a 10μF capacitor.
A4, B4	SPKLP	Positive Left-Channel Class D Speaker Output
A5, B5	SPKLN	Negative Left-Channel Class D Speaker Output
A6	RECP/LOUTL/ RXINP	Positive Receiver Amplifier Output or Left Line Output. Can be positive bypass switch input when receiver amp is shut down.
A7	PVDD	Headphone Power Supply. Bypass to HPGND with a 1µF capacitor.
A8	HPVSS	Inverting Charge-Pump Output. Bypass to HPGND with a 1µF ceramic capacitor.
A9	HPGND	Headphone Ground
В6	RECN/LOUTR/ RXINN	Negative Receiver Amplifier Output or Right Line Output. Can be negative bypass switch input when receiver amp is shut down.
В7	C1P	Charge-Pump Flying Capacitor Positive Terminal. Connect a 1µF ceramic capacitor between C1N and C1P.
B8	C1N	Charge-Pump Flying Capacitor Negative Terminal. Connect a 1µF ceramic capacitor between C1N and C1P.
B9	HPVDD	Noninverting Charge-Pump Output. Bypass to HPGND with a 1µF ceramic capacitor.
C1, C2	SPKRP	Positive Right-Channel Class D Speaker Output
C3, D3	SPKRVDD	Right-Speaker Power Supply. Bypass to SPKRGND with a 1µF capacitor.
C4, C5	SPKLGND	Left-Speaker Ground
C6, C7, D5, D6, D7, E3	N.C.	No Connection
C8	HPSNS	Headphone Amplifier Ground Sense. Connect to the headphone jack ground terminal or connect to ground.
C9	HPL	Left-Channel Headphone Output
D1	BCLKS1	S1 Digital Audio Bit Clock Input/Output. BCLKS1 is an input when the ICs are in slave mode and an output when in master mode. The input/output voltage is referenced to DVDDS1.
D2	SDOUTS1	S1 Digital Audio Serial-Data ADC Output. The output voltage is referenced to DVDDS1.
D4	LRCLKS1	S1 Digital Audio Left-Right Clock Input/Output. LRCLKS1 is the audio sample rate clock and determines whether S1 audio data is routed to the left or right channel. In TDM mode, LRCLKS1 is a frame sync pulse. LRCLKS1 is an input when the IC is in slave mode and an output when in master mode.
D8	INB2	Single-Ended Line Input B2. Also positive differential line input B.
D9	HPR	Right-Channel Headphone Output
E1	DVDDS1	S1 Digital Audio Interface Power-Supply Input. Bypass to DGND with a 1µF capacitor.
E2	MCLK	Master Clock Input. Acceptable input frequency range is 10MHz to 60MHz.
E4	SDINS1	S1 Digital Audio Serial-Data DAC Input. The input/output voltage is referenced to DVDDS1. The input voltage is referenced to DVDDS1.

_Pin Description (continued)

PIN	NAME	FUNCTION
E5	ĪRQ	Hardware Interrupt Output. \overline{IRQ} can be programmed to pull low when bits in status register 0x00 change state. Read status register 0x00 to clear \overline{IRQ} once set. Repeat faults have no effect on \overline{IRQ} until it is cleared by reading the I ² C status register 0x00. Connect a 10k Ω pullup resistor to DVDD for full output swing.
E6	JACKSNS	Jack Sense. Detects the insertion of a jack. See the Jack Detection section.
E7	INB1	Single-Ended Line Input B1. Also negative differential line input B.
E8	MIC1P/ DIGMICDATA	Positive Differential Microphone 1 Input. AC-couple a microphone with a series 1µF capacitor. Can be retasked as a digital microphone data input.
E9	INA2/ EXTMICN	Single-Ended Line Input A2. Also positive differential line input A or negative differential external microphone input.
F1	DGND	Digital Ground
F2	BCLKS2	S2 Digital Audio Bit Clock Input/Output. BCLKS2 is an input when the IC is in slave mode and an output when in master mode. The input/output voltage is referenced to DVDDS2.
F3	LRCLKS2	S2 Digital Audio Left-Right Clock Input/Output. LRCLKS2 is the audio sample rate clock and determines whether audio data on S2 is routed to the left or right channel. In TDM mode, LRCLKS2 is a frame sync pulse. LRCLKS2 is an input when the IC is in slave mode and an output when in master mode. The input/output voltage is referenced to DVDDS2.
F4	SDA	I ² C Serial-Data Input/Output. Connect a pullup resistor to DVDD for full output swing.
F5	SCL	I ² C Serial-Clock Input. Connect a pullup resistor to DVDD for full output swing.
F6	REG	Common-Mode Voltage Reference. Bypass to AGND with a 1µF capacitor.
F7	MICBIAS	Low-Noise Bias Voltage. Outputs a 2.2V microphone bias. An external resistor in the $2.2k\Omega$ to $1k\Omega$ range should be used to set the microphone current.
F8	MIC1N/ DIGMICCLK	Negative Differential Microphone 1 Input. AC-couple a microphone with a series 1µF capacitor. Can be retasked as a digital microphone clock output.
F9	INA1/ EXTMICP	Single-Ended Line Input A1. Also negative differential line input A or positive differential external microphone input.
G1	SDOUTS2	S2 Digital Audio Serial-Data ADC Output. The output voltage is referenced to DVDDS2.
G2	DVDDS2	S2 Digital Audio Interface Power-Supply Input. Bypass to DGND with a 1µF capacitor.
G3	SDINS2	S2 Digital Audio Serial-Data DAC Input. The input voltage is referenced to DVDDS2.
G4	DVDD	Digital Power Supply. Supply for the digital core and I ² C interface. Bypass to DGND with a 1µF capacitor.
G5	AVDD	Analog Power Supply. Bypass to AGND with a 1µF capacitor.
G6	REF	Converter Reference. Bypass to AGND with a 2.2µF capacitor.
G7	AGND	Analog Ground
G8	MIC2N	Negative Differential Microphone 2 Input. AC-couple a microphone with a series 1μF capacitor.
G9	MIC2P	Positive Differential Microphone 2 Input. AC-couple a microphone with a series 1µF capacitor.

Detailed Description

The MAX98088 is a fully integrated stereo audio codec with FLEXSOUND technology and integrated amplifiers.

Two differential microphone amplifiers can accept signals from three analog inputs. One input can be retasked to support two digital microphones. Any combination of two microphones (analog or digital) can be recorded simultaneously. The analog signals are amplified up to 50dB and recorded by the stereo ADC. The digital record path supports voice filtering with selectable preset highpass filters and high stopband attenuation at fs/2. An automatic gain control (AGC) circuit monitors the digitized signal and automatically adjusts the analog microphone gain to make best use of the ADC's dynamic range. A noise gate attenuates signals below the user-defined threshold to minimize the noise output by the ADC.

The IC includes two analog line inputs. One of the line inputs can be optionally retasked as a third analog microphone input. Both line inputs support either stereo single-ended input signals or mono differential signals. The line inputs are preamplified and then routed either to the ADC for recording or to the output amplifiers for playback. The single-ended line inputs signals from INA1 and INA2 can bypass the PGAs, and be connected directly to the ADC input to provide the best dynamic range.

Integrated analog switches allow two differential microphone signals to be routed out the third microphone input to an external device. This eliminates the need for an external analog switch in systems that have two devices recording signals from the same microphone.

Through two digital audio interfaces, the device can transmit one stereo audio signal and receive two stereo audio signals in a wide range of formats including I²S, PCM, and up to four mono slots in TDM. Each interface can be connected to either of two audio ports (S1 and S2) for communication with external devices. Both audio interfaces support 8kHz to 96kHz sample rates. Each input signal is independently equalized using 5-band parametric equalizers. A multiband automatic level control (ALC) boosts signals by up to 12dB. One signal path additionally supports the same voiceband filtering as the ADC path.

The IC includes a stereo Class D speaker amplifier, a high-efficiency Class H stereo headphone amplifiers, and a differential receiver amplifier that can be configured as a stereo line output.

When the receiver amplifier is disabled, analog switches allow RECP/RXINP and RECN/RXINN to be reused for signal routing. In systems where a single transducer is used for both the loudspeaker and receiver, an external receiver amplifier can be routed to the left speaker through RECP/RXINP and RECN/RXINN, bypassing the Class D amplifier, to connect to the loudspeaker. If the internal receiver amplifier is used, then leave RECP/RXINP and RECN/RXINN unconnected. In systems where an external amplifier drives both the receiver and the MAX98088/MAX98089's input, one of the differential signals can be disconnected from the receiver when not needed by passing it through the analog switch that connects RECP/RXINP to RECN/RXINN.

The stereo Class D amplifier provides efficient amplification for two speakers. The amplifier includes active emissions limiting to minimize the radiated emissions (EMI) traditionally associated with Class D. In most systems, no output filtering is required to meet standard EMI limits.

To optimize speaker sound quality, the IC includes an excursion limiter, a distortion limiter, and a power limiter. The excursion limiter is a dynamic highpass filter with variable corner frequency that increases in response to high signal levels. Low-frequency energy typically causes more distortion than useful sound at high signal levels, so attenuating low frequencies allows the speaker to play louder without distortion or damage. At lower signal levels, the filter corner frequency reduces to pass more low frequency energy when the speaker can handle it. The distortion limiter reduces the volume when the output signal exceeds a preset distortion level. This ensures that regardless of input signal and battery voltage, excessive distortion is never heard by the user. The power limiter monitors the continuous power into the loudspeaker and lowers the signal level if the speaker is at risk of overheating.

The stereo Class H headphone amplifier uses a dual-mode charge pump to maximize efficiency while outputting a ground-referenced signal. This eliminates the need for DC-blocking capacitors or a midrail bias for the headphone jack ground return. Ground sense reduces output noise caused by ground return current.

The IC integrates jack detection allowing the detection of insertion and removal of accessories.

I²C Slave Address

Configure the MAX98088 using the I^2C control bus. The IC uses a slave address of 0x20 or 00100000 for write operations and 0x21 or 00100001 for read operations. See the I^2C Serial Interface section for a complete interface description.

Registers

Table 1 lists all of the registers, their addresses, and power-on-reset states. Registers 0x00 to 0x03 and 0xFF are read-only while all of the other registers are read/write. Write zeros to all unused bits in the register table when updating the register, unless otherwise noted.

Table 1. Register Map

REGISTER	В7	В6	B5	B4	В3	B2	B1	В0	ADDRESS	DEFAULT	R/W	PAGE
STATUS						1			1	1		
Status	CLD	SLD	ULK	_	_	_	JDET	_	0x00	_	R	111
Microphone AGC/NG		NG				AGC			0x01	_	R	70
Jack Status	_	JKSNS	_	_	_	_	_	_	0x02	_	R	110
Battery Voltage	_	_	_			VBAT			0x03	_	R/W	110
Interrupt Enable	ICLD	ISLD	IULK	0	0	0	IJDET	0	0x0F	0x00	R/W	111
MASTER CLO	OCK CON	TROL	,			,				,		
Master Clock	0	0	PSC	CLK	0	0	0	0	0x10	0x00	R/W	81
DAI1 CLOCK	CONTRO	L										
Clock Mode		5	SR1			FRE	Q1		0x11	0x00	R/W	81, 82
Any Clock	PLL1				NI1[14:8]				0x12	0x00	R/W	82
Control				NI1[7:1]				NI1[0]	0x13	0x00	R/W	82
DAI1 CONFIG	GURATION	V										
Format	MAS1	WCI1	BCI1	DLY1	0	TDM1	FSW1	WS1	0x14	0x00	R/W	76
Clock	ADC_0	OSR1	DAC_ORS1	0	0		BSEL1		0x15	0x00	R/W	77
I/O Configuration	SE	L1	LTEN1	LBEN1	DMONO1	HIZOFF1	SDOEN1	SDIEN1	0x16	0x00	R/W	77, 78
Time-Division Multiplex	SLO	TL1	SLC)TR1		SLOTE	DLY1		0x17	0x00	R/W	78
Filters	MODE1		AVFLT1		DHF1		DVFLT1		0x18	0x00	R/W	86
DAI2 CLOCK	CONTRO	L										
Clock Mode		5	SR2		0	0	0	0	0x19	0x00	R/W	81
Any Clock	PLL2				NI2[14:8]				0x1A	0x00	R/W	82
Control				NI2[7:1]				NI2[0]	0x1B	0x00	R/W	82
DAI2 CONFIG	URATION	V										
Format	MAS2	WCI2	BCI2	DLY2	0	TDM2	FSW2	WS2	0x1C	0x00	R/W	76
Clock	0	0	DAC_ ORS2	0	0		BSEL2		0x1D	0x00	R/W	77
I/O Configuration	SE	L2	0	LBEN2	DMONO2	HIZOFF2	SDOEN2	SDIEN2	0x1E	0x00	R/W	77, 78

Table 1. Register Map (continued)

REGISTER	В7	В6	B5	B4	В3	B2	B1	В0	ADDRESS	DEFAULT	R/W	PAGE
Time-Division Multiplex	SLO	TL2	SLC	DTR2		SLOTI	DLY2	1	0x1F	0x00	R/W	78
Filters	0	0	0	0	DHF2	0	0	DCB2	0x20	0x00	R/W	86
SRC		,							'			
Sample Rate Converter	0	0	0	SRMIX_ MODE	SRMIX_ ENL	SRMIX_ ENR	SRC_ ENL	SRC_ ENR	0x21	0x00	R/W	85
MIXERS												
DAC Mixer		MD	XDAL			MIXE	AR		0x22	0x00	R/W	92
Left ADC Mixer				MIX	(ADL				0x23	0x00	R/W	69
Right ADC Mixer				MIX	ADR				0x24	0x00	R/W	69
Left Headphone Amplifier Mixer				MIX	(HPL				0x25	0x00	R/W	105
Right Headphone Amplifier Mixer				MIX	(HPR				0x26	0x00	R/W	105
Headphone Amplifier Mixer Control	0	0	MIXHPR_ PATHSEL	MIXHPL_ PATHSEL	MIXHP	R_GAIN	MIXHP	L_GAIN	0x27	0x00	R/W	105
Left Receiver Amplifier Mixer				MIXI	RECL				0x28	0x00	R/W	94
Right Receiver Amplifier Mixer				MIXE	RECR				0x29	0x00	R/W	94
Receiver Amplifier Mixer Control	LINE_ MODE	0	0	0	MIXREC	R_GAIN	MIXREC	CL_GAIN	0x2A	0x00	R/W	94
Left Speaker Amplifier Mixer				MIX	(SPL				0x2B	0x00	R/W	97
Right Speaker Amplifier Mixer				MIX	(SPR				0x2C	0x00	R/W	97
Speaker Amplifier Mixer Control	0	0	0	0	MIXSPI	R_GAIN	MIXSPI	_GAIN	0x2D	0x00	R/W	97

Table 1. Register Map (continued)

REGISTER	B7	В6	B5	B4	В3	B2	B1	В0	ADDRESS	DEFAULT	R/W	PAGE
LEVEL CONT	l .	50		54		52			ADDITECT	DEI AGET	10,00	. AGE
Sidetone	DS	TS	0			DVST			0x2E	0x00	R/W	74
DAI1 Playback Level	DV1M	0		/1G	DV1				0x2F	0x00	R/W	91
DAI1 Playback Level	0	0	0	EQCLP1		DVE	Q1		0x30	0x00	R/W	90
DAI2 Playback Level	DV2M	0	0	0		DV	2		0x31	0x00	R/W	91
DAI2 Playback Level	0	0	0	EQCLP2		DVE	Q2		0x32	0x00	R/W	90
Left ADC Level	0	0	A۱	/LG		AV	L		0x33	0x00	R/W	73
Right ADC Level	0	0	A۷	'RG		AV	R		0x34	0x00	R/W	73
Microphone 1 Input Level	0	PA-	1EN			PGAM1			0x35	0x00	R/W	66
Microphone 2 Input Level	0	PA2	2EN			PGAM2			0x36	0x00	R/W	66
INA Input Level	0	INAEXT	0	0	0		PGAINA		0x37	0x00	R/W	68
INB Input Level	0	INBEXT	0	0	0		PGAINB		0x38	0x00	R/W	68
Left Headphone Amplifier Volume Control	HPLM	0	0			HPVOLL			0x39	0x00	R/W	106
Right Headphone Amplifier Volume Control	HPRM	0	0			HPVOLR			0x3A	0x00	R/W	106
Left Receiver Amplifier Volume Control	RECLM	0	0		l	RECVOLL			0x3B	0x00	R/W	95
Right Receiver Amplifier Volume Control	RECRM	0	0		ı	RECVOLR			0x3C	0x00	R/W	95

Table 1. Register Map (continued)

REGISTER	B7	В6	B5	B4	В3	B2	B1	В0	ADDRESS	DEFAULT	R/W	PAGE
Left Speaker Amplifier Volume Control	SPLM	0	0			SPVOLL			0x3D	0x00	R/W	98
Right Speaker Amplifier Volume Control	SPRM	0	0			SPVOLR			0x3E	0x00	R/W	98
MICROPHON	IE AGC											
Configuration	AGCSRC		AGCRLS	3	AGC	CATK	AGC	HLD	0x3F	0x00	R/W	70, 71
Threshold			NTH			AGC	TH		0x40	0x00	R/W	71
SPEAKER SI	GNAL PR	OCESSIN	NG		1	1	1		1	T		
Excursion Limiter Filter	0		DHPUCF	Ξ	0	0	DHF	PLCF	0x41	0x00	R/W	100
Excursion Limiter Threshold	0	0	0	0	0		DHPTH		0x42	0x00	R/W	100
ALC	ALCEN		ALCRLS)	ALCMB		ALCTH	-	0x43	0x00	R/W	89, 100
Power Limiter		PW	/RTH		0		PWRK		0x44	0x00	R/W	101
Power Limiter		PV	VRT2			PWF	RT1		0x45	0x00	R/W	102
Distortion Limiter		THI	DCLP		0	0	0	THDT1	0x46	0x00	R/W	103
CONFIGURA	TION				J.	L	l		J.	L		
Audio Input	INADIFF	INBDIFF	0	0	0	0	0	0	0x47	0x00	R/W	68
Microphone	MIC	CLK	DIGMICL	DIGMICR	0	0	EXT	MIC	0x48	0x00	R/W	66
Level Control	VS2EN	VSEN	ZDEN	0	0	0	EQ2EN	EQ1EN	0x49	0x00	R/W	90, 108
Bypass Switches	INABYP	0	0	MIC2BYP	0	0	RECBYP	SPKBYP	0x4A	0x00	R/W	67, 107
Jack Detection	JDETEN	0	0	0	0	0	JD	EB	0x4B	0x00	R/W	110
POWER MAN	NAGEMEN	ΙT										
Input Enable	INAEN	INBEN	0	0	MBEN	0	ADLEN	ADREN	0x4C	0x00	R/W	63
Output Enable	HPLEN	HPREN	SPLEN	SPREN	RECLEN	RECREN	DALEN	DAREN	0x4D	0x00	R/W	64
Top-Level Bias Control	BGEN	SPREGEN	VCMEN	BIASEN	0	0	0	0	0x4E	0xF0	R/W	64
DAC Low Power Mode 1		DAI2_	DAC_LP			DAI1_D/	AC_LP		0x4F	0x00	R/W	83
DAC Low Power Mode 2	0	0	0	0	DAC2_IP_ DITH_EN	DAC1_IP_ DITH_EN	CGM2_ EN	CGM1_ EN	0x50	0x0F	R/W	83
System Shutdown	SHDN	VBATEN	0	0	PERFMODE	HPPLYBACK	PWRSV8K	PWRSV	0x51	0x00	R/W	63, 100

Table 1. Register Map (continued)

REGISTER	B7	В6	B5	В4	В3	B2	B1	В0	ADDRESS	DEFAULT	R/W	PAGE
DSP COEFFIC	CIENTS									'	,	
				K_1	[15:8]				0x52/0x84	0xXX	R/W	89
				K_1	[7:0]				0x53/0x85	0xXX	R/W	89
				K1_1	[15:8]				0x54/0x86	0xXX	R/W	89
				K1_	1[7:0]				0x55/0x87	0xXX	R/W	89
EQ Band 1				K2_1	[15:8]				0x56/0x88	0xXX	R/W	89
(DAI1/DAI2)				K2_	1[7:0]				0x57/0x89	0xXX	R/W	89
				c1_1	[15:8]				0x58/0x8A	0xXX	R/W	89
				c1_	1[7:0]				0x59/0x8B	0xXX	R/W	89
				c2_1	[15:8]				0x5A/0x8C	0xXX	R/W	89
				c2_	1[7:0]				0x5B/0x8D	0xXX	R/W	89
				K_2	[15:8]				0x5C/0x8E	0xXX	R/W	89
				K_2	2[7:0]				0x5D/0x8F	0xXX	R/W	89
				K1_2	2[15:8]				0x5E/0x90	0xXX	R/W	89
				K1_	2[7:0]				0x5F/0x91	0xXX	R/W	89
EQ Band 2				K2_2	2[15:8]				0x60/0x92	0xXX	R/W	89
(DAI1/DAI2)				K2_	2[7:0]				0x61/0x93	0xXX	R/W	89
				c1_2	[15:8]				0x62/0x94	0xXX	R/W	89
				c1_2	2[7:0]				0x63/0x95	0xXX	R/W	89
				c2_2	[15:8]				0x64/0x96	0xXX	R/W	89
				c2_2	2[7:0]				0x65/0x97	0xXX	R/W	89
				K_3	[15:8]				0x66/0x98	0xXX	R/W	89
				K_3	8[7:0]				0x67/0x99	0xXX	R/W	89
				K1_3	3[15:8]				0x68/0x9A	0xXX	R/W	89
				K1_:	3[7:0]				0x69/0x9B	0xXX	R/W	89
EQ Band 3				K2_3	8[15:8]				0x6A/0x9C	0xXX	R/W	89
(DAI1/DAI2)				K2_3	3[7:0]				0x6B/0x9D	0xXX	R/W	89
				c1_3	[15:8]				0x6C/0x9E	0xXX	R/W	89
				c1_0	3[7:0]				0x6D/0x9F	0xXX	R/W	89
				c2_3	[15:8]				0x6E/0xAE	0xXX	R/W	89
				c2_0	3[7:0]				0x6F/0xA1	0xXX	R/W	89
				K_4	[15:8]				0x70/0xA2	0xXX	R/W	89
				K_4	[7:0]				0x71/0xA3	0xXX	R/W	89
				K1_4	I[15:8]				0x72/0xA4	0xXX	R/W	89
				K1_4	4[7:0]				0x73/0xA5	0xXX	R/W	89
EQ Band 4				K2_4	[15:8]				0x74/0xA6	0xXX	R/W	89
(DAI1/DAI2)				K2_4	4[7:0]				0x75/0xA7	0xXX	R/W	89
				c1_4	[15:8]				0x76/0xA8	0xXX	R/W	89
				c1_4	4[7:0]				0x77/0xA9	0xXX	R/W	89
				c2_4	[15:8]				0x78/0xAA	0xXX	R/W	89
				c2_4	4[7:0]				0x79/0xAB	0xXX	R/W	89

Table 1. Register Map (continued)

REGISTER	B7	В6	B5	B4	В3	B2	B1	В0	ADDRESS	DEFAULT	R/W	PAGE
				K_5	[15:8]				0x7A/0xAC	0xXX	R/W	89
				K_5	5[7:0]				0x7B/0xAD	0xXX	R/W	89
				K1_5	5[15:8]				0x7C/0xAE	0xXX	R/W	89
				K1_	5[7:0]				0x7D/0xAF	0xXX	R/W	89
EQ Band 5				K2_5	[15:8]				0x7E/0xB0	0xXX	R/W	89
(DAI1/DAI2)				K2_	5[7:0]				0x7F/0xB1	0xXX	R/W	89
				c1_5	[15:8]				0x80/0xB2	0xXX	R/W	89
				c1_	5[7:0]				0x81/0xB3	0xXX	R/W	89
				c2_5	[15:8]				0x82/0xB4	0xXX	R/W	89
				c2_	5[7:0]				0x83/0xB5	0xXX	R/W	89
				a1[15:8]				0xB6/0xC0	0xXX	R/W	89
				a1	[7:0]				0xB7/0xC1	0xXX	R/W	89
				a2[15:8]				0xB8/0xC2	0xXX	R/W	89
Excursion				a2	[7:0]				0xB9/0xC3	0xXX	R/W	89
Limiter				b0[15:8]				0xBA/0xC4	0xXX	R/W	89
Biquad				b0	[7:0]				0xBB/0xC5	0xXX	R/W	89
(DAI1/DAI2)				b1[15:8]				0xBC/0xC6	0xXX	R/W	89
				b1	[7:0]				0xBD/0xC7	0xXX	R/W	89
				b2[15:8]				0xBE/0xC8	0xXX	R/W	89
				b2	[7:0]				0xBF/0xC9	0xXX	R/W	89
REVISION ID									•			
Rev ID				R	REV				0xFF	0x40	R	112

Power Management

The IC includes comprehensive power management to allow the disabling of all unused circuits, minimizing supply current.

Table 2. Power Management Registers

REGISTER	BIT	NAME	DESCRIPTION
	7	SHDN	Global Shutdown. Disables everything except the headset detection circuitry, which is controlled separately. 0 = Device Shutdown 1 = Device Enabled
	6	VBATEN	See the Battery Measurement section.
	3	PERFMODE	Performance Mode. Selects DAC to headphone playback performance mode. 0 = High performance playback mode 1 = Low power playback mode
0x51	2	HPPLYBCK	Headphone Only Playback Mode. Configures System Bias Control register bits for low power playback when using DAC to headphone playback path only. When enabled, this bit overrides the System Bias Control register settings. When disabled, the System Bias Control register is used to enable system bias blocks. Set both HPPLYBCK and PERFMODE for lowest power consumption when using DAC to headphone playback path only. 0 = Disabled 1 = Enabled.
	1	PWRSV8K	8kHz Power Save Mode. PWRSV8K configures the ADC for reduced power consumption when fs = 8kHz. PWRSV8K can be used in conjunction with PWRSV for more power savings. 0 = Normal, high-performance mode. 1 = Low power mode.
	0	PWRSV	Power Save Mode. PWRSV configures the ADC for reduced power consumption for all sample rates. PWRSV can be used in conjunction with PWRSV8K for more power savings. 0 = Normal, high-performance mode. 1 = Low power mode.
	7	INAEN	Line Input A Enable 0 = Disabled 1 = Enabled
	6	INBEN	Line Input B Enable 0 = Disabled 1 = Enabled
0x4C	3	MBEN	Microphone Bias Enable 0 = Disabled 1 = Enabled
	1	ADLEN	Left ADC Enable 0 = Disabled 1 = Enabled
	0	ADREN	Right ADC Enable 0 = Disabled 1 = Enabled

Table 2. Power Management Registers (continued)

REGISTER	BIT	NAME	DESCRIPTION						
	7	HPLEN	Left Headphone Enable 0 = Disabled 1 = Enabled						
	6	HPREN	Right Headphone Enable 0 = Disabled 1 = Enabled						
	5	SPLEN	Left Speaker Enable 0 = Disabled 1 = Enabled						
	4	SPREN	Right Speaker Enable 0 = Disabled 1 = Enabled						
0x4D	3	RECLEN	Receiver/Left Line Output Enable. Use this bit to enable the differential receiver output or left line output. 0 = Disabled 1 = Enabled						
	2	RECREN RECREN							
	1	DALEN	Left DAC Enable 0 = Disabled 1 = Enabled						
	0	DAREN	Right DAC Enable 0 = Disabled 1 = Enabled						
	7	BGEN	Bandgap Enable 0 = Disabled 1 = Enabled						
0.45	6	SPREGEN	2.5V Regulator Enable. SPREGEN enables a 2.5V internal regulator required for the ADC, speaker and receiver amplifier. The 2.5V regulator is powered by SPKLVDD. 0 = Disabled 1 = Enabled						
0x4E	5	VCMEN	Common-Mode Voltage Resistor String Enable. VCMEN enables the common mode voltages for the amplifiers in the CODEC. 0 = Disabled 1 = Enabled						
	4	BIASEN	Chip Bias Enable. BIASEN needs to be set for the CODEC amplifiers to be enabled. 0 = Disabled 1 = Enabled						

Microphone Inputs

The device includes three differential microphone inputs and a low-noise microphone bias for powering the microphones (Figure 6). One microphone input can also be configured as a digital microphone input accepting signals from up to two digital microphones. Two microphones, analog or digital, can be recorded simultaneously.

In the typical application, one microphone input is used for the handset microphone and the other is used as an accessory microphone. In systems using a background noise microphone, INA can be retasked as another microphone input.

In systems where the codec is not the only device recording microphone signals, connect microphones to

MIC2P/MIC2N and EXTMICP/EXTMICN. MIC1P/MIC1N then become outputs that route the microphone signals to an external device as needed. Two devices can then record microphone signals without needing external analog switches.

Analog microphone signals are amplified by two stages of gain and then routed to the ADCs. The first stage offers selectable 0dB, 20dB, or 30dB settings. The second stage is a programmable-gain amplifier (PGA) adjustable from 0dB to 20dB in 1dB steps. To maximize the signal-to-noise ratio, use the gain in the first stage whenever possible. Zero-crossing detection is included on the PGA to minimize zipper noise while making gain changes.

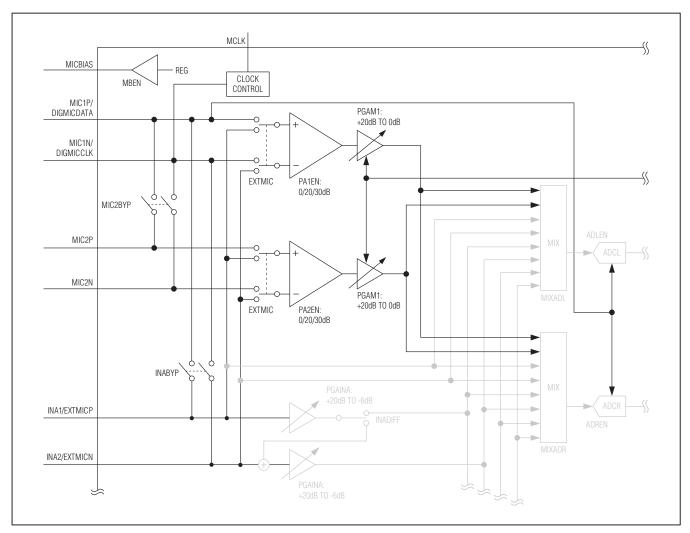


Figure 6. Microphone Input Block Diagram

Table 3. Microphone Input Registers

REGISTER	BIT	NAME		DESC	RIPTION						
	6	PA1EN/PA2EN	MIC1/MIC2 Preamplifier Gain Course microphone gain adjustment. 00 = Preamplifier disabled 01 = 0dB 10 = 20dB								
	4		11 = 30dB MIC1/MIC2 PGA Fine microphone gain adjustment.								
			VALUE	GAIN (dB)	VALUE	GAIN (dB)					
	3		0x00	+20	0x0B	+9					
0x35/0x36			0x01	+19	0x0C	+8					
			0x02	+18	0x0D	+7					
	2		0x03	+17	0x0E	+6					
		PGAM1/PGAM2	0x04	+16	0x0F	+5					
			0x05	+15	0x10	+4					
	1		0x06	+14	0x11	+3					
			0x07	+13	0x12	+2					
			0x08	+12	0x13	+1					
	0		0x09	+11	0x14 to 0x1F	0					
			0x0A	+10							
			Digital Microphone	Clock Frequency							
	7	MICOLK	Select a frequency that is within the digital microphone's clock frequency range. Set OSR1 = 1 when using a digital microphone.								
	6	MICCLK	00 = PCLK/8 01 = PCLK/6 10 = 64 x LRCLK 11 = Reserved								
040	5	DIGMICL	Left Digital Microp Set PAL1EN = 00 fc 0 = Disabled 1 = Enabled								
0x48	4	DIGMICR	Right Digital Micro Set PAR1EN = 00 for 0 = Disabled 1 = Enabled								
	1	EXTMIC	External Microphone Connection Routes INA_/EXTMIC_ to the microphone preamplifiers. Set INAEN = 0 when using INA_/EXTMIC_ as a microphone input.								
	0	EXTIVILE	00 = Disabled 01 = MIC1 input 10 = MIC2 input 11 = Reserved	10 = MIC2 input							

Table 3. Microphone Input Registers (continued)

REGISTER	BIT	NAME	DESCRIPTION		
	7	INABYP	INA_/EXTMIC_ to MIC1_ Bypass Switch 0 = Disabled 1 = Enabled		
0x4A	4	MIC2BYP	MIC1_ to MIC2_ Bypass Switch 0 = Disabled 1 = Enabled		
UX4A	1	RECBYP	See the <i>Output Bypass Switches</i> section.		
	0	SPKBYP	dee the Output Dypass Switches Section.		

Line Inputs

The device includes two sets of line inputs (Figure 7). Each set can be configured as a stereo single-ended input or as a mono differential input. Each input includes adjustable gain to match a wide range of input signal levels. If a custom gain is needed, the external gain mode provides a trimmed feedback resistor. Set the gain

PGAINA:
+20dB TO -6dB

INBI

PGAINB:
+20dB TO -6dB

PGAINB:
+20dB TO -6dB

INBDIFF

PGAINB:
+20dB TO -6dB

Figure 7. Line Input Block Diagram

by choosing the appropriate input resistor and using the following formula:

$$AVPGAIN = 20 \times log (20K/RIN)$$

The external gain mode also allows summing multiple signals into a single input, by connecting multiple input resistors as show in Figure 8, and inputting signals larger than 1VP-P.

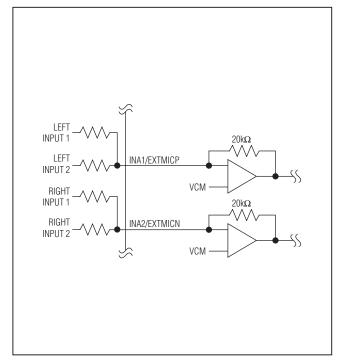


Figure 8. Summing Multiple Input Signals into INA/INB

INB2

Table 4. Line Input Registers

REGISTER	BIT	NAME	DESCRIPTION		
0x37/0x38	6	INAEXT/INBEXT	Line Input A/B External Gain Switches out the internal input resistor and selects a trimmed $20k\Omega$ feedback resistor. Use an external input resistor to set the gain of the line input. $0 = Disabled$ $1 = Enabled$		
	2		Line Input A/B Internal Gain Settings $000 = +20 dB$ $001 = +14 dB$		
	1	PGAINA/PGAINB	010 = +3dB 011 = 0dB 100 = -3dB		
	0		101 = -6dB 110 = -6dB 111 = -6dB		
0x47	7	INADIFF	Line Input A Differential Enable 0 = Stereo single-ended input 1 = Mono differential input		
UX47	6	INBDIFF	Line Input B Differential Enable 0 = Stereo single-ended input 1 = Mono differential input		

ADC Input Mixers

The IC's stereo ADC accepts input from the microphone amplifiers, line inputs amplifiers, and directly from the INA1 and INA2. The ADC mixer routes any combination of the eight audio inputs to the left and right ADCs (Figure 9).

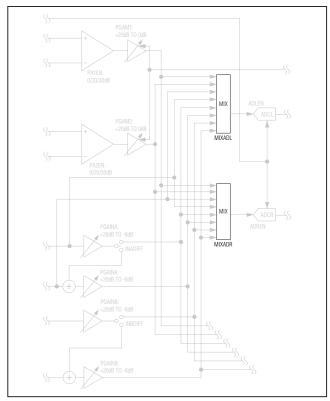


Figure 9. ADC Input Mixer Block Diagram

Table 5. ADC Input Mixer Register

REGISTER	BIT	NAME	DESCRIPTION			
	7	MIXADL/MIXADR	Left/Right ADC Input Mixer			
	6		Selects which analog inputs are recorded by the left/right ADC. 1xxxxxxx = MIC1 x1xxxxxx = MIC2 xx1xxxxx = INA1 pin direct xxx1xxxx = INA2 pin direct xxx1xxxx = INA1			
	5					
0.00/0.04	4					
0x23/0x24	3					
	2					
	1		xxxxx1xx = INA2 (INADIFF = 0) or INA2 - INA1 (INADIFF = 1) xxxxxx1x = INB1			
	0		xxxxxxx1 = INB2 (INBDIFF = 0) or INB2 - INB1 (INBDIFF = 1)			

Record Path Signal Processing

The device's record signal path includes both automatic gain control (AGC) for the microphone inputs and a digital noise gate at the output of the ADC (Figure 10).

Microphone AGC

The IC's AGC monitors the signal level at the output of the ADC and then adjusts the MIC1 and MIC2 analog PGA settings automatically. When the signal level is below the predefined threshold, the gain is increased up to its maximum (20dB). If the signal exceeds the threshold, the gain is reduced to prevent the output signal level exceeding the threshold. When AGC is enabled, the microphone PGA is not user programmable. The AGC provides a more constant signal level and improves the available ADC dynamic range.

Noise Gate

Since the AGC increases the levels of all signals below a user-defined threshold, the noise floor is effectively increased by 20dB. To counteract this, the noise gate reduces the gain at low signal levels. Unlike typical noise gates that completely silence the output below a defined level, the noise gate in the IC applies downward expansion. The noise gate attenuates the output at a rate of 1dB for each 2dB the signal is below the threshold.

The noise gate can be used in conjunction with the AGC or on its own. When the AGC is enabled, the noise gate reduces the output level only when the AGC has set the gain to the maximum setting. Figure 11 shows the gain response resulting from using the AGC and noise gate.

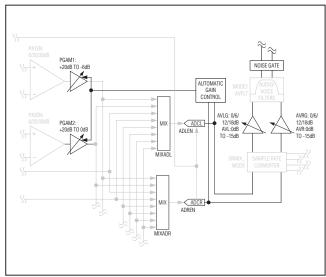


Figure 10. Record Path Signal Processing Block Diagram

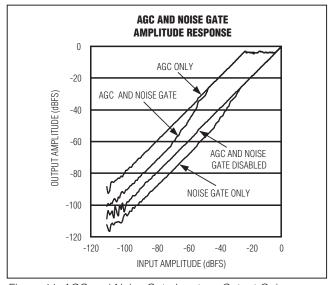


Figure 11. AGC and Noise Gate Input vs. Output Gain

Table 6. Record Path Signal Processing Registers

REGISTER	BIT	NAME	DESCRIPTION					
	7		Noise Gate Attenuation Reports the current noise gate attenuation. 000 = 0dB					
	6	NG	001 = 1dB 010 = 2dB 011 = 3dB to 5dB 100 = 6dB to 7dB					
	5		101 = 8dB to 9dB 110 = 10dB to 11dB 111 = 12dB					
	4		AGC Gain Reports the current AGC gain setting.					
0x01			VALUE	GAIN (dB)	VALUE	GAIN (dB)		
0.10			0x00	+20	0x0B	+9		
	3		0x01	+19	0x0C	+8		
			0x02	+18	0x0D	+7		
		AGC	0x03	+17	0x0E	+6		
	2		0x04	+16	0x0F	+5		
			0x05	+15	0x10	+4		
	1		0x06	+14	0x11	+3		
			0x07	+13	0x12	+2		
			0x08	+12	0x13	+1		
	0		0x09	+11	0x14 to 0x1F	0		
			0x0A	+10				
	7	AGCSRC	AGC/Noise Gate Signal Source Determines which ADC channel the AGC and noise gates analyze. Gain is adjusted on both channels regardless of the AGCSRC setting. 0 = Left ADC output 1 = Maximum of either the left or right ADC output					
0x3F	6		AGC Release Time Defined as the duration from start to finish of gain increase in the region shown in Figure 12. Release times are longer for low AGC threshold levels. 000 = 78ms					
	5	AGCRLS	001 = 156ms 010 = 312ms 011 = 625ms 100 = 1.25s					
	4		101 = 2.5s 110 = 5s 111 = 10s					

Table 6. Record Path Signal Processing Registers (continued)

REGISTER	BIT	NAME	DESCRIPTION					
0x3F	2	AGCATK	AGC Attack Time Defined as the time required to reduce gain by 63% of the total gain reduction (one time constant of the exponential response). Attack times are longer for low AGC threshold levels. See Figure 12 for details. 00 = 2ms 01 = 7.2ms 10 = 31ms 11 = 123ms					
	1	AGCHLD	AGC Hold Time The delay before the AGC release begins. The hold time counter starts whenever the signal drops below the AGC threshold and is reset by any signal that exceeds the threshold. Set AGCHLD to enable the AGC circuit. See Figure 12 for details.					
	0		00 = AGC disabled 01 = 50ms 10 = 100ms 11 = 400ms					
	7	ANTH	Noise Gate Threshold Gain is reduced for signals below the threshold to quiet noise. The thresholds are relative to the ADC's full-scale output voltage.					
	6		VALUE	THRESHOLD (dBFS)	VALUE	THRESHOLD (dBFS)		
			0x0	Noise gate disabled	0x8	-45		
			0x1	Reserved	0x9	-41		
			0x2	Reserved	0xA	-38		
	5		0x3	-64	0xB	-34		
			0x4	-62	0xC	-30		
	4		0x5	-58	0xD	-27		
			0x6	-53	0xE	-22		
0×40			0x7	-50	0xF	-16		
0x40	3		AGC Threshold Gain is reduced when signals exceed the threshold to prevent clipping. The thresholds are relative to the ADC's full-scale voltage.					
	2	AGCTH	VALUE	THRESHOLD (dBFS)	VALUE	THRESHOLD (dBFS)		
			0x0	-3	0x8	-11		
			0x1	-4	0x9	-12		
	1		0x2	-5	0xA	-13		
			0x3	-6	0xB	-14		
			0x4	-7	0xC	-15		
	0		0x5	-8	0xD	-16		
			0x6	-9	0xE	-17		
			0x7	-10	0xF	-18		

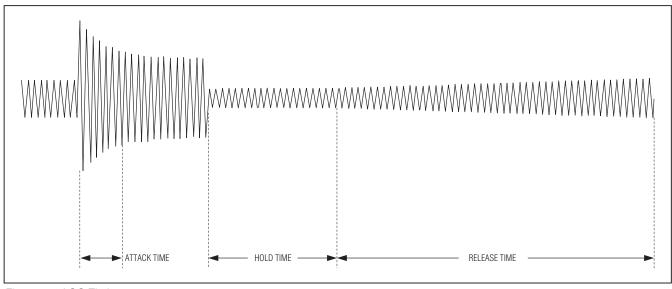


Figure 12. AGC Timing

ADC Record Level Control

The IC includes separate digital level control for the left and right ADC outputs (Figure 13). To optimize dynamic

range, use analog gain to adjust the signal level and set the digital level control to 0dB whenever possible. Digital level control is primarily used when adjusting the record level for digital microphones.

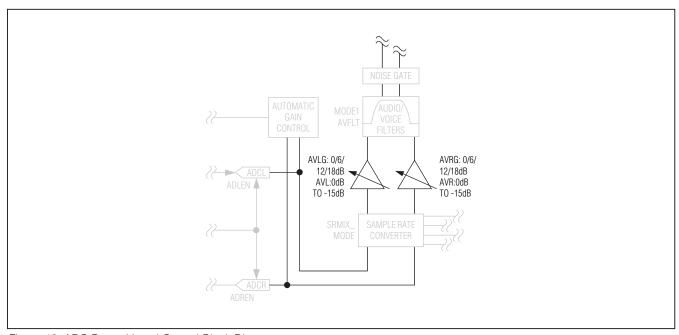


Figure 13. ADC Record Level Control Block Diagram

Table 7. ADC Record Level Control Register

REGISTER	BIT	NAME		DESCR	RIPTION	
	5	AVI G/AVBG	Left/Right ADC Gain 00 = 0dB 01 = 6dB	1		
	4	- AVLG/AVRG	10 = 12dB 11 = 18dB			
	3		Left/Right ADC Leve	el		
		AVL/AVR	VALUE	GAIN (dB)	VALUE	GAIN (dB)
0x33/0x34	2		0x0	+3	0x8	-5
			0x1	+2	0x9	-6
			0x2	+1	0xA	-7
	1		0x3	0x3 0		-8
			0x4	-1	0xC	-9
			0x5		0xD	-10
	0		0x6 -3		0xE	-11
			0x7	-4	0xF	-12

Sidetone

Enable sidetone during full-duplex operation to add a low-level copy of the recorded audio signal to the play-back audio signal (Figure 14). Sidetone is commonly

used in telephony to allow the speaker to hear himself speak, providing a more natural user experience. The IC implements sidetone digitally. Doing so helps prevent unwanted feedback into the playback signal path and better matches the playback audio signal.

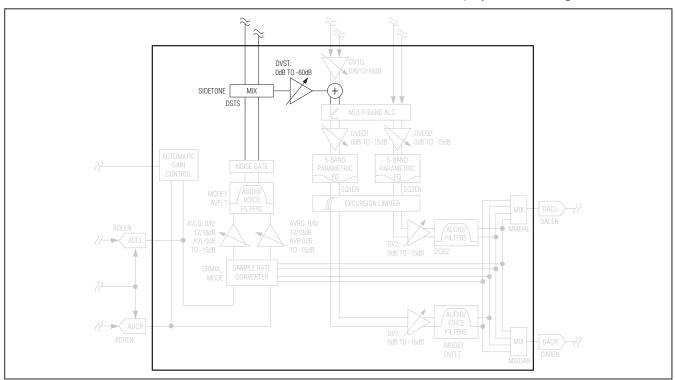


Figure 14. Sidetone Block Diagram

Table 8. Sidetone Register

REGISTER	BIT	NAME		DESCR	IPTION			
	7	DSTS	Sidetone Source Selects which ADC output is fed back as sidetone. When mixing the left and right ADC outputs, each is attenuated by 6dB to prevent full-scale signals from clipping. 00 = Sidetone disabled 01 = Left ADC					
	6		10 = Right ADC 11 = Left + Right ADC)				
	4		Sidetone Level Adjusts the sidetone s	signal level. All levels a	re referenced to the AL			
			VALUE	LEVEL (dB)	VALUE	LEVEL (dB)		
	3		0x00	Sidetone disabled	0x10	-30.5		
		DVST	0x01	-0.5	0x11	-32.5		
			0x02	-2.5	0x12	-34.5		
0x2E			0x03	-4.5	0x13	-36.5		
	2		0x04	-6.5	0x14	-38.5		
			0x05	-8.5	0x15	-40.5		
	-		0x06	-10.5	0x16	-42.5		
			0x07	-12.5	0x17	-44.5		
			0x08	-14.5	0x18	-46.5		
	1 1		0x09	-16.5	0x19	-48.5		
	'		0x0A	-18.5	0x1A	-50.5		
			0x0B	-20.5	0x1B	-52.5		
			0x0C	-22.5	0x1C	-54.5		
	0		0x0D	-24.5	0x1D	-56.6		
			0x0E	-26.5	0x1E	-58.5		
			0x0F	-28.5	0x1F	-60.5		

Digital Audio Interfaces

The IC includes two separate playback signal paths and one record signal path. Digital audio interface 1 (DAI1) is used to transmit the recorded stereo audio signal and receive a stereo audio signal for playback. Digital audio interface 2 (DAI2) is used to receive a second stereo audio signal. Use DAI1 for all full-duplex operations and for all voice signals. Use DAI2 for music and to mix two playback audio signals. The digital audio interfaces are separate from the audio ports to enable either interface to communicate with any external device connected to the audio ports.

Each audio interface can be configured in a variety of formats including left justified, I2S, PCM, and time division multiplexed (TDM). TDM mode supports up to 4 mono audio slots in each frame. The IC can use up to

2 mono slots per interface, leaving the remaining two slots available for another device. Table 9 shows how to configure the device for common digital audio formats. Figures 16 and 17 show examples of common audio formats. By default, SDOUTS1 and SDOUTS2 are set high impedance when the IC is not outputting data to facilitate sharing the bus. Configure the interface in TDM mode using only slot 1 to transmit and receive mono PCM voice data.

The IC's digital audio interfaces support both ADC to DAC loop-through and digital loopback. Loop-through allows the signal converted by the ADC to be routed to the DAC for playback. The signal is routed from the record path to the playback path in the digital audio interface to allow the IC's full complement of digital signal processing to be used. Loopback allows digital

data input to either SDINS1 or SDINS2 to be routed from one interface to the other for output on SDOUTS2 or SDOUTS1. Both interfaces must be configured for the same sample rate, but the interface format need

not be the same. This allows the IC to route audio data from one device to another, converting the data format as needed. Figure 15 shows the available digital signal routing options.

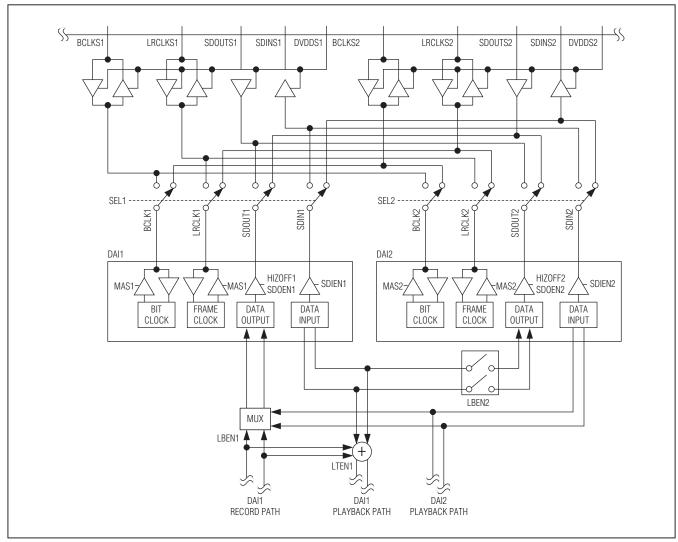


Figure 15. Digital Audio Signal Routing

Table 9. Common Digital Audio Formats

MODE	WCI1/WCI2	BCI1/BCI2	DLY1/DLY2	TDM1/TDM2	SLOTL1/SLOTL2	SLOTR1/SLOTR2
Left Justified	Set as desired	Set as desired	0	0	X	X
I2S	1	0	1	0	X	X
PCM	X	1	X	1	0	0
TDM	X	1	X	1	Set as	desired

X = Don't care.

Table 10. Digital Audio Interface Registers

REGISTER	BIT	NAME	DESCRIPTION
	7	MAS1/MAS2	DAI1/DAI2 Master Mode In master mode, DAI1/DAI2 outputs LRCLK and BCLK. In slave mode, DAI1/DAI2 accept LRCLK and BCLK as inputs. 0 = Slave mode 1 = Master mode
	6	WCI1/WCI2	DAI1/DAI2 Word Clock Invert TDM1/TDM2 = 0: 0 = Left-channel data is transmitted while LRCLK is low. 1 = Right-channel data is transmitted while LRCLK is low. TDM1/TDM2 = 1: Always set WCI = 0.
	5	0 = SDIN is accepted on the rising SDOUT is valid on the rising e 1 = SDIN is accepted on the falling SDOUT is valid on the falling Master Mode: 0 = LRCLK transitions on the falling	BCI1/BCI2 must be set to 1 when TDM1/TDM2 = 1. 0 = SDIN is accepted on the rising edge of BCLK. SDOUT is valid on the rising edge of BCLK. 1 = SDIN is accepted on the falling edge of BCLK. SDOUT is valid on the falling edge of BCLK.
0x14/0x1C	4	DLY1/DLY2	DAI1/DAI2 Data Delay DLY1/DLY2 has no effect when TDM1/TDM2 = 1. 0 = The most significant data bit is clocked on the first active BCLK edge after an LRCLK transition. 1 = The most significant data bit is clocked on the second active BCLK edge after an LRCLK transition.
	2	TDM1/TDM2	DAI1/DAI2 Time-Division Multiplex Mode (TDM Mode) Set TDM1/TDM2 when communicating with devices that use a frame synchronization pulse on LRCLK instead of a square wave. 0 = Disabled 1 = Enabled (BCI1/BCI2 must be set to 1)
	1	FSW1/FSW2	DAI1/DAI2 Wide Frame Sync Pulse Increases the width of the frame sync pulse to the full data width when TDM1/TDM2 = 1. FSW1/FSW2 has no effect when TDM1/TDM2 = 0. 0 = Disabled 1 = Enabled
	0	WS1/WS2	DAI1/DAI2 Audio Data Bit Depth Determines the maximum bit depth of audio being transmitted and received. Data is always 16 bit when TDM1/TMD2 = 0. 0 = 16 bits 1 = 24 bits

Table 10. Digital Audio Interface Registers (continued)

REGISTER	BIT	NAME	DESCRIPTION
	7	OSR1	ADC Oversampling Ratio Use the higher setting for maximum performance. Use the lower setting for reduced power consumption at the expense of performance. 00 = 96x
	6	OSNI	01 = 64x 10 = Reserved 11 = Reserved
	5	DAC_OSR1/ DAC_OSR2	DAC Oversample Clock (DAC_OSR1/DAC_OSR2 1 = DAC input clock = PCLK/4 0 = DAC input clock = PCLK/2
0x15/0x1D	2		DAI1/DAI2 BCLK Output Frequency When operating in master mode, BSEL1/BSEL2 set the frequency of BCLK. When operating in slave mode, BSEL1/BSEL2 have no effect. Select the lowest BCLK frequency that clocks all data input to the DAC and output by the ADC.
	1	BSEL1/ BSEL2	000 = BCLK disabled 001 = 64 x LRCLK 010 = 48 x LRCLK 011 = 128 x LRCLK (invalid for DHF1/DHF2 = 1)
	0		100 = PCLK/2 101 = PCLK/4 110 = PCLK/8 111 = PCLK/16
	7	0514/0510	DAI1/DAI2 Audio Port Selector Selects which port is used by DAI1/DAI2. 00 = None
	6	SEL1/SEL2	01 = Port S1 10 = Port S2 11 = Reserved
	5	LTEN1	DAI1 Digital Loopthrough Connects the output of the record signal path to the input of the playback path. Data input to DAI1 from an external device is mixed with the recorded audio signal. 0 = Disabled 1 = Enabled
0x16/0x1E	4	LBEN1/ LBEN2	DAI1/DAI2 Digital Audio Interface Loopback LBEN1 routes the digital audio input to DAI1 back out on DAI2. LBEN2 routes the digital audio input to DAI2 back out on DAI2. Selecting LBEN2 disables the ADC output data. 0 = Disabled 1 = Enabled
	3	DMONO1/ DMONO2	DAI1/DAI2 DAC Mono Mix Mixes the left and right digital input to mono and routes the combined signal to the left and right playback paths. The left and right input data is attenuated by 6dB prior to the mono mix. 0 = Disabled 1 = Enabled

Table 10. Digital Audio Interface Registers (continued)

REGISTER	BIT	NAME	DESCRIPTION		
	2	HIZOFF1/ HIZOFF2	Disable DA1/DAI2 Output High-Impedance Mode Normally SDOUT is set high impedance between data words. Set HIZOFF1/HIZOFF2 to force a level on SDOUT at all times. 0 = Disabled 1 = Enabled		
0x16/0x1E	1	SDOEN1/ SDOEN2	DAI1/DAI2 Record Path Output Enable DAI2 outputs data only if LBEN1 = 1. 0 = Disabled 1 = Enabled		
	0	SDIEN1/ SDIEN2	DAI1/DAI2 Playback Path Input Enable 0 = Disabled 1 = Enabled		
	7	SLOTL1/	TDM Left Time Slot Selects which of the four slots is used for left data on DAI1/DAI2. If the same slot is selected for left and right audio, left audio is placed in the slot. 00 = Slot 1		
		SLOTL2	01 = Slot 2 10 = Slot 3 11 = Slot 4		
0x17/0x1F	5	SLOTR1/	TDM Right Time Slot Selects which of the four slots is used for right data on DAI1/DAI2. If the same slot is selected for left and right audio, left audio is placed in the slot. 00 = Slot 1		
<i>5</i> , , , , , , , , , , , , , , , , , , ,	4	SLOTR2	01 = Slot 2 10 = Slot 3 11 = Slot 4		
	3		TDM Slot Delay		
	2	SLOTDLY1/	Adds 1 BCLK cycle delay to the data in the specified TDM slot. 1xxx = Slot 4 delayed		
	1	SLOTDLY2	x1xx = Slot 3 delayed xx1x = Slot 2 delayed		
	0		xxx1 = Slot 1 delayed		

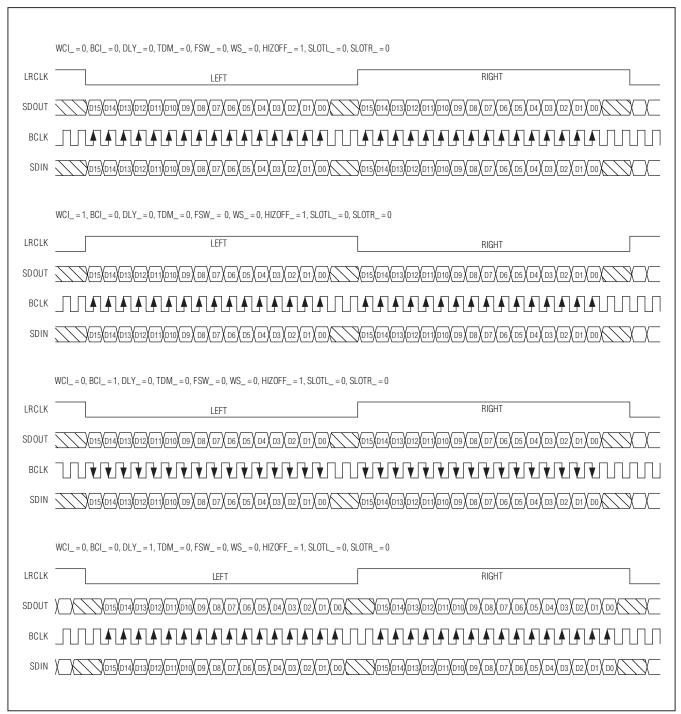


Figure 16. Non-TDM Data Format Examples

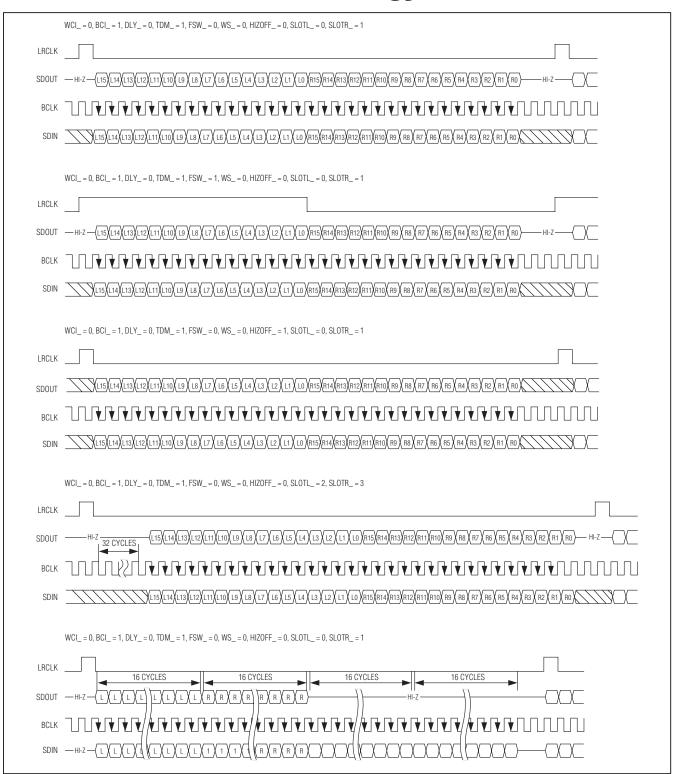


Figure 17. TDM Mode Data Format Examples

Clock Control

The digital signal paths in the IC require a master clock (MCLK) between 10MHz and 60MHz to function. Internally, the MAX98088/MAX98089 requires a clock between 10MHz and 20MHz. A prescaler divides MCLK by 1, 2, or 4 to create the internal clock (PCLK). PCLK is used to clock all portions of the IC.

The MAX98088/MAX98089 includes two digital audio signal paths, both capable of supporting any sample rate from 8kHz to 96kHz. Each path is independently configured to allow different sample rates. To accommodate a wide range of system architectures, three main clocking modes are supported:

• **PLL Mode:** When operating in slave mode, enable the PLL to lock onto any LRCLK input. This mode requires the least configuration, but provides the lowest performance. Use this mode to simplify initial setup or when normal mode and exact integer mode cannot be used.

- Normal Mode: This mode uses a 15-bit clock divider to set the sample rate relative to PCLK. This allows high flexibility in both the PCLK and LRCLK frequencies and can be used in either master or slave mode.
- Exact Integer Mode (DAI1 only): In both master and slave modes, common MCLK frequencies (12MHz, 13MHz, 16MHz, and 19.2MHz) can be programmed to operate in exact integer mode for both 8kHz and 16kHz sample rates. In these modes, the MCLK and LRCLK rates are selected by using the FREQ1 bits instead of the NI. and PLL control bits.
- DAC Low-Power Mode: This mode bypasses the PLL for reduce power consumptions and uses fixed counters to generate the clocks. The DAI_DAC_LP bits override the overclock settings.

Table 11. Clock Control Registers

REGISTER	BIT	NAME	DESCRIPTION					
0x10	5	PSCLK	MCLK Prescaler Generates PCLK, wh 00 = PCLK disabled	Generates PCLK, which is used by all internal circuitry.				
0.10	$01 = 10 \text{MHz} \le \text{MCLK} \le 20 \text{MHz} (\text{PCLK} = \text{MCLK})$ $10 = 20 \text{MHz} \le \text{MCLK} \le 40 \text{MHz} (\text{PCLK} = \text{MCLK}/2)$ $11 = 40 \text{MHz} \le \text{MCLK} \le 60 \text{MHz} (\text{PCLK} = \text{MCLK}/4)$							
	7		Used by the ALC to d	DAI1/DAI2 Sample Rate Used by the ALC to correctly set the dual-band crossover frequency and the excursion limiter to set the predefined corner frequencies.				
	6	6	VALUE	SAMPLE RATE (kHz)	VALUE	SAMPLE RATE (kHz)		
			0x0	Reserved	0x8	48		
0x11/0x19		SR1/SR2	0x1	8	0x9	88.2		
	5		0x2	11.025	0xA	96		
			0x3	16	0xB	Reserved		
		4	0x4	22.05	0xC	Reserved		
			0x5	24	0xD	Reserved		
	4		0x6	32	0xE	Reserved		
			0x7	44.1	0xF	Reserved		

Table 11. Clock Control Registers (continued)

REGISTER	BIT	NAME	DESCRIPTION					
			Exact Integer Mode Overrides PLL1 and I	NI1 and config	gures a sp	ecific PCLK to	LRCLK ratio.	
	3		VALUE	SAMPLE	RATE	VALUE	SAMPLE RATE	
			0x0	Disable	ed	0x8	PCLK = 12MHz, LRCLK = 8kHz	
			0x1	Reserve	ed	0x9	PCLK = 12MHz, LRCLK = 16kHz	
	2		0x2	Reserve	ed	0xA	PCLK = 13MHz, LRCLK = 8kHz	
0x11	2	FREQ1	0x3	Reserve	ed	0xB	PCLK = 13MHz, LRCLK = 16kHz	
			0x4	Reserve	ed	0xC	PCLK = 16MHz, LRCLK = 8kHz	
			0x5	Reserve	ed	0xD	PCLK = 16MHz, LRCLK = 16kHz	
	1		0x6	Reserve	ed	0xE	PCLK = 19.2MHz, LRCLK = 8kHz	
			0x7	Reserved		0xF	PCLK = 19.2MHz, LRCLK = 16kHz	
	7 PLL1/PLL2		PLL Mode Enable (Slave Mode Only) PLL1/PLL2 enables a digital PLL that locks on to the externally supplied LRCLK frequency and automatically sets the LRCLK divider (NI1/NI2). 0 = Disabled 1 = Enabled					
0x12/0x1A	5		Normal Mode LRCLK Divider When PLL1/PLL2 = 0, the frequency of LRCLK is determin for common NI values.				ed by NI1/NI2. See Table 12	
	3 2		SAMPLE RATE	.	DHF1/DHF2		NI1/NI2 FORMULA	
	1 0	NI1/	8kHz ≤ LRCLK ≤ 48	3kHz	Hz 0		$NI = \frac{65536 \times 96 \times f_{LRCLK}}{f_{PCLK}}$	
	7	NI2					I OLIX	
	6		48kHz < LRCLK < 9	CI/LI-	1		$NI = \frac{65536 \times 48 \times f_{LRCLK}}{}$	
	5		40KI 12 < LHOLK \(\leq 9\)	OKI IZ	'		f _{PCLK}	
	4							
	3		fLRCLK = LRCLK fred	uency				
0x13/0x1B	1		fPCLK = Prescaled MCLK frequency (PCLK)					
0.010,000	0	NI1[0]/NI2[0]	to enable rapid lock adjusts NI1/NI2. Whe	mode. Normal en rapid lock n orrect value, t	ly, the PLL node is pro hus speed	automatically aperly configuiding up lock tire	NI2[0] when PLL1/PLL2 = 1 valculates and dynamically red, the PLL starting point is me. Wait one LRCLK period	

Table 11. Clock Control Registers (continued)

REGISTER	BIT	NAME	jisters (continu	DESCRIF	PTION		
	7		DAI_ DAC Low Pow These bits setup the for DAC low power n	ver Select. clocks to be generated f		that bypass the PLL	
			VALUE SETTING		VALUE	SETTING	
	6	DAI2_DAC_LP	0x0	PLL derived clock	0x8	PCLK = 2304 x LRCLK	
	5		0x1	PCLK = 128 x LRCLK	0x9	Reserved	
0.45	4		0x2	PCLK = 192 x LRCLK	0xA	Reserved	
0x4F	3		0x3	PCLK = 256 x LRCLK	0xB	Reserved	
	3		0x4	PCLK = 384 x LRCLK	0xC	Reserved	
	2	DAI1_DAC_LP	0x5	PCLK = 768 x LRCLK	0xD	Reserved	
	1		0x6	PCLK = 1152 x LRCLK	0xE	Reserved	
	0		0x7	PCLK = 1536 x LRCLK	0xF	Reserved	
	3	DAC2DITHEN	DIA2 DAC Input Dither Enable DAC2DITHEN is recommended to be set when DAI2_DAC_LP = 0000. 0 = Disabled 1 = Enabled				
	2	DAC1DITHEN	DIA1 DAC Input Dither 1 Enable DAC1DITHEN is recommended to be set when DAI1_DAC_LP = 0000. 0 = Disabled 1 = Enabled				
0x50	1	CGM2_EN	DIA2 Clock Gen Module Enable CGM1_EN has to be set along with CGM2_EN to enable the clock generation for DAI2 DAC playback path. 0 = Disabled 1 = Enabled				
	0	CGM1_EN	1 = Enabled DIA1/Master Clock Gen Module Enable CGM1_EN enables the master clock generation, and need to be set for DAC playbac or ADC record. 0 = Disabled 1 = Enabled				

Table 12. Common NI1/NI2 Values

						LRCL	K (kHz)						
PCLK (MHz)					DHF1/2 =	0				[DHF1/2 = 1		
	8	11.025	12	16	22.05	24	32	44.1	48	64	88.2	96	
10	13A9	1B18	1D7E	2752	3631	3AFB	4EA5	6C61	75F7	4EA5	6C61	75F7	
11	11E0	18A2	1ACF	23BF	3144	359F	477E	6287	6B3E	477E	6287	6B3E	
11.2896	116A	1800	1A1F	22D4	3000	343F	45A9	6000	687D	45A9	6000	687D	
12	1062	1694	1893	20C5	2D29	3127	4189	5A51	624E	4189	5A51	624E	
12.288	1000	160D	1800	2000	2C1A	3000	4000	5833	6000	4000	5833	6000	
13	0F20	14D8	16AF	1E3F	29AF	2D5F	3C7F	535F	5ABE	3C7F	535F	5ABE	
16	0C4A	10EF	126F	1893	21DE	24DD	3127	43BD	49BA	3127	43BD	49BA	
16.9344	0B9C	1000	116A	1738	2000	22D4	2E71	4000	45A9	2E71	4000	45A9	
18.432	0AAB	0EB3	1000	1555	1D66	2000	2AAB	3ACD	4000	2AAB	3ACD	4000	
20	09D5	0D8C	0EBF	13A9	1B18	1D7E	2752	3631	3AFB	2752	3631	3AFB	

Note: Values in bold are exact integers that provide maximum full-scale performance.

Sample Rate Converter

The sample rate conversion scheme enables the mixing of asynchronous audio data from the digital audio inter-

faces (SDIN1/SDIN2), and for the resulting mixed audio to output on either audio interface through SDOUT1 or SDOUT2.

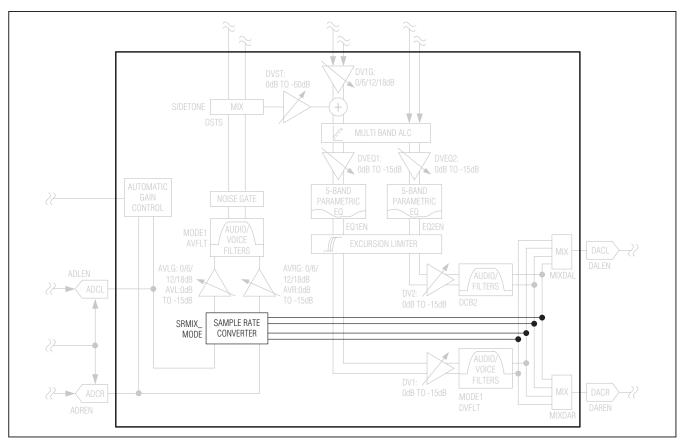


Figure 18. Sample Rate Converter

Table 13. Sample Rate Converter

REGISTER	BIT	NAME	DESCRIPTION
	4	SRMIX_MODE	Sample Rate Mix Mode 0 = (DAI1 + DAI2) 1 = (DAI1 + DAI2)/2
0x21	3	SRMIX_ENL	Sample Rate Mix Enable
UNZ I	2	SRMIX_ENR	0 = SRC mix disable 1 = SRC mix enable
	1	SRC_ENL	Sample Rate Converter Enable 0 = Sample rate converter disable
	0	SRC_ENR	1 = Sample rate converter disable 1 = Sample rate converter enable

Passband Filtering

Each digital signal path in the IC includes options for defining the path bandwidth (Figure 19). The playback and record paths connected to DAI1 support both voice and music filtering while the playback path connected to DAI2 supports music filtering only.

The voice IIR filters provide greater than 70dB stopband attenuation at frequencies above fs/2 to reduce aliasing. Three selectable highpass filters eliminate unwanted low-frequency signals.

Use music mode when processing high-fidelity audio content. The music FIR filters reduce power consumption and are linear phase to maintain stereo imaging. An optional DC-blocking filter is available to eliminate unwanted DC offset.

In music mode, a second set of FIR filters are available to support sample rates greater than 50kHz. The filters can be independently selected for DAI1 and DAI2 and support both the playback and record audio paths.

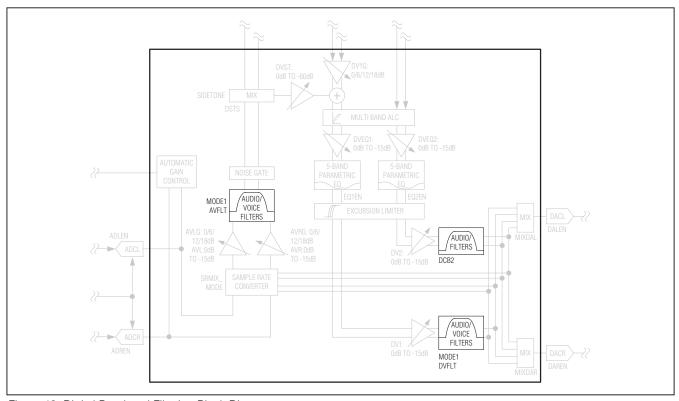


Figure 19. Digital Passband Filtering Block Diagram

Table 14. Passband Filtering Registers

REGISTER	BIT	NAME		DESCF	RIPTION				
	7	MODE1	0 = Voice filters	DAI1 Passband Filtering Mode 0 = Voice filters 1 = Music filters (recommended for fs > 24kHz)					
	6		DAI1 ADC Highpa	DAI1 ADC Highpass Filter Mode					
	5		MODE1	AVFLT1					
		AVFLT1	0	See Table 15					
	4	AVELTI	1	Select a nonzero value to enable the DC-blocking filter.					
0x18	3 DHF1		DAI1 High Sample Rate Mode Selects the sample rate range. 0 = 8kHz ≤ LRCLK ≤ 48kHz 1 = 48kHz ≤ LRCLK ≤ 96kHz						
	2		DAI1 DAC Highpa	ss Filter Mode					
	1		MODE1	DVFLT1					
	_ '	DVFLT1	0	See Table 15					
	0	541211	1	Select a nonzero value to enable the DC-blocking filter.					
0.20	3	DHF2	DAI2 High Sample Rate Mode Selects the sample rate range. 0 = 8kHz ≤ LRCLK ≤ 48kHz 1 = 48kHz < LRCLK ≤ 96kHz						
0x20	0	DCB2	DAI2 DC Blocking Filter Enables a DC-blocking filter on the DAI2 playback audio path. 0 = Disabled 1 = Enabled						

Table 15. Voice Highpass Filters

AVFTL/DVFLT VALUE	INTENDED SAMPLE RATE	FILTER RESPONSE
000	N/A	Disabled
001/011	16kHz/8kHz	-10 -20 -30 -40 -50 -60 0 200 400 600 800 1000 FREQUENCY (Hz)
010/100	16kHz/8kHz	-10 -10 -20 -30 -40 -50 -60 0 200 400 600 800 1000 FREQUENCY (Hz)
101	8kHz to 48kHz	0 -10 (g) 30 LRCLK = 48kHz 0 200 400 600 800 1000 FREQUENCY (Hz)
110/111	N/A	Reserved

Playback Path Signal Processing

The IC playback signal path includes automatic level control (ALC) and a 5-band parametric equalizer (EQ) (Figure 20). The DAI1 and DAI2 playback paths include separate ALCs controlled by a single set of registers. Two completely separate parametric EQs are included for the DAI1 and DAI2 playback paths.

Automatic Level Control

The automatic level control (ALC) circuit ensures maximum signal amplitude without producing audible clipping. This is accomplished by a variable gain stage that works on a sample by sample basis to increase the gain up to 12dB. A look-ahead circuit determines if the next sample exceeds full scale and reduces the gain so that the sample is exactly full scale.

A programmable low signal threshold determines the minimum signal amplitude that is amplified. Select a threshold that prevents the amplification of background noise. When the signal level drops below the low signal threshold, the ALC reduces the gain to 0dB until the signal increases above the threshold. Figure 21 shows an example of ALC input vs. output curves.

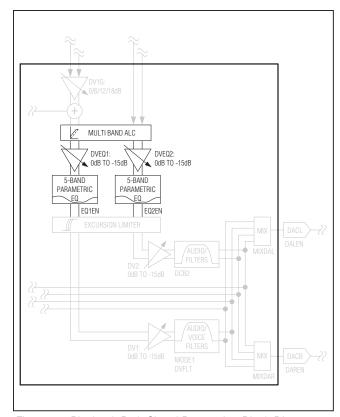


Figure 20. Playback Path Signal Processing Block Diagram

The ALC can optionally be configured in dual-band mode. In this mode, the input signal is filtered into two bands with a 5kHz center frequency. Each band is routed through independent ALCs and then summed together. In multiband mode, both bands use the same parameters.

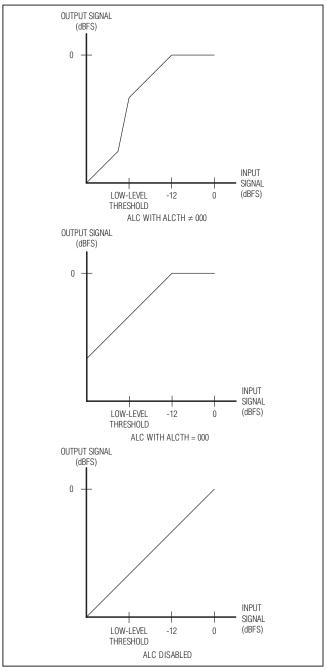


Figure 21. ALC Input vs. Output Examples

Table 16. Automatic Level Control Registers

REGISTER	BIT	NAME	DESCRIPTION			
	7	ALCEN	ALC Enable Enables ALC on both the DAI1 and DAI2 p 0 = Disabled 1 = Enabled	playback paths.		
	6		ALC and Excursion Limiter Release Time Sets the release time for both the ALC and Excursion Limiter. See the Excursion Limiter section for Excursion Limiter release times. ALC release time is defined as the time required to adjust the gain from 12dB to 0dB.			
			VALUE 000	ALC RELEASE TIME (s)		
		ALCRLS	001	4		
	5	ALUNLO	010	2		
			011	1		
	4		100	0.5		
			101	0.25		
0x43			110	Reserved		
			111	Reserved		
	3	ALCMB	Multiband Enable Enables dual-band processing with a 5kHz center frequency. SR1 and SR2 must be configured properly to achieve the correct center frequency for each playback path. 0 = Single-band ALC 1 = Dual-band ALC			
	2		Low Signal Threshold Selects the minimum signal level to be boo 000 = -∞dB (low-signal threshold disabled			
	1	ALCTH	001 = -12dB 010 = -18dB 011 = -24dB 100 = -30dB			
	0		101 = -36dB 110 = -42dB 111 = -48dB			

Parametric Equalizer

The parametric EQ contains five independent biquad filters with programmable gain, center frequency, and bandwidth. Each biquad filter has a gain range of ±12dB and a center frequency range from 20Hz to 20kHz. Use a filter Q less than that shown in Figure 22 to achieve ideal frequency responses. Setting a higher Q results in non-ideal frequency response. The biquad filters are series connected, allowing a total gain of ±60dB.

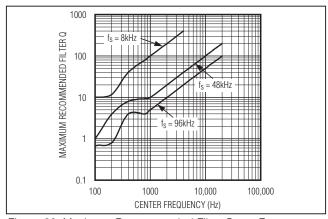


Figure 22. Maximum Recommended Filter Q vs. Frequency

Use the attenuator at the EQ's input to avoid clipping the signal. The attenuator can be programmed for fixed attenuation or dynamic attenuation based on signal level. If the dynamic EQ clip detection is enabled, the signal level from the EQ is fed back to the attenuator circuit to determine the amount of gain reduction necessary to avoid clipping.

The MAX98088/MAX98089 EV kit software includes a graphic interface for generating the EQ coefficients. The coefficients are sample rate dependent and stored in registers 0x52 through 0xB5.

Table 17. EQ Registers

REGISTER	BIT	NAME		DESCRIPTION				
	4	EQCLP1/ EQCLP2	DAI1/DAI2 EQ Clip Detection Automatically controls the EQ attenuator to prevent clipping in the EQ. 0 = Enabled 1 = Disabled					
	3			prevent clipping in th	e EQ when full-scale signals are boost- EN/EQ2EN = 1 and EQCLP1/EQCLP2			
0x30/0x32			VALUE	GAIN (dB)	VALUE	GAIN (dB)		
07.00,07.02	2	DVEQ1/DVEQ2	0x0	0	0x8	-8		
			0x1	-1	0x9	-9		
	1		0x2	-2	0xA	-10		
			0x3	-3	0xB	-11		
			0x4	-4	0xC	-12		
			0x5	-5	0xD	-13		
	0		0x6	-6	0xE	-14		
			0x7	-7	0xF	-15		
	7	VS2EN						
	6	VSEN	See the Click-and-Pop	Reduction section.				
	5	ZDEN						
0x49	1	EQ2EN	DAI2 EQ Enable 0 = Disabled 1 = Enabled					
	0	EQ1EN	DAI1 EQ Enable 0 = Disabled 1 = Enabled					

Playback Level Control

The IC includes separate digital level control for the DAI1 and DAI2 playback audio paths. The DAI1 signal path

allows boost when MODE1 = 0 and attenuation in any mode. The DAI2 signal path allows attenuation only.

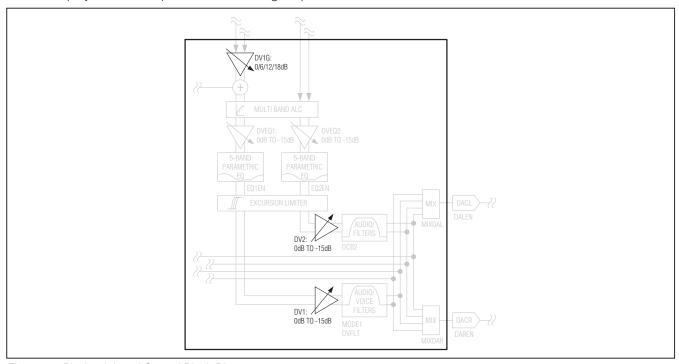


Figure 23. Playback Level Control Block Diagram

Table 18. DAC Playback Level Control Register

REGISTER	BIT	NAME	DESCRIPTION						
	7	DV1M/DV2M	DAI1/DAI2 Mute 0 = Disabled 1 = Enabled						
	5			DAI1 Voice Mode Gain DV1G only applies when MODE1 = 0.					
	4	DV1G	01 = 6dB 10 = 12dB 11 = 18dB						
0x2F/0x31	3		DAI1/DAI2 Attenuation						
0,21,0,01			VALUE	GAIN (dB)	VALUE	GAIN (dB)			
			0x0	0	0x8	-8			
	2		0x1	-1	0x9	-9			
		D) (4 /D) (0	0x2	-2	0xA	-10			
		DV1/DV2	0x3	-3	0xB	-11			
	1		0x4	-4	0xC	-12			
			0x5	-5	0xD	-13			
			0x6	-6	0xE	-14			
	0		0x7	-7	0xF	-15			

DAC Input Mixers

The IC's stereo DAC accepts input from two digital audio paths. The DAC mixer routes any audio path to the left and right DACs (Figure 24).

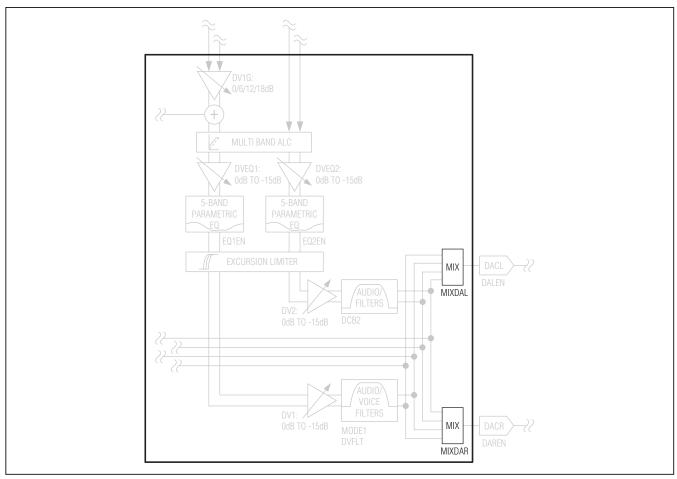


Figure 24. DAC Input Mixer Block Diagram

Table 19. DAC Input Mixer Register

REGISTER	BIT	NAME	DESCRIPTION	
	7		Left DAC Input Mixer	
	6	NAIVO AI	1xxx = DAI1 left channel	
	5	MIXDAL	x1xx = DAI1 right channel xx1x = DAI2 left channel	
000	4		xxx1 = DAI2 right channel	
0x22	3		Right DAC Input Mixer	
	2		1xxx = DAI1 left channel	
	1	MIXDAR	x1xx = DAI1 right channel xx1x = DAI2 left channel	
	0		xxx1 = DAI2 right channel	

Receiver Amplifier

The IC includes a single differential receiver amplifier. The receiver amplifier is designed to drive a 32Ω earpiece speaker. In cases where a single transducer is used for the loudspeaker and receiver, use the SPKBYP switch to route the receiver amplifier output to the left speaker outputs. The receiver amplifier can also be configured as stereo single-ended line outputs using the I²C interface.

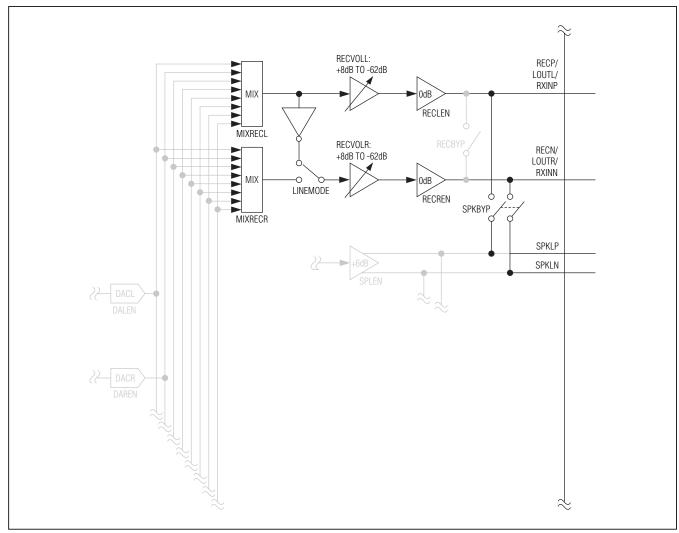


Figure 25. Receiver Amplifier Block Diagram

Receiver Output Mixer

The IC's receiver amplifier accepts input from the stereo DAC, the line inputs (single-ended or differential), and the MIC inputs. Configure the mixer to mix any combination of the available sources. When more than one signal is selected, the mixed signal can be configured to attenuate 6dB, 9dB, or 12dB.

Table 20. Receiver Output Mixer Register

REGISTER	BIT	NAME	DESCRIPTION		
	7		Left Receiver Output Mixer		
	6		1xxxxxxx = Right DAC		
	5		x1xxxxxx = MIC1		
0x28	4	MIXRECL	xx1xxxxx = MIC2		
UX28	3	MIXRECL	xxx1xxxx = INA2 (INADIFF = 0) or INA2-INA1 (INADIFF = 1) xxxx1xxx = INA1		
	2		xxxxx1xx = INB2 (INBDIFF = 0) or INB2-INB1 (INBDIFF = 1)		
	1		xxxxxx1x = INB1		
	0		xxxxxxx1 = Left DAC		
	7		Right Receiver Output Mixer		
	6		1xxxxxxx = Left DAC		
	5		x1xxxxxx = MIC1		
0x29	4	MIXRECR	xx1xxxxx = MIC2 $xx1xxxxx = MIC2$ $xx1xxxxx = MIC2$ $xx1xxxxx = MIC2$ $xx1xxxxx = MIC2$		
0x29	3		xxx1xxxx = INA2 (INADIFF = 0) or INA2-INA1 (INADIFF = 1) xxxx1xxx = INA1		
	2		xxxxx1xx = INB2 (INBDIFF = 0) or INB2-INB1 (INBDIFF = 1)		
	1		xxxxxx1x = INB1		
	0		xxxxxxx1 = Right DAC		
	7	LINE_MODE	Receiver Output Mode. Configures receive path output mode between BTL and stereo line output. 0 = BTL 1 = Stereo line output		
	3	MIXRECR	Right Receiver Mixer Gain Select 00 = 0dB 01 = -6dB		
0x2A	2	_GAIN	10 = -9dB 11 = -12dB		
	1		Left Receiver Mixer Gain Select		
	0	MIXRECL	00 = 0dB 01 = -6dB		
		_GAIN	10 = -9dB		
	0		11 = -12dB		

Receiver Output Volume

Table 21. Receiver Output Level Register

REGISTER	BIT	NAME		DESCRIPTION				
	7	RECLM/ RECRM	Receiver Output Mu 0 = Disabled 1 = Enabled	ute				
	4		Receiver Output Vo	lume Level				
	4		VALUE	VOLUME (dB)	VALUE	VOLUME (dB)		
			0x00	-62	0x10	-10		
	3		0x01	-58	0x11	-8		
	3		0x02	-54	0x12	-6		
			0x03	-50	0x13	-4		
	2	RECVOLL/ RECVOLR	0x04	-46	0x14	-2		
0x3B/0x3C			0x05	-42	0x15	0		
			0x06	-38	0x16	+1		
			0x07	-35	0x17	+2		
			0x08	-32	0x18	+3		
	1		0x09	-29	0x19	+4		
	'		0x0A	-26	0x1A	+5		
			0x0B	-23	0x1B	+6		
			0x0C	-20	0x1C	+6.5		
	0		0x0D	-17	0x1D	+7		
	0		0x0E	-14	0x1E	+7.5		
			0x0F	-12	0x1F	+8		

Speaker Amplifiers

The IC integrates a stereo filterless Class D amplifier that offers much higher efficiency than Class AB without the typical disadvantages.

The high efficiency of a Class D amplifier is due to the switching operation of the output stage transistors. In a Class D amplifier, the output transistors act as current steering switches and consume negligible additional power. Any power loss associated with the Class D output stage is mostly due to the I²R loss of the MOSFET on-resistance, and quiescent current overhead.

The theoretical best efficiency of a linear amplifier is 78%, however, that efficiency is only exhibited at peak output power. Under normal operating levels (typical music reproduction levels), efficiency falls below 30%, whereas the IC's Class D amplifier still exhibits 80% efficiency under the same conditions.

Traditional Class D amplifiers require the use of external LC filters or shielding to meet EN55022B and FCC electromagnetic-interference (EMI) regulation standards. Maxim's patented active emissions limiting edge-rate control circuitry reduces EMI emissions.

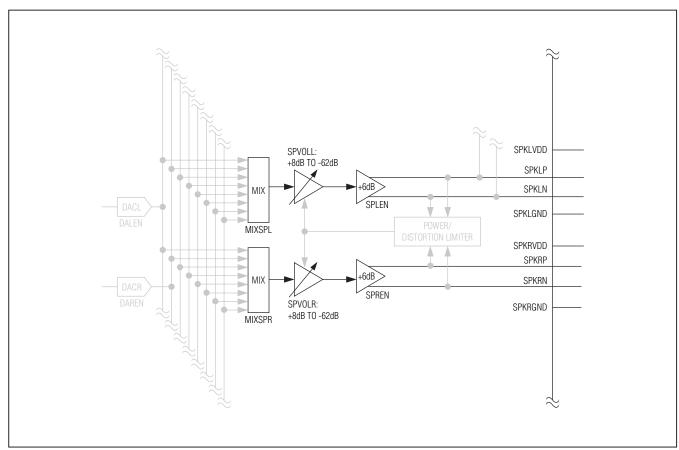


Figure 26. Speaker Amplifier Path Block Diagram

Speaker Output Mixers

The IC's speaker amplifiers accept input from the stereo DAC, the line inputs (single-ended ore differential), and the MIC inputs. Configure the mixer to mix any combination of the available sources. When more than one signal is selected, the mixer can be configured to attenuate the signal by 6dB, 9dB or 12dB.

Table 22. Speaker Output Mixer Register

REGISTER	BIT	NAME	DESCRIPTION	
	7		Left Speaker Output Mixer	
	6		1xxxxxxx = Right DAC	
	5		x1xxxxxx = MIC1	
000	4	MIVODI	xx1xxxxx = MIC2	
0x2B	3	MIXSPL	xxx1xxxx = INA2 (INADIFF = 0) or INA2-INA1 (INADIFF = 1) xxxx1xxx = INA1	
	2		xxxxx1xx = INB2 (INBDIFF = 0) or INB2-INB1 (INBDIFF = 1)	
	1		xxxxxx1x = INB1	
	0		xxxxxxx1 = Left DAC	
	7		Right Speaker Output Mixer	
	6		1xxxxxxx = Left DAC	
	5	MIXSPR	x1xxxxxx = MIC1	
000	4		xx1xxxxx = MIC2 xxx1xxxx = INA2 (INADIFF = 0) or INA2-INA1 (INADIFF = 1) xxxx1xxx = INA1	
0x2C	3			
	2		xxxxx1xx = INB2 (INBDIFF = 0) or INB2-INB1 (INBDIFF = 1)	
	1		xxxxxx1x = INB1	
	0		xxxxxxx1 = Right DAC	
	3	MIXSPR	Right Speaker Mixer Gain Select 00 = 0dB 01 = -6dB	
0.00	2	_GAIN	10 = -0dB 10 = -9dB 11 = -12dB	
0x2D	1	MIXSPL	Left Speaker Mixer Gain Select 00 = 0dB	
	0	_GAIN	01 = -6dB 10 = -9dB 11 = -12dB	

Speaker Output Volume

Table 23. Speaker Output Mixer Register

REGISTER	BIT	NAME		DESCRI	PTION	
	7	SPLM/SPRM	Left/Right Speake 0 = Disabled 1 = Enabled	er Output Mute		
			Left/Right Speake	er Output Volume Leve	el	
	4		VALUE	VOLUME (dB)	VALUE	VOLUME (dB)
	4		0x00	-62	0x10	-10
			0x01	-58	0x11	-8
			0x02	-54	0x12	-6
	3	SPVOLL/SPVOLR	0x03	-50	0x13	-4
			0x04	-46	0x14	-2
0x3D/0x3E			0x05	-42	0x15	0
			0x06	-38	0x16	+1
			0x07	-35	0x17	+2
			0x08	-32	0x18	+3
	2		0x09	-29	0x19	+4
			0x0A	-26	0x1A	+5
			0x0B	-23	0x1B	+6
			0x0C	-20	0x1C	+6.5
	1		0x0D	-17	0x1D	+7
	'		0x0E	-14	0x1E	+7.5
			0x0F	-12	0x1F	+8

Speaker Amplifier Signal Processing

The IC includes signal processing to improve the sound quality of the speaker output and protect transducers from damage. An excursion limiter dynamically adjusts the highpass corner frequency, while a power limiter and distortion limiter prevent the amplifier from outputting too much distortion or power. The excursion limiter is located in the DSP while the distortion limiter and power limiter control the analog volume control (Figure 28). All three limiters analyze the speaker amplifier's output signal to determine when to take action.

Excursion Limiter

The excursion limiter is a dynamic highpass filter that monitors the speaker outputs and increases the highpass corner frequency when the speaker amplifier's output exceeds a predefined threshold. The filter smoothly

transitions between the high and low corner frequency to prevent unwanted artifacts. The filter can operate in four different modes:

- Fixed-Frequency Preset Mode. The highpass corner frequency is fixed at the upper corner frequency and does not change with signal level.
- **Fixed-Frequency Programmable Mode.** The highpass corner frequency is fixed to that specified by the programmable biquad filter.
- Preset Dynamic Mode. The highpass filter automatically slides between a preset upper and lower corner frequency based on output signal level.
- **User-Programmable Dynamic Mode.** The highpass filter slides between a user-programmed biquad filter on the low side to a predefined corner frequency on the high side.

The transfer function for the user-programmable biquad is:

$$H(z) = \frac{b_0 + b_1 z^{-1} + b_2 z^{-2}}{1 + a_1 z^{-1} + a_2 z^{-2}}$$

The coefficients b₀, b₁, b₂, a₁, and a₂ are sample rate dependent and stored in registers 0xB4 through 0xC7. Store b₀, b₁, and b₂ as positive numbers. Store a₁ and a₂ as negated two's complement numbers. Separate filters can be stored for the DAI1 and DAI2 playback paths.

The MAX98088/MAX98089 EV kit software includes a graphic interface for generating the user-programmable biquad coefficients.

Note: Only change the excursion limiter settings when the signal path is disabled to prevent undesired artifacts.

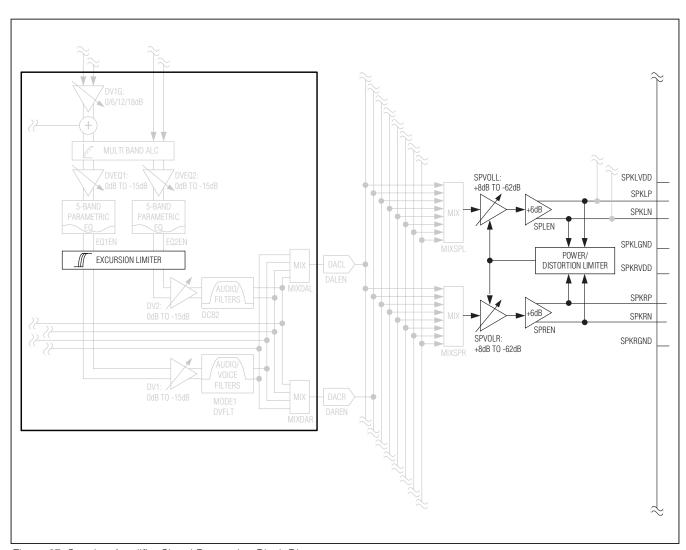


Figure 27. Speaker Amplifier Signal Processing Block Diagram

Table 24. Excursion Limiter Registers

REGISTER	BIT	NAME	DESCRIPTION						
	6		Excursion Limiter Corner Frequency The excursion limiter has limited sliding range and minimum corner frequencies. Listed below are all the valid filter combinations.						
	5		LOWER CORNER FREQUENCY	UPPER CORNER FREQUENCY	MINIMUM BIQUAD CORNER FREQUENCY	DHPUCF	DHPLCF		
		DHPUCF		niter disabled	_	000	00		
)Hz	_	001	00		
			600)Hz	_	010	00		
	4		800)Hz	_	011	00		
			1k	Hz	_	100	00		
044			Programmable	e using biquad	100Hz	000	11		
0x41			200Hz	400Hz	_	001	01		
	1		400Hz	600Hz	_	010	10		
			400Hz	800Hz	_	011	10		
		DHPLCF	Programmable using biquad	400Hz	200Hz	001	11		
		DI II EOI	Programmable using biquad	600Hz	300Hz	010	11		
	0		Programmable using biquad	800Hz	400Hz	011	11		
			Programmable using biquad	1kHz	500Hz	100	11		
	6		Control section for A	ALC release times. Earlie from the high corn	nd Excursion Limiter. See xcursion limiter release timer frequency to the low co	e is defined rner freque	d as the ncy.		
			VAI		EXCURSION LIMITER	RELEASE	TIME (S)		
0.40		A1 0D1 0	000		2				
0x43	5	ALCRLS	001		1				
			010		0.5				
					0.25				
			100		0.25				
	4			10	Reserved				
			111 Reserved						
	3		Excursion Limiter Measured at the Cla		ier outputs. Signals above	the thresho	old use		
			Measured at the Class D speaker amplifier outputs. Signals above the threshold use the upper corner frequency. Signals below the threshold use the lower corner fre-						
	2		quency. VBAT must correctly reflect the voltage of SPKLVDD to achieve accurate thresholds.						
		D. 15-1:	000 = 0.34VP						
0x42		DHPTH	001 = 0.71 Vp						
	1		010 = 1.30 Vp 011 = 1.77 Vp 100 = 2.33 Vp						
	0		100 = 2.33Vp 101 = 3.25Vp 110 = 4.25Vp						
	0								

Power Limiter

The IC's power limiter tracks the RMS power delivered to the loudspeaker and briefly mutes the speaker amplifier output if the speaker is at risk of sustaining permanent damage.

Loudspeakers are typically damaged when the voice coil overheats due to extended operation above the rated power. During normal operation, heat generated in the voice coil is transferred to the speaker's magnet, which transfers heat to the surrounding air. For the voice coil to overheat, both the voice coil and the magnet must overheat. The result is that a loudspeaker can operate above its rated power for a significant time before it heats sufficiently to cause damage.

The IC's power limiter includes user-programmable time constants and power thresholds to match a wide range of loudspeakers. Program the power limiter's threshold to match the loudspeaker's rated power handling. This can be determined through measurement or the loudspeaker's specification. Program time constant 1 to match the voice coil's thermal time constant. Program time constant 2 to match the magnet's thermal time constant. The time constants can be determined by plotting the voice coil's resistance vs. time as power is applied to the speaker.

Table 25. Power Limiter Registers

REGISTER	BIT	NAME	DESCRIPTION					
	7		Power Limiter Threshold If the RMS output power fr put is briefly muted to prot ing an 8Ω load. VBAT mu achieve accurate thresho	om the speaker amplifice ect the speaker. The the start correctly reflect the	reshold is measu	red in watts assum-		
	6		VALUE	THRESHOLD (W)	VALUE	THRESHOLD (W)		
	0	PWRTH	0x0	Power limiter disabled	0x8	0.27		
			0x1	0.05	0x9	0.35		
	_		0x2	0.06	0xA	0.48		
	5		0x3	0.09	0xB	0.72		
			0x4	0.11	0xC	1.00		
			0x5	0.13	0xD	1.43		
0x44	4		0x6	0.18	0xE	1.57		
			0x7	0.22	0xF	1.80		
	2	Power Limiter Weighting Factor Determines the balance between time constant 1 and 2 to match the dominar each time constant in the loudspeaker.						
			VALUE	T1 (%)		T2 (%)		
			000	50		50		
	1	PWRK	001	62.5		37.5		
		LVVUV	010	75		25		
			011	87.5		12.5		
			100	100		0		
	0		101	12.5		87.5		
			110	25		75		
			111	37.5		62.5		

Table 25. Power Limiter Registers (continued)

REGISTER	BIT	NAME		DESCRI	PTION			
	7			Power Limiter Time Constant 2 Select a value that matches the thermal time constant of the loudspeaker's magnet.				
			VALUE	TIME CONSTANT (min)	VALUE	TIME CONSTANT (min)		
	6		0x0	Disabled	0x8	3.75		
		PWRT2	0x1	0.50	0x9	5.00		
		PWRIZ	0x2	0.67	0xA	6.66		
	5		0x3	0.89	0xB	8.88		
			0x4	1.19	0xC	Reserved		
			0x5	1.58	0xD	Reserved		
	4		0x6	2.11	0xE	Reserved		
0x45			0x7	2.81	0xF	Reserved		
0x45	3		Power Limiter Time Constant 1 Select a value that matches the thermal time constant of the loudspeaker's voice coil.					
		2	VALUE	TIME CONSTANT (s)	VALUE	TIME CONSTANT (s)		
	2		0x0	Disabled	0x8	3.75		
		DW/DT4	0x1	0.50	0x9	5.00		
		PWRT1	0x2	0.67	0xA	6.66		
	1		0x3	0.89	0xB	8.88		
			0x4	1.19	0xC	Reserved		
			0x5	1.58	0xD	Reserved		
	0		0x6	2.11	0xE	Reserved		
			0x7	2.81	0xF	Reserved		

Distortion Limiter

The IC's distortion limiter ensures that the speaker amplifier's output does not exceed the programmed THD+N limit. The distortion limiter analyzes the Class D output duty cycle to determine the percentage of the waveform that is clipped. If the distortion exceeds the programmed threshold, the output gain is reduced.

Table 26. Distortion Limiter Registers

REGISTER	BIT	NAME	DESCRIPTION				
	7	THDCLP	Distortion Limit Measured in % THD+N.				
	6		VALUE	THD+N LIMIT (%)	VALUE	THD+N LIMIT (%)	
			0x0	Limiter disabled	0x8	12	
	5		0x1	< 1	0x9	14	
			0x2	1	0xA	16	
			0x3	2	0xB	18	
0x46	4		0x4	4	0xC	20	
			0x5	6	0xD	21	
			0x6	8	0xE	22	
			0x7	10	0xF	24	
	0	THDT1	Distortion Limiter Release Time Constant Duration of time required for the speaker amplifier's output gain to adjust back to the nominal level after a large signal has passed. 0 = 1.4s 1 = 2.8s				

Headphone

DirectDrive Headphone Amplifier

Traditional single-supply headphone amplifiers have outputs biased at a nominal DC voltage (typically half the supply). Large coupling capacitors are needed to block this DC bias from the headphone. Without these capacitors, a significant amount of DC current flows to the headphone, resulting in unnecessary power dissipation and possible damage to both headphone and headphone amplifier.

Maxim's second-generation DirectDrive architecture uses a charge pump to create an internal negative supply voltage. This allows the headphone outputs of the ICs to be biased at GND while operating from a single supply (Figure 1). Without a DC component, there is no need for the large DC-blocking capacitors. Instead of two large (220µF typ) capacitors, the IC's charge pump requires 3 small ceramic capacitors, conserving board space, reducing cost, and improving the frequency response of the headphone amplifier.

Charge Pump

The dual-mode charge pump generates both the positive and negative power supply for the headphone amplifier. To maximize efficiency, both the charge pump's

switching frequency and output voltage change based on signal level.

When the input signal level is less than 10% of PVDD, the switching frequency is reduced to a low rate. This minimizes switching losses in the charge pump. When the input signal exceeds 10% of PVDD, the switching frequency increases to support the load current.

For input signals below 25% of PVDD, the charge pump generates \pm (PVDD/2) to minimize the voltage drop across the amplifier's power stage and thus improve efficiency. Input signals that exceed 25% of PVDD cause the charge pump to output \pm PVDD. The higher output voltage allows for full output power from the headphone amplifier.

To prevent audible gliches when transitioning from the \pm (PVDD/2) output mode to the \pm PVDD output mode, the charge pump transitions very quickly. This quick change draws significant current from PVDD for the duration of the transition. The bypass capacitor on PVDD supplies the required current and prevents droop on PVDD.

The charge pump's dynamic switching mode can be turned off through the I^2C interface. The charge pump can then be forced to output either $\pm (PVDD/2)$ or $\pm PVDD$ regardless of input signal level.

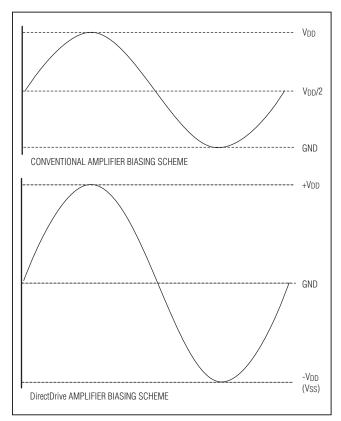


Figure 28. Traditional Amplifier Output vs. DirectDrive Output

Class H Operation

A Class H amplifier uses a Class AB output stage with power supplies that are modulated by the output signal. In the case of the ICs, two nominal power-supply differentials of 1.8V (+0.9V to -0.9V) and 3.6V (+1.8V to -1.8V) are available from the charge pump. Figure 29 shows the operation of the output-voltage-dependent power supply

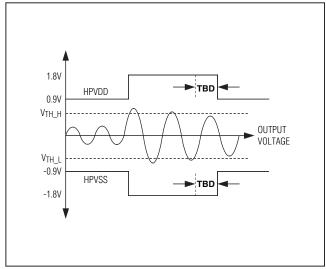


Figure 29. Class H Operation

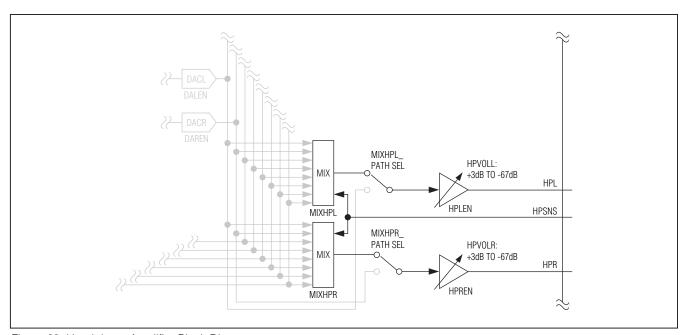


Figure 30. Headphone Amplifier Block Diagram

Headphone Output Mixers

The headphone amplifier mixer accepts input from the stereo DAC, the line inputs (single-ended or differential), and the MIC inputs. Configure the mixer to mix any combination of the available sources. When more than

one signal is selected, the mixer can be configured to attenuate the signal by 6dB, 9dB, or 12dB. The stereo DAC can bypass the headphone mixers, and be connected directly to the headphone amplifiers to provide lower power consumption.

Table 27. Headphone Output Mixer Register

REGISTER	BIT	NAME	DESCRIPTION
0x25	7	- MIXHPL	Left Headphone Output Mixer
	6		1xxxxxxx = Right DAC
	5		x1xxxxxx = MIC1
	4		xx1xxxxx = MIC2
	3		xxx1xxxx = INA2 (INADIFF = 0) or INA2 - INA1 (INADIFF = 1)
	2		xxxx1xxx = INA1 xxxxx1xx = INB2 (INBDIFF = 0) or INB2 - INB1 (INBDIFF = 1)
	1		xxxxx1xx = INB2 (INBDIFF = 0) OF INB2 - INBT (INBDIFF = 1)
	0		xxxxxxx1 = Left DAC
	7		Right Headphone Output Mixer
	6		1xxxxxxx = Left DAC
			x1xxxxxx = MIC1
	5		xx1xxxxx = MIC2
0x26	4	MIXHPR	xxx1xxxx = INA2 (INADIFF = 0) or INA2 - INA1 (INADIFF = 1)
	3		xxxx1xxx = INA1
	2		xxxxx1xx = INB2 (INBDIFF = 0) or INB2 - INB1 (INBDIFF = 1)
	1		xxxxxx1x = INB1
	0		xxxxxxx1 = Right DAC
	5	MIXHPR_ PATH	Right Headphone Mixer Path Select
		SEL	0 = Directly connect to the right DAC (bypass right headphone output mixer) 1 = Right headphone output mixer
	4	MIXHPL_ PATH SEL MIXHPR _GAIN	Left Headphone Mixer Path Select 0 = Directly connect to the left DAC (bypass left headphone output mixer)
			1 = Left headphone output mixer
			Right Headphone Mixer Gain Select
	3		00 = 0dB
0x27			01 = -6dB
	2		10 = -9dB
			11 = -12dB
	1	MIXHPL _GAIN	Left Headphone Mixer Gain Select
			00 = 0dB
	0		01 = -6dB
			10 = -9dB
			11 = -12dB

Headphone Output Volume

Table 28. Headphone Output Level Register

REGISTER	BIT	NAME	DESCRIPTION				
	7	HPLM/HPRM	Headphone Outpu 0 = Disabled 1 = Enabled	ut Mute			
		- HPVOLL/HPVOLR	Left/Right Headphone Output Volume Level				
			VALUE	VOLUME (dB)	VALUE	VOLUME (dB)	
	4		0x00	-67	0x10	-15	
			0x01	-63	0x11	-13	
			0x02	-59	0x12	-11	
			0x03	-55	0x13	-9	
	3		0x04	-51	0x14	-7	
0x39/0x3A			0x05	-47	0x15	-5	
			0x06	-43	0x16	-4	
	2		0x07	-40	0x17	-3	
			0x08	-37	0x18	-2	
			0x09	-34	0x19	-1	
	1		0x0A	-31	0x1A	0	
			0x0B	-28	0x1B	+1	
			0x0C	-25	0x1C	+1.5	
	0		0x0D	-22	0x1D	+2	
			0x0E	-19	0x1E	+2.5	
			0x0F	-17	0x1F	+3	

Output Bypass Switches

The IC's includes two output bypass switches that solve common applications problems. When a single transducer is used for the loudspeaker and receiver, the need exists for two amplifiers to power the same transducer. Bypass switches connect the IC's receiver amplifier output to the speaker amplifier's output, allowing either amplifier to power the same transducer. In systems where

an external receiver amplifier is used, route its output to the left speaker through RECP/RXINP and RECN/RXINN, bypassing the Class D amplifier. In systems where an external amplifier drives both the receiver and the IC's line input, one of the differential signals can be disconnected from the receiver when not needed by passing it through the analog switch that connects RECP/RXINP to RECN/RXINN.

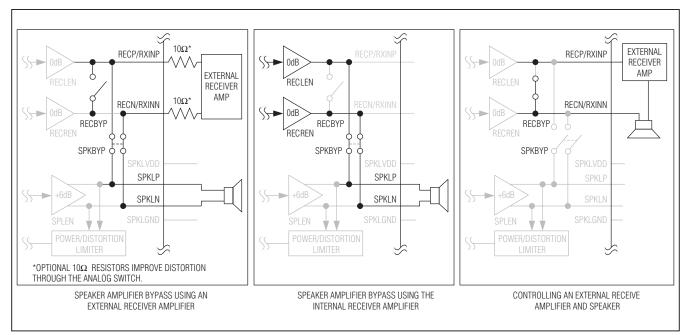


Figure 31. Output Bypass Switch Block Diagrams

Table 29. Output Bypass Switches Register

REGISTER	BIT	NAME	DESCRIPTION	
	7	INABYP	Coa the Migraphana Inputs section	
	4	MIC2BYP	See the Microphone Inputs section.	
0x4A	1	RECBYP	RXINP to RXINN Bypass Switch Shorts RXINP to RXINN allowing a signal to pass through the ICs. Disable the receiver amplifier when RECBYP = 1. 0 = Disabled 1 = Enabled	
	0	SPKBYP	RXIN to SPKL Bypass Switch Shorts RXINP/RXINN to SPKLP/SPKLN allowing either the internal or an external receiver amplifier to power the left speaker. Disable the left speaker amplifier when SPKBYP = 1. 0 = Disabled 1 = Enabled	

Click-and-Pop Reduction

The IC includes extensive click-and-pop reduction circuitry. The circuitry minimizes clicks and pops at turn-on, turn-off, and during volume changes.

Zero-crossing detection is implemented on all analog PGAs and volume controls to prevent large glitches when volume changes are made. Instead of making a volume change immediately, the change is made when the audio signal crosses the midpoint. If no zero-crossing occurs within the timeout window, the change is forced.

Volume slewing breaks up large volume changes into the smallest available step size and the steps through each step between the initial and final volume setting. When enabled, volume slewing also occurs at device turn-on and turn-off. During turn-on the volume is set to mute before the output is enabled. Once the output is on, the volume ramps to the desired level. At turn-off the volume is ramped to mute before the outputs are disabled.

When there is no audio signal zero-crossing detection can prevent volume slewing from occurring. Enable enhanced volume slewing to prevent the volume controller from requesting another volume level until the previous one has been set. Each step in the volume ramp then occurs after a zero crossing has occurred in the audio signal or the timeout window has expired. During turn-off, enhance volume slewing is always disabled.

Table 30. Click-and-Pop Reduction Register

REGISTER	BIT	NAME	DESCRIPTION		
	7	VS2EN	Enhanced Volume Smoothing During volume slewing, the controller waits for each step in the ramp to be applied before sending the next step. When zero-crossing detection is enabled this prevents large steps in the output volume when no zero crossings are detected. 0 = Enabled 1 = Disabled Applies to volume changes in HPVOLL, HPVOLR, RECVOL, SPVOLL, and SPVOLR.		
0x47	6	VSEN	Volume Adjustment Smoothing Volume changes are smoothed by stepping through intermediate steps. Also ramps the volume from minimum to the programmed value at turn-on and back to minimum turn-off. 0 = Enabled 1 = Disabled Applies to volume changes in HPVOLL, HPVOLR, RECVOL, SPVOLL, and SPVOLR.		
	5	ZDEN	Zero-Crossing Detection Holds volume changes until there is a zero crossing in the audio signal. This reduces click and pop during volume changes (zipper noise). If no zero crossing is detected within 100ms, the volume change is forced. 0 = Enabled 1 = Disabled Applies to volume changes in PGAM1, PGAM2, PGAOUTA, PGAOUTB, PGAOUTC, HPVOLL, HPVOLR, RECVOL, SPVOLL, and SPVOLR.		
	1	EQ2EN	See the 5-Band Parametric EQ section.		
	0	EQ1EN	Joed the 3-Dana Farathethe Lee Section.		

Jack Detection

The IC features jack detection that can detect the insertion and removal of a jack as well as the load type. When a jack is detected, an interrupt on $\overline{\text{IRQ}}$ can be triggered to alert the microcontroller of the event. Figure 32 shows the typical configuration for jack detection.

Jack Detection and Removal

When the IC is in normal operation and the MICBIAS is enabled, jack insertion and removal can be detected

through JACKSNS. To detect a jack insertion and removal, the ICs must be powered on and MICBIAS enabled. Set JDETEN, MBEN, BIASEN, and VCMEN bits to enable jack detection circuitry. JACKSNS is pulled up by MICBIAS as long as no load is applied to JACKSNS. Table 31 shows the change in JKSNS that occurs when a jack is inserted and removed.

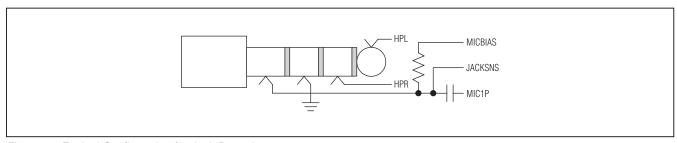


Figure 32. Typical Configuration for Jack Detection

Table 31. Change in JKSNS Upon Jack Insertion

JACK TYPE	MBEN = 1, BIASEN = 1, VCMEN = 1
GND GND R L	JKSNS: 1 → 0
MIC GND R L	JKSNS: 1 → 0

Table 32. Change in JKSNS Upon Jack Removal

JACK TYPE	MBEN = 1, BIASEN = 1, VCMEN = 1
GND GND R L	JKSNS: 0 → 1
MIC GND R L	JKSNS: 0 → 1

Table 33. Jack Detection Registers

REGISTER	BIT	NAME	DESCRIPTION	
0x02 (Read Only)	6	JKSNS	JACKSNS State Reports the status of JACKSNS when JDETEN = 1, MBEN = 1, BIASEN = 1, and VCMEN = 1. 0 = JACKSNS low 1 = JACKSNS high	
	7	JDETEN	Jack Detection Enable 0 = Disabled 1 = Enabled	
0x4B	1	IDED	Jack Detection Debounce Configures the debounce time for setting JDET. 00 = 25ms	
	0	JDEB	01 = 50ms 10 = 100ms 11 = 200ms	

Battery Measurement

The IC measures the voltage applied to SPKLVDD (typically the battery voltage) and reports the value in register 0x03. This value is also used by the speaker limiter circuitry to set accurate thresholds. When the battery measurement function is disabled, the battery voltage is user programmable.

Table 34. Battery Measurement Registers

REGISTER	BIT	NAME	DESCRIPTION
	4		Battery Voltage
	3		Read VBAT when VBATEN = 1 to determine VSPKLVDD. Program VBAT when VBATEN = 0 to allow proper speaker amplifier signal processing. Calculate the battery voltage using the following formula:
0x03	2	VBAT	
	1		
	0		$V_{BATTERY} = 2.55V + [VBAT/10]$
	7	SHDN	See Power Management
0x51	6	VBATEN	Battery Measurement Enable. Enables an internal ADC to measure VSPKLVDD. 0 = Disabled (register 0x03 readable and writeable) 1 = Enabled (register 0x03 read only)
UX51	3	PERFMODE	See the Power Management section.
	2	HPPLYBCK	See the Power Management section.
	1	PWRSV8K	See the Power Management section.
	0	PWRSV	See the Power Management section.

Device Status

The IC uses register 0x00 and \overline{IRQ} to report the status of various device functions. The status register bits are set when their respective events occur, and cleared upon reading the register. Device status can be determined

either by poling register 0x00 or configuring the \overline{IRQ} to pull low when specific events occur. \overline{IRQ} is an opendrain output that requires a pullup resistor for proper operation. Register 0x0F determines which bits in the status register trigger \overline{IRQ} to pull low.

Table 35. Status and Interrupt Registers

REGISTER	BIT	NAME	DESCRIPTION		
	7	CLD	Full Scale 0 = All digital signals are less than full scale. 1 = The DAC or ADC signal path has reached or exceeded full scale. This typically indicates clipping.		
0x00 (Read Only)	6	SLD	Volume Slew Complete SLD reports that any of the programmable-gain arrays or volume controllers has completed slewing from a previous setting to a new programmed setting. If multiple gain arrays or volume controllers are changed at the same time, the SLD flag is set after the last volume slew completes. SLD also reports when the digital audio interface soft-start or soft-stop process has completed. MCLK is required for proper SLD operation. 0 = No volume slewing sequences have completed since the status register was last read. 1 = Volume slewing complete.		
	5	ULK	Digital Audio Interface Unlocked 0 = Both digital audio interfaces are operating normally. 1 = Either digital audio interface is configured incorrectly or receiving invalid data.		
	1	JDET	Jack Configuration Change JDET reports changes to any bit in the Jack Status register (0x02). Changes to the Jack Status bits are debounced before setting JDET. The debounce period is programmable using the JDEB bits. JDET is always set the first time JDETEN or SHDN is set the first time power is applied to the IC. Read the status register following such an event to clear JDET and allow for proper jack detection. 0 = No change in jack configuration. 1 = Jack configuration has changed.		
	7	ICLD	Full-Scale Interrupt Enable 0 = Disabled 1 = Enabled		
UXUF	5	IULK	Digital Audio Interface Unlocked Interrupt Enable 0 = Disabled 1 = Enabled		
	1	IJDET	Jack Configuration Change Interrupt Enable 0 = Disabled 1 = Enabled		

Device Revision

Table 36. Device Revision Register

REGISTER	BIT	NAME	DESCRIPTION
	7		
	6		
	5		
0xFF	4	REV	Device Revision Code REV is always set to 0x40.
(Read Only)	3		
	2		
	1		
	0		

I²C Serial Interface

The IC features an I2C/SMBus™-compatible, 2-wire serial interface comprising a serial-data line (SDA) and a serial-clock line (SCL). SDA and SCL facilitate communication between the IC and the master at clock rates up to 400kHz. Figure 5 shows the 2-wire interface timing diagram. The master generates SCL and initiates data transfer on the bus. The master device writes data to the IC by transmitting the proper slave address followed by the register address and then the data word. Each transmit sequence is framed by a START (S) or REPEATED START (Sr) condition and a STOP (P) condition. Each word transmitted to the IC is 8 bits long and is followed by an acknowledge clock pulse. A master reading data from the IC transmits the proper slave address followed by a series of nine SCL pulses. The IC transmits data on SDA in sync with the master-generated SCL pulses. The master acknowledges receipt of each byte of data. Each read sequence is framed by a START or REPEATED START condition, a not acknowledge, and a STOP condition. SDA operates as both an input and an open-drain output. A pullup resistor, typically greater than 500Ω , is required on SDA. SCL operates only as an input. A pullup resistor, typically greater than 500Ω , is required on SCL if there are multiple masters on the bus, or if the single master has an open-drain SCL output. Series resistors in line with SDA and SCL are optional. Series resistors protect the digital inputs of the IC from high voltage spikes on the bus lines, and minimize crosstalk and undershoot of the bus signals.

Bit Transfer

One data bit is transferred during each SCL cycle. The data on SDA must remain stable during the high period of the SCL pulse. Changes in SDA while SCL is high are control signals (see the *START* and *STOP* Conditions section).

START and STOP Conditions

SDA and SCL idle high when the bus is not in use. A master initiates communication by issuing a START condition. A START condition is a high-to-low transition on SDA with SCL high. A STOP condition is a low-to-high transition on SDA while SCL is high (Figure 33). A START condition from the master signals the beginning of a transmission to the IC. The master terminates transmission, and frees the bus, by issuing a STOP condition. The bus remains active if a REPEATED START condition is generated instead of a STOP condition.

Early STOP Conditions

The IC recognizes a STOP condition at any point during data transmission except if the STOP condition occurs in the same high pulse as a START condition. For proper operation, do not send a STOP condition during the same SCL high pulse as the START condition.

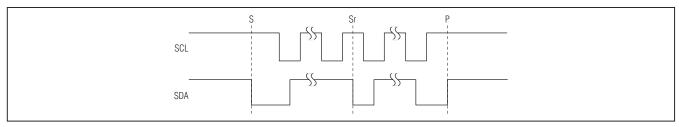


Figure 33. START, STOP, and REPEATED START Conditions SMBus is a trademark of Intel Corp.

Slave Address

The slave address is defined as the seven most significant bits (MSBs) followed by the read/write bit. For the IC, the seven most significant bits are 0010000. Setting the read/write bit to 1 (slave address = 0x21) configures the IC for read mode. Setting the read/write bit to 0 (slave address = 0x20) configures the ICs for write mode. The address is the first byte of information sent to the IC after the START condition.

Acknowledge

The acknowledge bit (ACK) is a clocked 9th bit that the IC uses to handshake receipt each byte of data when in write mode (Figure 34). The IC pulls down SDA during the entire master-generated 9th clock pulse if the previous byte is successfully received. Monitoring ACK allows for detection of unsuccessful data transfers. An unsuccessful data transfer occurs if a receiving device

is busy or if a system fault has occurred. In the event of an unsuccessful data transfer, the bus master retries communication. The master pulls down SDA during the 9th clock cycle to acknowledge receipt of data when the IC is in read mode. An acknowledge is sent by the master after each read byte to allow data transfer to continue. A not acknowledge is sent when the master reads the final byte of data from the IC, followed by a STOP condition.

Write Data Format

A write to the IC includes transmission of a START condition, the slave address with the R/W bit set to 0, one byte of data to configure the internal register address pointer, one or more bytes of data, and a STOP condition. Figure 35 illustrates the proper frame format for writing one byte of data to the IC. Figure 35 illustrates the frame format for writing n-bytes of data to the IC.

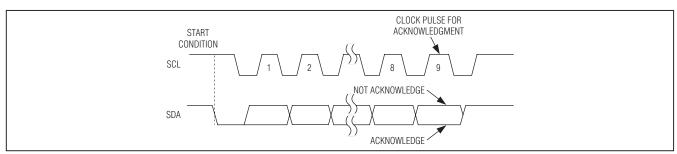


Figure 34. Acknowledge

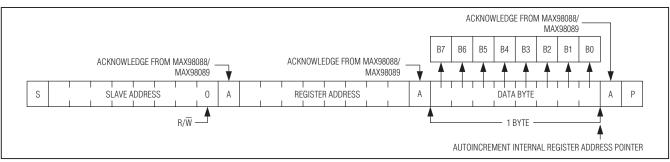


Figure 35. Writing One Byte of Data to the ICs

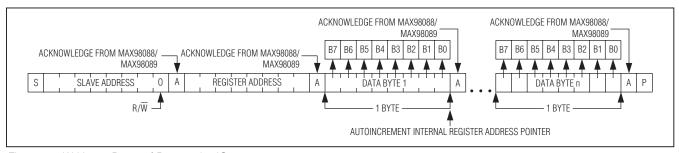


Figure 36. Writing n-Bytes of Data to the ICs

The slave address with the R/W bit set to 0 indicates that the master intends to write data to the ICs. The ICs acknowledge receipt of the address byte during the master-generated 9th SCL pulse.

The second byte transmitted from the master configures the IC's internal register address pointer. The pointer tells the IC where to write the next byte of data. An acknowledge pulse is sent by the ICs upon receipt of the address pointer data.

The third byte sent to the ICs contains the data that is written to the chosen register. An acknowledge pulse from the ICs signals receipt of the data byte. The address pointer autoincrements to the next register address after each received data byte. This autoincrement feature allows a master to write to sequential registers within one continuous frame. The master signals the end of transmission by issuing a STOP condition. Register addresses greater than 0xC7 are reserved. Do not write to these addresses.

Read Data Format

Send the slave address with the R/\overline{W} bit set to 1 to initiate a read operation. The IC acknowledges receipt of its slave address by pulling SDA low during the 9th SCL clock pulse. A START command followed by a read command resets the address pointer to register 0x00.

The first byte transmitted from the ICs is the content of register 0x00. Transmitted data is valid on the rising edge of SCL. The address pointer autoincrements after each read data byte. This autoincrement feature allows all registers to be read sequentially within one continuous frame. A STOP condition can be issued after any number of read data bytes. If a STOP condition is issued followed by another read operation, the first data byte to be read is from register 0x00.

The address pointer can be preset to a specific register before a read command is issued. The master presets the address pointer by first sending the IC's slave address with the R/\overline{W} bit set to 0 followed by the register address. A REPEATED START condition is then sent followed by the slave address with the R/\overline{W} bit set to 1. The IC then transmits the contents of the specified register. The address pointer autoincrements after transmitting the first byte.

The master acknowledges receipt of each read byte during the acknowledge clock pulse. The master must acknowledge all correctly received bytes except the last byte. The final byte must be followed by a not acknowledge from the master and then a STOP condition. Figure 37 illustrates the frame format for reading one byte from the IC. Figure 38 illustrates the frame format for reading multiple bytes from the ICs.

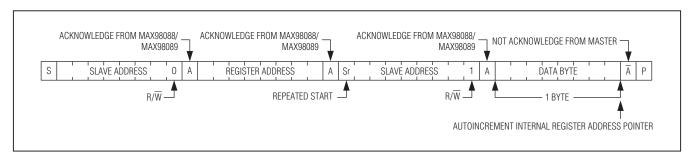


Figure 37. Reading One Byte of Data from the ICs

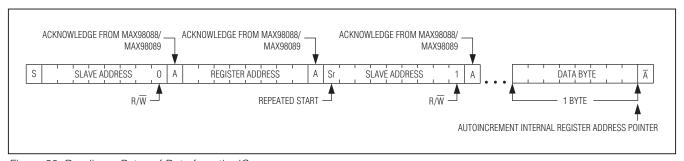


Figure 38. Reading n Bytes of Data from the ICs

_Applications Information

Typical Operating Circuits

Figures 39 and 40 provide example operating circuits for the ICs. sThe external components shown are the minimum required for the ICs to operate. Additional components may be required by the application.

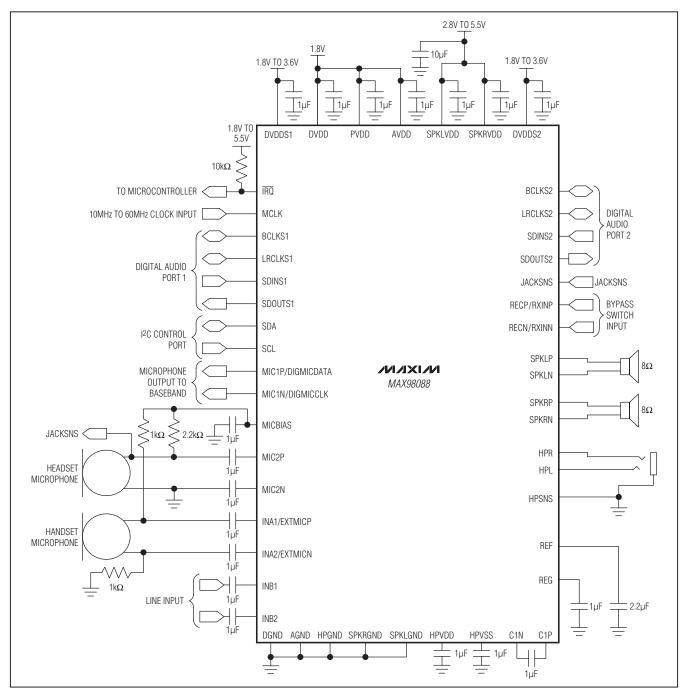


Figure 39. Typical Application Circuit Using Analog Microphone Inputs and the Bypass Switch

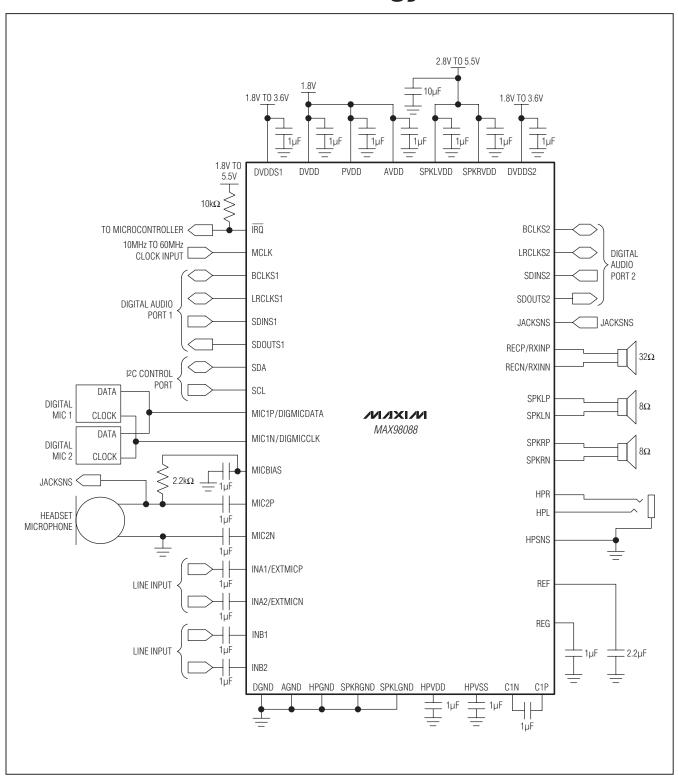


Figure 40. Typical Application Circuit Using the Digital Microphone Input and Receiver Amplifier

Filterless Class D Operation

Traditional Class D amplifiers require an output filter to recover the audio signal from the amplifier's output. The filters add cost, increase the solution size of the amplifier, and can decrease efficiency and THD+N performance. The traditional PWM scheme uses large differential output swings (2 x VDD peak to peak) and causes large ripple currents. Any parasitic resistance in the filter components results in a loss of power, lowering the efficiency.

The IC does not require an output filter. The device relies on the inherent inductance of the speaker coil and the natural filtering of both the speaker and the human ear to recover the audio component of the square-wave output. Eliminating the output filter results in a smaller, less costly, more efficient solution.

Because the frequency of the IC's output is well beyond the bandwidth of most speakers, voice coil movement due to the square-wave frequency is very small. Although this movement is small, a speaker not designed to handle the additional power can be damaged. For optimum results, use a speaker with a series inductance > $10\mu H$. Typical 8Ω speakers exhibit series inductances in the $20\mu H$ to $100\mu H$ range.

RF Susceptibility

GSM radios transmit using time-division multiple access (TDMA) with 217Hz intervals. The result is an RF signal with strong amplitude modulation at 217Hz and its harmonics that is easily demodulated by audio amplifiers. The IC is designed specifically to reject RF signals; however, PCB layout has a large impact on the susceptibility of the end product.

In RF applications, improvements to both layout and component selection decrease the IC's susceptibility to RF noise and prevent RF signals from being demodulated into audible noise. Trace lengths should be kept below 1/4 of the wavelength of the RF frequency of interest. Minimizing the trace lengths prevents them from functioning as antennas and coupling RF signals into the IC. The wavelength (λ) in meters is given by: $\lambda = c/f$ where $c = 3 \times 10^8$ m/s, and f = the RF frequency of interest.

Route audio signals on middle layers of the PCB to allow ground planes above and below to shield them from RF interference. Ideally, the top and bottom layers of the PCB should primarily be ground planes to create effective shielding.

Additional RF immunity can also be obtained by relying on the self-resonant frequency of capacitors as it exhibits a frequency response similar to a notch filter. Depending on the manufacturer, 10pF to 20pF capacitors typically exhibit self resonance at the RF frequencies of interest. These capacitors, when placed at the input pins, can effectively shunt the RF noise to ground. For these capacitors to be effective, they must have a low-impedance, low-inductance path to the ground plane. Avoid using microvias to connect to the ground plane whenever possible as these vias do not conduct well at RF frequencies.

Startup/Shutdown Sequencing

To ensure proper device initialization and minimal click-and-pop, program the IC's $\overline{SHDN}=1$ after configuring all registers. Table 37 lists an example startup sequence for the device. To shut down the IC, simply set $\overline{SHDN}=0$.

Table 37. Example Startup Sequence

SEQUENCE	DESCRIPTION	REGISTERS
1	Ensure SHDN = 0	0x51
2	Configure clocks	0x10 to 0x13, 0x19 to 0x1B
3	Configure digital audio interface	0x14 to 0x17, 0x1C to 0x1F
4	Configure digital signal processing	0x18, 0x20, 0x3F to 0x46
5	Load coefficients	0x52 to 0xC9
6	Configure mixers	0x22 to 0x2D
7	Configure gain and volume controls	0x2E to 0x3E
8	Configure miscellaneous functions	0x47 to 0x4B
9	Enable desired functions	0x4C, 0x50
10	Set SHDN = 1	0x51

Many configuration options in the ICs can be made while the devices are operating, however, some registers should only be adjusted when the corresponding audio path is disabled. Table 38 lists the registers that are sensitive during operation. Either disable the corresponding audio path or set $\overline{SHDN} = 0$ while changing these registers.

Component SelectionOptional Ferrite Bead Filter

In applications where speaker leads exceed 20mm, additional EMI suppression can be achieved by using a filter constructed from a ferrite bead and a capacitor to ground (Figure 41). Use a ferrite bead with low DC resistance, high-frequency (> 600MHz) impedance between 100Ω and 600Ω , and rated for at least 1A. The capacitor value varies based on the ferrite bead chosen and the actual speaker lead length. Select a capacitor less than 1nF based on EMI performance.

Input Capacitor

An input capacitor, C_{IN} , in conjunction with the input impedance of the IC line inputs forms a highpass filter

that removes the DC bias from an incoming analog signal. The AC coupling capacitor allows the amplifier to automatically bias the signal to an optimum DC level. Assuming zero-source impedance, the -3dB point of the highpass filter is given by:

$$f_{-3dB} = \frac{1}{2\pi R_{IN} C_{IN}}$$

Choose C_{IN} so that f-3dB is well below the lowest frequency of interest. For best audio quality use capacitors whose dielectrics have low-voltage coefficients, such as tantalum or aluminum electrolytic. Capacitors with high-voltage coefficients, such as ceramics, may result in increased distortion at low frequencies.

Charge-Pump Capacitor Selection

Use capacitors with an ESR less than $100m\Omega$ for optimum performance. Low-ESR ceramic capacitors minimize the output resistance of the charge pump. Most surface-mount ceramic capacitors satisfy the ESR requirement. For best performance over the extended temperature range, select capacitors with an X7R dielectric.

Table 38. Registers That Are Sensitive to Changes During Operation

REGISTER	DESCRIPTION	
0x10 to 0x13, 0x19 to 0x1B	Clock Control Registers	
0x14 to 0x17, 0x1C to 0x1F	Digital Audio Interface Configuration	
0x18, 0x20	Digital Passband Filters	
0x25 to 0x2D	Analog Mixers	
0x52 to 0xC9	Digital Signal Processing Coefficients	

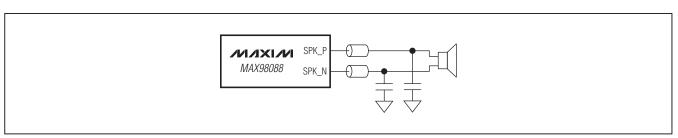


Figure 41. Optional Class D Ferrite Bead Filter

Charge-Pump Flying Capacitor

The value of the flying capacitor (connected between C1N and C1P) affects the output resistance of the charge pump. A value that is too small degrades the device's ability to provide sufficient current drive, which leads to a loss of output voltage. Increasing the value of the flying capacitor reduces the charge-pump output resistance to an extent. Above $1\mu F$, the on-resistance of the internal switches and the ESR of external charge-pump capacitors dominate.

Charge-Pump Holding Capacitor

The holding capacitor (bypassing HPVSS) value and ESR directly affect the ripple at HPVSS. Increasing the capacitor's value reduces output ripple. Likewise, decreasing the ESR reduces both ripple and output resistance. Lower capacitance values can be used in systems with low maximum output power levels. See the Output Power vs. Load Resistance graph in the *Typical Operating Characteristics* section for more information

Unused Pins

Table 39 shows how to connect the IC's pins when unused.

Table 39. Unused Pins

NAME	CONNECTION	NAME	CONNECTION
SPKRP	Unconnected	INB1	Unconnected
SPKRVDD	Always connected	INA2/MICEXTN	Unconnected
SPKLVDD	Always connect	LRCLKS2	Unconnected
SPKLP	Unconnected	MCLK	Always connect
RECN/RXINN	Unconnected	SDINS2	AGND
HPVDD	Unconnected	ĪRQ	Unconnected
C1P	Unconnected	MIC1P/DIGMICDATA	Unconnected
HPGND	AGND	INA1/MICEXTP	Unconnected
SPKRN	Unconnected	DGND	Always connect
SPKRGND	Always connect	BCLKS2	Unconnected
SPKLGND	Always connect	SDA	Always connect
SPKLN	Unconnected	SCL	Always connect
RECP/RXINP	Unconnected	REG	Always connect
C1N	Unconnected	REF	Always connect
HPL	Unconnected	MIC1N/DIGMICCLK	Unconnected
HPVSS	Unconnected	MIC2P	Unconnected
SDINS1	AGND	SDOUTS2	Unconnected
LRCLKS1	Unconnected	DVDDS2	DVDD
HPSNS	AGND	DVDD	Always connect
INB2	Unconnected	AVDD	Always connect
HPR	Unconnected	PVDD	Always connect
DVDDS1	DVDD	AGND	Always connect
SDOUTS1	Unconnected	MICBIAS	Unconnected
BCLKS1	Unconnected	MIC2N	Unconnected
JACKSNS	Unconnected		

Recommended PCB Routing

The IC uses a 63-bump WLP package. Figure 42 provides an example of how to connect to all active bumps using 3 layers of the PCB. To ensure uninterrupted ground returns, use layer 2 as a connecting layer between layer 1 and layer 2 and flood the remaining area with ground.

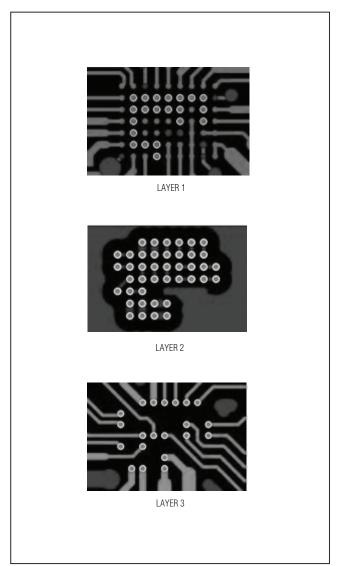


Figure 42. Suggested Routing for the MAX98088

Supply Bypassing, Layout, and Grounding

Proper layout and grounding are essential for optimum performance. When designing a PCB for the ICs, partition the circuitry so that the analog sections of the IC are separated from the digital sections. This ensures that the analog audio traces are not routed near digital traces.

Use a large continuous ground plane on a dedicated layer of the PCB to minimize loop areas. Connect AGND, DGND, HPGND, SPKLGND, and SPKRGND directly to the ground plane using the shortest trace length possible. Proper grounding improves audio performance, minimizes crosstalk between channels, and prevents any digital noise from coupling into the analog audio signals.

Ground the bypass capacitors on MICBIAS, REG, PREG, and REF directly to the ground plane with minimum trace length. Also be sure to minimize the path length to AGND. Bypass AVDD directly to AGND.

Connect all digital I/O termination to the ground plane with minimum path length to DGND. Bypass DVDD, DVDDS1, and DVDDS2 directly to DGND.

Place the capacitor between C1P and C1N as close as possible to the ICs to minimize trace length from C1P to C1N. Inductance and resistance added between C1P and C1N reduce the output power of the headphone amplifier. Bypass HPVSS with a capacitor located close to HPVSS with a short trace length to HPGND. Close decoupling of HPVSS minimizes supply ripple and maximizes output power from the headphone amplifier.

HPSNS senses ground noise on the headphone jack and adds the same noise to the output audio signal, thereby making the output (headphone output minus ground) noise free. Connect HPSNS to the headphone jack shield to ensure accurate pickup of headphone ground noise.

Bypass SPKLVDD and SPKRVDD to SPKLGND and SPKRGND, respectively, with as little trace length as possible. Connect SPKLP, SPKLN, SPKRP, and SPKRN to the stereo speakers using the shortest traces possible. Reducing trace length minimizes radiated EMI. Route SPKLP/SPKLN and SPKRP/SPKRN as differential pairs on the PCB to minimize loop area, thereby the inductance of the circuit. If filter components are used on the speaker outputs, be sure to locate them as close as possible to the IC to ensure maximum effectiveness. Minimize the trace length from any ground-connected passive components to SPKLGND and SPKRGND to further minimize radiated EMI.

Route microphone signals from the microphone to the ICs as a differential pair, ensuring that the positive and negative signals follow the same path as closely as possible with equal trace length. When using single-ended microphones or other single-ended audio sources, ground the negative microphone input as close as possible to the audio source and then treat the positive and negative traces as differential pairs.

An evaluation kit (EV kit) is available to provide an example layout for the IC. The EV kit allows quick setup of the IC and includes easy-to-use software allowing all internal registers to be controlled.

WLP Applications Information

For the latest application details on WLP construction, dimensions, tape carrier information, PCB techniques, bump-pad layout, and recommended reflow temperature profile, as well as the latest information on reliability testing results, refer to the Application Note 1891: Wafer-Level Packaging (WLP) and Its Applications. Figure 43 shows the dimensions of the WLP balls used on the MAX98088.

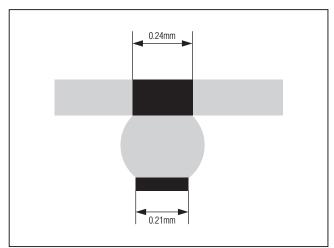
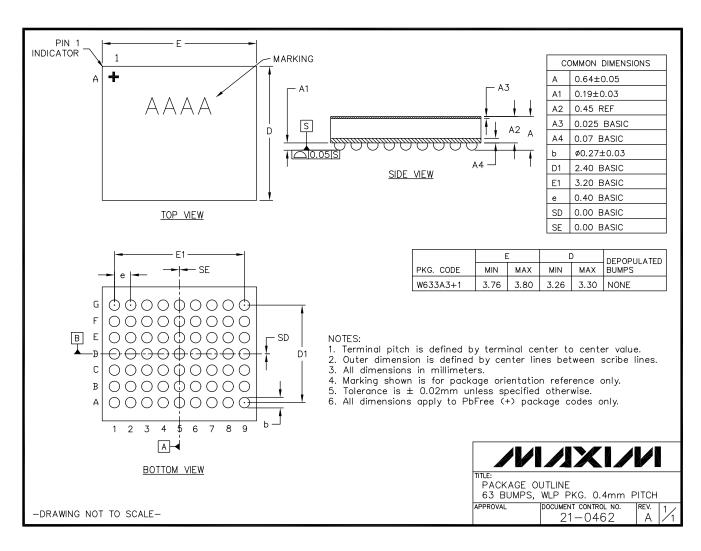


Figure 43. WLP Ball Dimensions

Package Information

For the latest package outline information and land patterns, go to www.maxim-ic.com/packages. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE TYPE	PACKAGE CODE	OUTLINE NO.	LAND PATTERN NO.
63 WLP	W633A3+1	<u>21-0462</u>	_



Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	6/10	Initial release	_

Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.